



COM Express™ conga-TC97

5th Generation Intel® Core™ i7, i5, i3 Single Chip Ultra Low TDP Processors

User's Guide

Revision 1.1

Revision History

Revision	Date (yyyy.mm.dd)	Author	Changes
0.1	2015.01.30	AEM	<ul style="list-style-type: none">• Preliminary release
0.2	2015.06.02	AEM	<ul style="list-style-type: none">• Added power consumption values in section 2.5 "Power Consumption"• Updated the block diagram in section 3 "Block Diagram"• Corrected the statement that the PWRBTN# signal is active on rising edge in table 17 "Power and System Management Signal Descriptions"• Updated the IO address ranges sent to the LPC Bus in section 9.1.1 "LPC Bus"• Added BIOS setup description in section 10
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Preface

This user's guide provides information about the components, features, connectors and BIOS Setup menus available on the conga-TC97. It is one of three documents that should be referred to when designing a COM Express™ application. The other reference documents that should be used include the following:

COM Express™ Design Guide

COM Express™ Specification

The links to these documents can be found on the congatec AG website at www.congatec.com

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Warnings indicate conditions that, if not observed, can cause personal injury.



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Note

Notes call attention to important information that should be observed.

Terminology

Term	Description
GB	Gigabyte (1,073,741,824 bytes)
GHz	Gigahertz (one billion hertz)
kB	Kilobyte (1024 bytes)
MB	Megabyte (1,048,576 bytes)
Mbit	Megabit (1,048,576 bits)
kHz	Kilohertz (one thousand hertz)
MHz	Megahertz (one million hertz)
TDP	Thermal Design Power
PCIe	PCI Express
SATA	Serial ATA
PEG	PCI Express Graphics
PCH	Platform Controller Hub
eDP	Embedded DisplayPort
T.O.M.	Top of memory = max. DRAM installed
HDA	High Definition Audio
N.C	Not connected
N.A	Not available
TBD	To be determined

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1 Introduction

1.1 COM Express™ Concept

COM Express™ is an open industry standard defined specifically for COMs (computer on modules). Its creation makes it possible to smoothly transition from legacy interfaces to the newest technologies available today. COM Express™ modules are available in following form factors:

- Mini 84mm x 55mm
- Compact 95mm x 95mm
- Basic 125mm x 95mm
- Extended 155mm x 110mm

The COM Express™ specification 2.1 defines seven different pinout types.

Types	Connector Rows	PCI Express Lanes	PCI	IDE Channels	LAN ports	USB 2.0/ USB 3.0	Display Interfaces
Type 1	A-B	Up to 6			1	8 / 0	VGA, LVDS
Type 2	A-B C-D	Up to 22	32 bit	1	1	8 / 0	VGA, LVDS, PEG/SDVO
Type 3	A-B C-D	Up to 22	32 bit		3	8 / 0	VGA, LVDS, PEG/SDVO
Type 4	A-B C-D	Up to 32		1	1	8 / 0	VGA, LVDS, PEG/SDVO
Type 5	A-B C-D	Up to 32			3	8 / 0	VGA, LVDS, PEG/SDVO
Type 6	A-B C-D	Up to 24			1	8 / 4	VGA, LVDS, PEG, 3x DDI
Type 10	A-B	Up to 4			1	8 / 0	1x DDI

The conga-TC97 modules use the Type 6 pinout definition and comply with COM Express 2.1 specification. They are equipped with two high performance connectors that ensure stable data throughput.

The COM (computer on module) integrates all the core components and is mounted onto an application specific carrier board. COM modules are legacy-free design (no Super I/O, PS/2 keyboard and mouse) and provide most of the functional requirements for any application. These functions include, but are not limited to a rich complement of contemporary high bandwidth serial interfaces such as PCI Express, Serial ATA, USB 2.0, and Gigabit Ethernet. The Type 6 pinout provides the ability to offer PCI Express, Serial ATA, and LPC options thereby expanding the range of potential peripherals. The robust thermal and mechanical concept, combined with extended power-management capabilities, is perfectly suited for all applications.

Carrier board designers can use as little or as many of the I/O interfaces as deemed necessary. The carrier board can therefore provide all the interface connectors required to attach the system to the application specific peripherals. This versatility allows the designer to create a dense and optimized package, which results in a more reliable product while simplifying system integration. Most importantly, COM Express™ modules are scalable, which means once an application has been created there is the ability to diversify the product range through the use of different performance class or form factor size modules. Simply unplug one module and replace it with another; no redesign is necessary.

1.2 Options Information

The conga-TC97 is currently available in three variants. This user's guide describes all of these variants. The table below shows the different configurations available. Check for the Part No. that applies to your product. This will tell you what options described in this user's guide are available on your particular module.

Table 1 conga-TC97 Variants

Part-No.	045103	045104	045105	045106
Processor	Intel® Core™ i7-5650U 2.2 GHz Dual Core™	Intel® Core™ i5-5350U 1.8 GHz Dual Core™	Intel® Core™ i3-5010U 2.1 GHz Dual Core™	Intel® Celeron® 3765U 1.9 GHz Dual Core™
Intel® Smart Cache	4 MByte	3 MByte	3 MByte	2 MByte
Max. Turbo Frequency	3.2 GHz	2.9 GHz	N.A	N.A
Processor Graphics	Intel® HD graphics 6000 (GT3)	Intel® HD graphics 6000 (GT3)	Intel® HD graphics 5500 (GT2)	Intel® HD graphics (GT1)
Graphics Max. Dynamic Freq	1.0 GHz	1.0 GHz	0.9 GHz	0.85 GHz
Memory (DDR3L)	1600 MT/s dual channel	1600 MT/s dual channel	1600 MT/s dual channel	1600 MT/s dual channel
LVDS	Yes	Yes	Yes	Yes
DisplayPort (DP)	Yes	Yes	Yes	Yes
HDMI	Yes	Yes	Yes	Yes
Processor TDP (Max)	15 W	15 W	15 W	15 W

2 Specifications

2.1 Feature List

Table 2 Feature Summary

Form Factor	Based on COM Express™ standard pinout Type 6 Rev. 2.1 (Compact size 95 x 95 mm).	
Processor	5 th Generation Intel® Core™ i7,i5, i3 Single Chip Ultra Low TDP Processors.	
Memory	Two memory sockets (located on the top and bottom side of the conga-TC97). Supports <ul style="list-style-type: none"> - SO-DIMM non-ECC DDR3L (low voltage @ 1.35V) modules - Data rates up to 1600 MT/s - Maximum 32 GB capacity 	
congatec Board Controller	Multi-stage watchdog, non-volatile user data storage, manufacturing and board information, board statistics, hardware monitoring, fan control, I2C bus, Power loss control.	
Chipset	Intel® 9 Series PCH-LP integrated in the Multi-Chip Package.	
Audio	High Definition Audio (HDA)/digital audio interface with support for multiple codecs	
Ethernet	Gigabit Ethernet support via the onboard Intel® I218LM GbE Phy. Also offers AMT 10 support.	
Graphics Options	<p>Next Generation Intel® HD Graphics (6000/5500) with support for Intel® Clear Video Technology (HD encode/transcode, Blu-ray playback), DirectX Video Acceleration (full AVC/VC1/MPEG2 hardware decode), OpenGL 4.0 and DirectX11.1. Up to 3 independent displays supported (Must be two DDI's (DP, HDMI/DVI) plus one eDP/LVDS)</p> <p>LVDS (Integrated flat panel interface with 25-112MHz single/dual-channel LVDS Transmitter). Supports:</p> <ul style="list-style-type: none"> - Single-channel LVDS interface: 1 x 18 bpp or 1 x 24 bpp. - Dual channel LVDS interface: 2 x 18 bpp or 2 x 24 bpp panel. - VESA LVDS and OpenLDI color mappings - Automatic Panel Detection via Embedded Panel Interface based on VESA EDID™ 1.3. - Resolution up to 1920x1200 in dual LVDS bus mode. <p>Optional eDP interface (NOTE: Either eDP or LVDS signals supported. Both not supported).</p>	
Peripheral Interfaces	<p>4x Serial ATA® 6Gb/s with RAID support 0/1/5/10</p> <p>4 PCI Express® Lanes (can be configured via special/customized BIOS firmware to support four x1 or one x4 links.</p> <p>8x USB 2.0 (EHCI)</p> <p>2x USB 3.0 (XHCI)</p> <p>2x Serial Interface (UART0/1)</p>	<p>2x DisplayPort 1.2 (DP): 2x DisplayPorts on digital ports B, C. Multiplexed with HDMI/DVI ports. Hot-Plug detect support.</p> <p>2x HDMI 1.4: 2x HDMI ports on digital ports B, C. Multiplexed with DisplayPort (DP)/DVI. Hot-plug detect support.</p> <p>2x DVI: 2x DVI ports on digital ports B, C. Multiplexed with HDMI/DP ports. Hot-Plug detect support.</p> <p>Optional VGA interface (NOTE: This option is offered on digital port C. The display combination for revisions with VGA support is 1x DDI, 1x VGA and 1x LVDS/eDP).</p>
BIOS	AMI Aptio® UEFI 5.x firmware, 8 or 16 MByte serial SPI with congatec Embedded BIOS features.	
Power Management	ACPI 4.0 compliant with battery support. Also supports Suspend to RAM (S3) and Intel AMT 10. Configurable TDP Ultra low standby power consumption, Deep Sx.	
Security	Optional discrete Trusted Platform Module "TPM 1.2/2.0"; new AES Instructions for faster and better encryption.	



Note

Some of the features mentioned in the above feature summary are optional. Check the part number of your module and compare it to the options information table in section 1.2 to determine what options are available on your particular module.

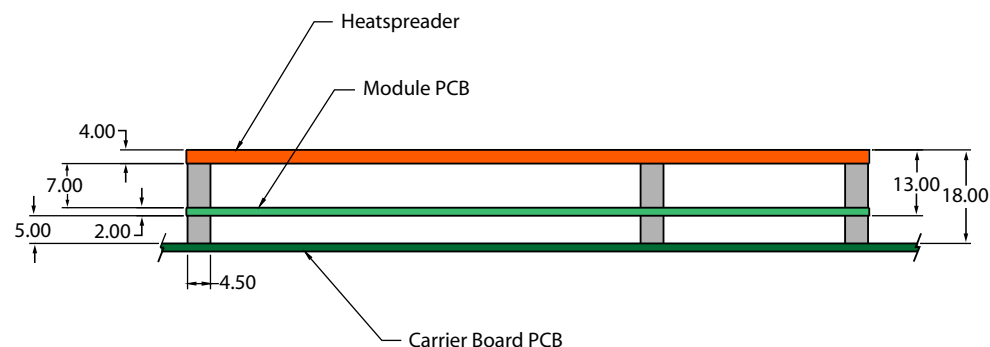
2.2 Supported Operating Systems

The conga-TC97 supports the following operating systems.

- Microsoft® Windows® 10
- Microsoft® Windows® 8
- Microsoft® Windows® 7
- Microsoft® Windows® Embedded Standard
- Linux

2.3 Mechanical Dimensions

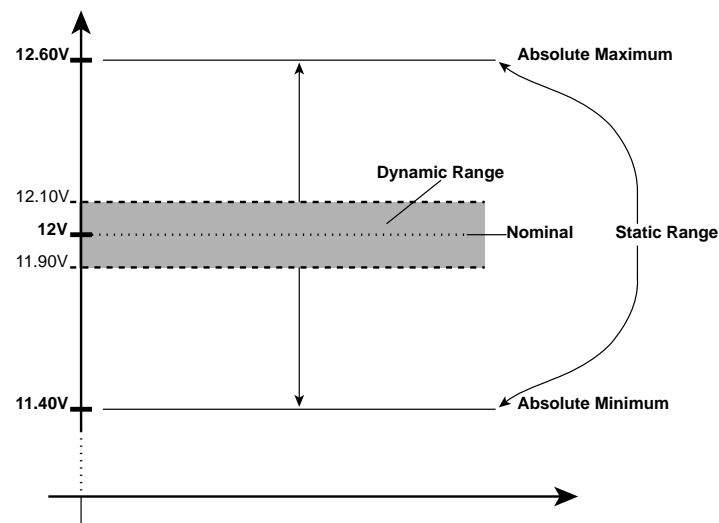
- 95.0 mm x 95.0 mm (3.74" x 3.74")
- Height approximately 18 or 21mm (including heatspreader) depending on the carrier board connector that is used. If the 5mm (height) carrier board connector is used, then approximate overall height is 18mm. If the 8mm (height) carrier board connector is used, then approximate overall height is 21mm.



2.4 Supply Voltage Standard Power

- 12V DC \pm 5%

The dynamic range shall not exceed the static range.



2.4.1 Electrical Characteristics

Power supply pins on the module's connectors limit the amount of input power. The following table provides an overview of the limitations for pinout Type 6 (dual connector, 440 pins).

Power Rail	Module Pin Current Capability (Amps)	Nominal Input (Volts)	Input Range (Volts)	Derated Input (Volts)	Max. Input Ripple (10Hz to 20MHz) (mV)	Max. Module Input Power (w. derated input) (Watts)	Assumed Conversion Efficiency	Max. Load Power (Watts)
VCC_12V	12	12	11.4-12.6	11.4	+/- 100	137	85%	116
VCC_5V-SBY	2	5	4.75-5.25	4.75	+/- 50	9		
VCC_RTC	0.5	3	2.0-3.3		+/- 20			

2.4.2 Rise Time

The input voltages shall rise from 10% of nominal to 90% of nominal at a minimum slope of 250V/s. The smooth turn-on requires that, during the 10% to 90% portion of the rise time, the slope of the turn-on waveform must be positive.

2.5 Power Consumption

The power consumption values listed in this document were measured under a controlled environment. The hardware used for testing includes a conga-TC97 module, conga-TEVAL carrier board, HDMI-equipped LCD monitor, SATA SSD drive, and USB keyboard/mouse. The SATA drive was powered externally by an ATX power supply so that it does not influence the power consumption value that is measured for the module. To ensure that only the power consumption of the CPU module is measured, the conga-TEVAL power consumption was determined before the measurement and subtracted from the overall power consumption value measured.

The USB keyboard/mouse were detached once the module was configured within the OS. All recorded values were averaged over a 30 second time period. Cooling of the module was done by the module specific heatspreader and a fan cooled heatsink to measure the power consumption under normal thermal conditions.

Each module was measured while running Windows 7 Professional 64Bit, Hyper Threading enabled, Speed Step enabled, CPU Turbo Mode enabled and Power Plan set to "Power Saver". This setting ensures that Core™ processors run in LFM (lowest frequency mode) with minimal core voltage during desktop idle. Each module was tested while using two 2GB memory modules. Using different sizes of RAM, as well as one or two memory modules, will cause slight variances in the measured results.

To measure the worst case power consumption the cooling solution was removed and the CPU core temperature was allowed to run up to between 90° and 95°C while running 100% workload with the Power Plan set to "Balanced". The peak current value was then recorded. This value should be taken into consideration when designing the system's power supply to ensure that the power supply is sufficient during worst case scenarios.

Power consumption values were recorded during the following stages:

Windows 7 (64 bit)

- Desktop Idle (power plan = Power Saver)
- 100% CPU workload (see note below, power plan = Power Saver)
- 100% CPU workload at approximately 100°C peak power consumption (power plan = Balanced)
- Suspend to RAM. Supply power for S3 mode is 5V.



Note

A software tool was used to stress the CPU to Max Turbo Frequency.

Processor Information

The tables below provide additional information about the power consumption data for each of the conga-TC97 variants offered. The values are recorded at various operating mode.

2.5.1 Intel® Core™ i7-5650U

Part No. 045103 (GT3 Graphics)	Intel® Core™ i7-5650U 2.2 GHz 2 Core™ 4MB Intel® Smart Cache (14nm) Hardware revision TU97LD0 /BIOS revision TU97R003			
Max Turbo Frequency	3.2 GHz			
Memory Size	4GB			
Operating System	Windows 7 (64 bit)			
Power State	Desktop Idle	100% workload	100% workload in Turbo mode (peak)	Suspend to Ram (S3) 5V Input Power
Power consumption (measured in Amps./Watts)	0.28 A/ 3.40 W	1.50 A/ 18.00 W	2.13 A/ 25.50 W	0.08 A/ 0.40 W

2.5.2 Intel® Core™ i5-5350U

Part No. 045104 (GT3 Graphics)	Intel® Core™ i5-5350U 1.8 GHz 2 Core™ 3MB Intel® Smart Cache (14nm) Hardware revision TU97LD0 /BIOS revision TU97R003			
Max Turbo Frequency	2.9 GHz			
Memory Size	4GB			
Operating System	Windows 7 (64 bit)			
Power State	Desktop Idle	100% workload	100% workload in Turbo mode (peak)	Suspend to Ram (S3) 5V Input Power
Power consumption (measured in Amps./Watts)	0.29 A/ 3.50 W	1.43 A/ 17.10 W	1.72 A/ 20.60 W	0.14 A/ 0.7 W

2.5.3 Intel® Core™ i3-5010U

Part No. 045105 (GT2 Graphics)	Intel® Core™ i3-5010U 2.1 GHz 2 Core™ 3MB Intel® Smart Cache (14nm) Hardware revision TU97LD0 /BIOS revision TU97R003			
Max Turbo Frequency	N.A			
Memory Size	4GB			
Operating System	Windows 7 (64 bit)			
Power State	Desktop Idle	100% workload	100% workload approx. 100% CPU temp (peak)	Suspend to Ram (S3) 5V Input Power
Power consumption (measured in Amps./Watts)	0.27 A/ 3.20 W	1.18 A/ 14.20 W	N.A	0.12 A/ 0.60 W

2.5.4 Intel® Celeron® 3765U

Part No. 045106 (GT2 Graphics)	Intel® Celeron® 3765U 1.9 GHz 2 Core™ 2MB Intel® Smart Cache (14nm) Hardware revision TU97LD0 /BIOS revision TU97R003			
Max Turbo Frequency	N.A			
Memory Size	4GB			
Operating System	Windows 7 (64 bit)			
Power State	Desktop Idle	100% workload	100% workload approx. 100% CPU temp (peak)	Suspend to Ram (S3) 5V Input Power
Power consumption (measured in Amps./Watts)	TBD	TBD	TBD	TBD

2.6 Supply Voltage Battery Power

- 2.0V-3.5V DC
- Typical 3V DC

2.6.1 CMOS Battery Power Consumption

RTC @	Voltage	Current
-10°C	3V DC	1.56 µA
20°C	3V DC	1.82 µA
70°C	3V DC	3.60 µA

The CMOS battery power consumption value listed above should not be used to calculate CMOS battery lifetime. You should measure the CMOS battery power consumption in your customer specific application in worst case conditions, for example during high temperature and high battery voltage. The self-discharge of the battery must also be considered when determining CMOS battery lifetime. For more information about calculating CMOS battery lifetime refer to application note AN9_RTC_Battery_Lifetime.pdf on congatec AG website at www.congatec.com.

2.7 Environmental Specifications

Temperature	Operation: 0° to 60°C	Storage: -20° to +80°C
Humidity	Operation: 10% to 90%	Storage: 5% to 95%

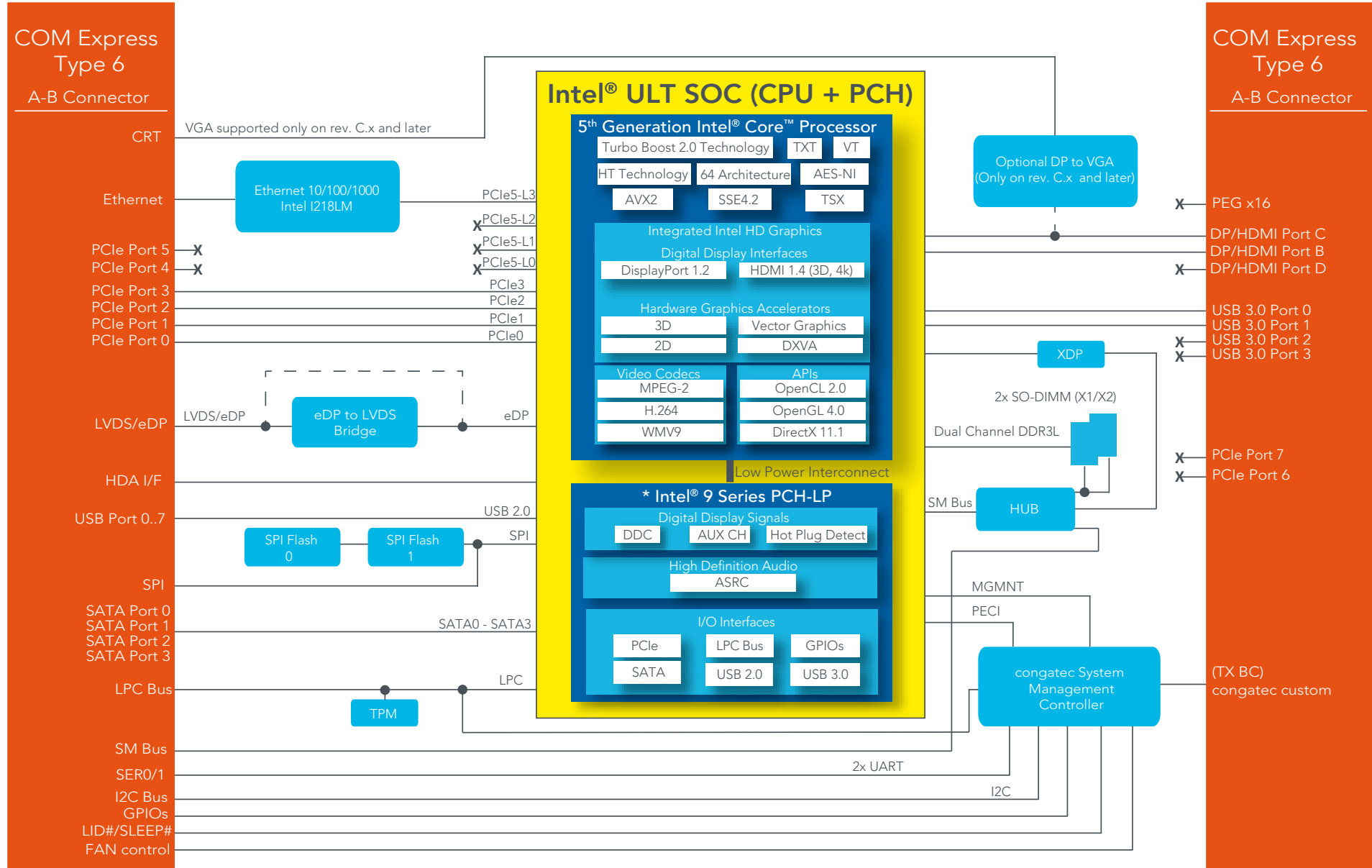


Caution

The above operating temperatures must be strictly adhered to at all times. When using a congatec heatspreader, the maximum operating temperature refers to any measurable spot on the heatspreader's surface.

Humidity specifications are for non-condensing conditions.

3 Block Diagram



* Intel 8 Series PCH-LP for single chip solutions.

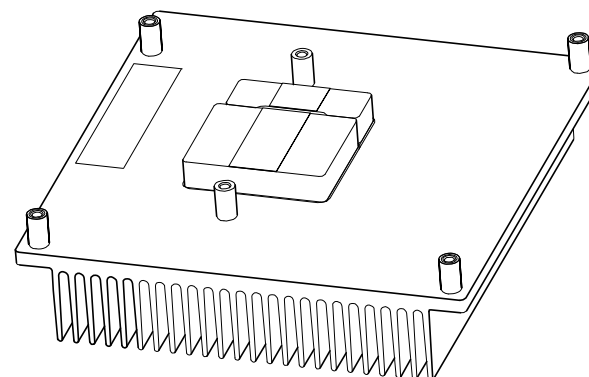
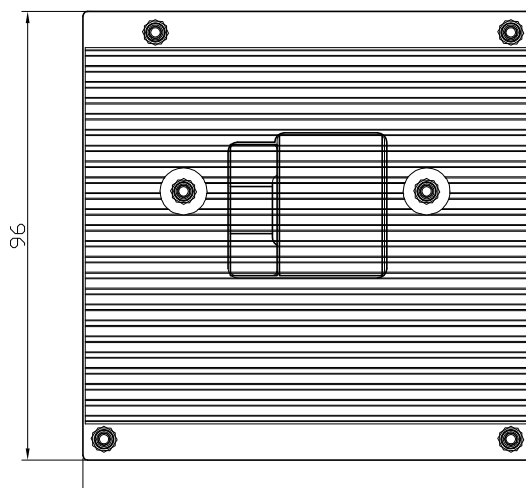
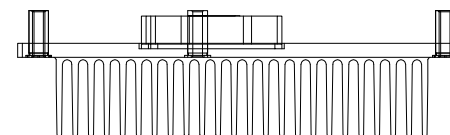
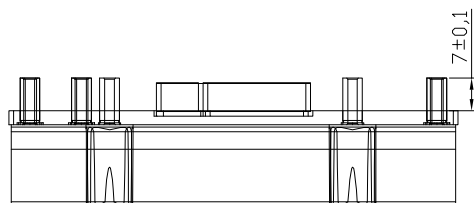
4 Cooling Solutions

congatec AG offers two cooling solutions for the conga-TC97:

- Passive cooling solution (CSP)
- Heatspreader

The dimensions of the cooling solutions are shown below. All measurements are in millimeters. The maximum torque specification for heatspreader screws is 0.3 Nm. Mechanical system assembly mounting shall follow the valid DIN/ISO specifications.

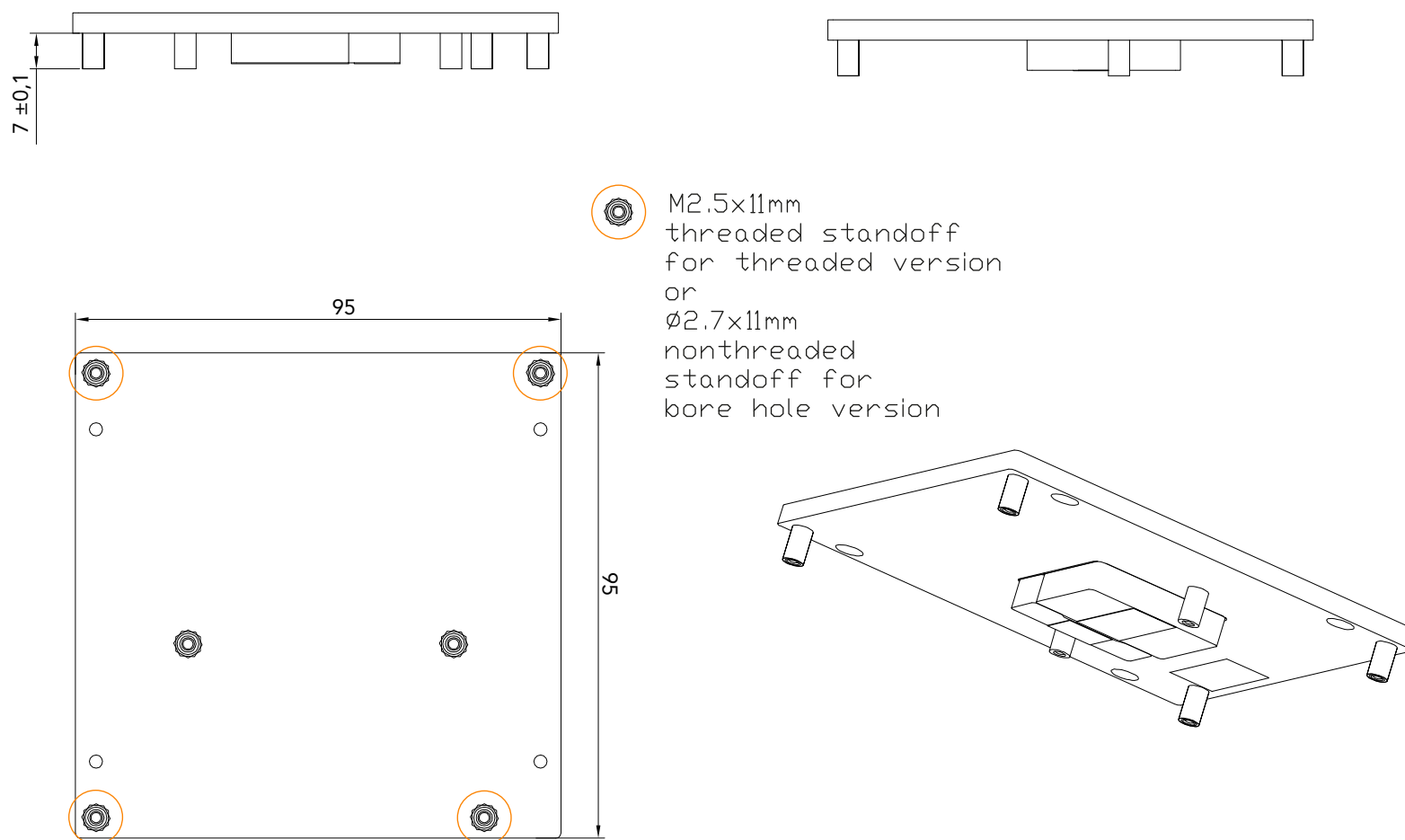
4.1 CSP Dimensions



4.2 Heatspreader Dimensions

The heatspreader acts as a thermal coupling device to the module and is thermally coupled to the CPU via a thermal gap filler. On some modules, it may also be thermally coupled to other heat generating components with the use of additional thermal gap fillers.

Although the heatspreader is the thermal interface where most of the heat generated by the module is dissipated, it is not to be considered as a heatsink. It has been designed as a thermal interface between the module and the application specific thermal solution. The application specific thermal solution may use heatsinks with fans, and/or heat pipes, which can be attached to the heatspreader. Some thermal solutions may also require that the heatspreader is attached directly to the systems chassis thereby using the whole chassis as a heat dissipater.





The gap pad material used on all heatspreaders contains silicon oil that can seep out over time depending on the environmental conditions it is subjected to. For more information about this subject, contact your local congatec sales representative and request the gap pad material manufacturer's specification.

**Caution**

The congatec heatspreaders/cooling solutions are tested only within the commercial temperature range of 0° to 60°C. Therefore, if your application that features a congatec heatspreader/cooling solution operates outside this temperature range, ensure the correct operating temperature of the module is maintained at all times. This may require additional cooling components for your final application's thermal solution.

For adequate heat dissipation, use the mounting holes on the cooling solution to attach it to the module. Apply thread-locking fluid on the screws if the cooling solution is used in a high shock and/or vibration environment. To prevent the standoff from stripping or cross-threading, use non-threaded carrier board standoffs to mount threaded cooling solutions.

For applications that require vertically-mounted cooling solution, use only coolers that secure the thermal stacks with fixing post. Without the fixing post feature, the thermal stacks may move.

Also, do not exceed the maximum torque specified for the cooling solution screws. Doing so may damage the module or/and the carrier board.

5 Connector Rows

The conga-TC97 is connected to the carrier board via two 220-pin connectors (COM Express Type 6 pinout) for a total of 440 pins connectivity. These connectors are broken down into four rows. The primary connector consists of rows A and B while the secondary connector consists of rows C and D.

5.1 Primary Connector Rows A and B

The following subsystems can be found on the primary connector rows A and B.

5.1.1 Serial ATA™ (SATA)

The conga-TC97 provides 4 SATA interfaces (SATA 0-3) externally via the Intel® 9 Series PCH-LP integrated in the Multi-Chip Package. The SATA ports are based on Serial ATA specification, revision 3.0 and support up to 6.0 Gb/s data transfer rates.

The Intel® 9 Series PCH-LP featured on the conga-TC97 has one integrated SATA host controller. This controller supports only one mode of operation - AHCI mode using memory space. It does not support legacy mode using I/O space. Hot-plug is also supported when operating in non-native IDE mode. For more information, refer to section 10 “BIOS Setup Description”.

5.1.2 USB 2.0

The conga-TC97 offers 8 USB 2.0 interfaces on the A-B connector. The EHCI host controller in the PCH supports these interfaces with high-speed, full-speed and low-speed USB signaling. The controller complies with USB standard 1.1 and 2.0. For more information about how the USB host controllers are routed, see section 7.5.

5.1.3 High Definition Audio (HDA) Interface

The conga-TC97 provides an interface that supports the connection of HDA audio codecs.

5.1.4 Gigabit Ethernet

The conga-TC97 is equipped with a Gigabit Ethernet Controller that is integrated within the Intel® 9 Series PCH-LP. This controller is routed to the onboard Intel® I218-LM Phy through the use of the fifth PCI Express lane. The Ethernet interface consists of 4 pairs of low voltage differential pair signals designated from GBE0_MD0± to GBE0_MD3± plus control signals for link activity indicators. These signals can be used to connect

to a 10/100/1000 BaseT RJ45 connector with integrated or external isolation magnetics on the carrier board.



Note

The GBE0_LINK# output is only active during a 100Mbit or 1Gbit connection. It is not active during a 10Mbit connection. This is a limitation of Ethernet controller since it only has 3 LED outputs, ACT#, LINK100# and LINK1000#. The GBE0_LINK# signal is a logic AND of the GBE0_LINK100# and GBE0_LINK1000# signals on the conga-TC97 module.

5.1.5 LPC Bus

conga-TC97 offers the LPC (Low Pin Count) bus through the Intel® 9 Series PCH-LP. There are many devices available for this Intel® defined bus. The LPC bus corresponds approximately to a serialized ISA bus yet with a significantly reduced number of signals. Due to the software compatibility to the ISA bus, I/O extensions such as additional serial ports can be easily implemented on an application specific baseboard using this bus. See section 9.1.1 for more information about the LPC Bus.

5.1.6 I²C Bus Fast Mode

The I²C bus is implemented through the congatec board controller (Texas Instruments Tiva™ TM4E1231H6ZRB) and accessed through the congatec CGOS driver and API. The controller provides a Fast Mode multi-master I²C Bus that has maximum I²C bandwidth.

5.1.7 PCI Express™

The conga-TC97 offers 4 PCI Express™ lanes externally on the A-B connector via the Intel® 9 Series PCH-LP. The lanes are Gen 2 compliant and offer support for full 5 Gb/s bandwidth in each direction per x1 link.

Default configuration for the lanes on the AB connector is 4x1 link. A 1x4 and 2x2 link configuration is also possible but requires a special/ customized BIOS firmware. Contact congatec technical support for more information about this subject.

The PCI Express interface is based on the PCI Express Specification 2.0 with Gen 1 (2.5Gb/s) and Gen 2 (5 Gb/s) speed.

5.1.8 ExpressCard™

The conga-TC97 supports the implementation of ExpressCards, which requires the dedication of one USB 2.0 port or a x1 PCI Express link for each ExpressCard used.

5.1.9 Graphics Output (VGA/CRT)

The Intel® ULT SoC does not support VGA interface, however on the conga-TC97, an optional VGA interface is supported on the DDI digital port C via NXP PTN3392BS Displayport to VGA controller.

5.1.10 LCD (LVDS/eDP)

The conga-TC97 offers an LVDS/eDP interface on the AB connector. The LVDS/eDP interface is by default configured to provide LVDS signals. The interface can optionally be switched via the BIOS setup menu to support eDP signals.

The single/dual channel LVDS interface is provided through an onboard eDP to LVDS bridge device. The eDP to LVDS bridge processes incoming DisplayPort stream and converts the DP protocol to LVDS, before transmitting the processed stream in LVDS format. The bridge supports single and dual channel signalling with color depths of 18 bits or 24 bits per pixel and pixel clock frequency up to 112 MHz.



Note

The LVDS/eDP interface supports either LVDS or eDP signals. Both signals are not supported simultaneously.

5.1.11 General Purpose Serial Interface

Two TTL compatible two wire ports are available on Type 6 COM Express modules. These pins are designated SER0_TX, SER0_RX, SER1_TX and SER1_RX. Data out of the module is on the _TX pins. Hardware handshaking and hardware flow control are not supported. The module asynchronous serial ports are intended for general purpose use and for use with debugging software that make use of the “console redirect” features available in many operating systems.

The conga-TC97 offers two UART interfaces via two UART controllers integrated in the congatec Board Controller. These controllers support up to 1MBit/s and can operate in low-speed, full-speed and high-speed modes. The UART interfaces are routed to the AB connector and require congatec driver to function..



Note

The UART interfaces do not support legacy COM port emulation.

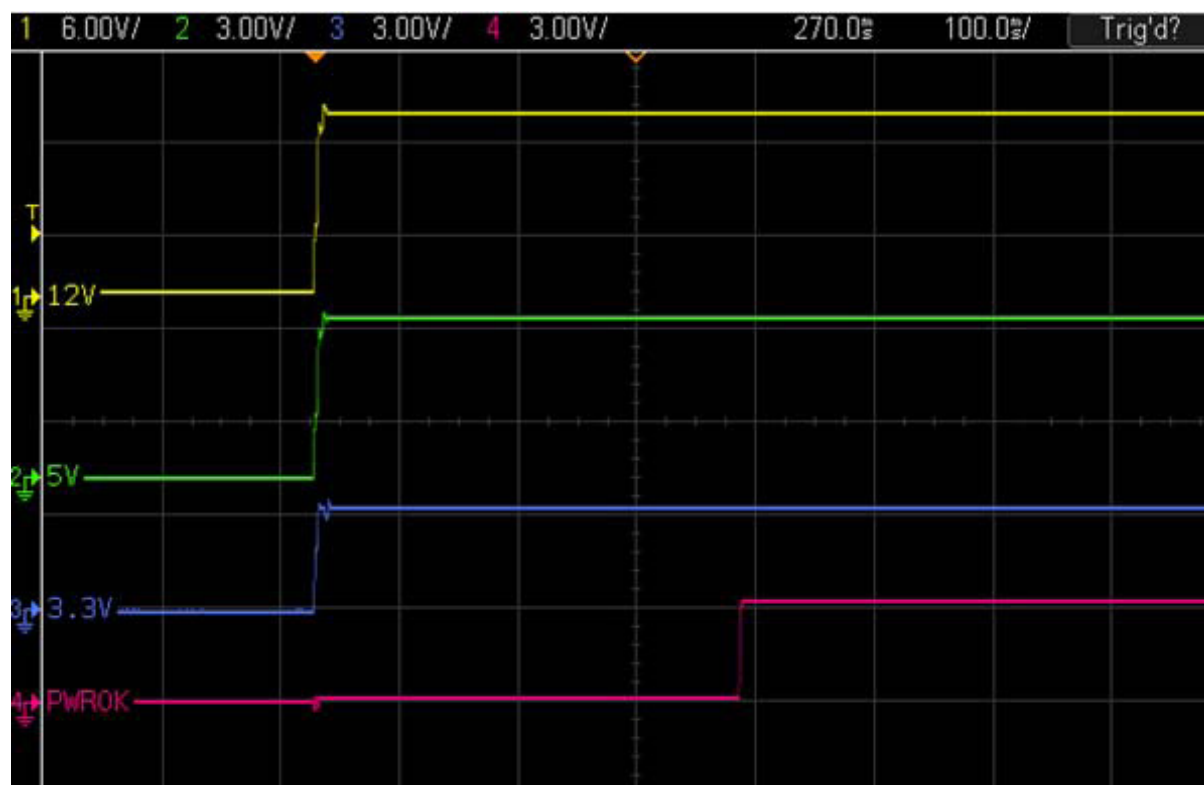
5.1.12 Power Control

PWR_OK

Power OK from main power supply or carrier board voltage regulator circuitry. A high value indicates that the power is good and the module can start its onboard power sequencing.

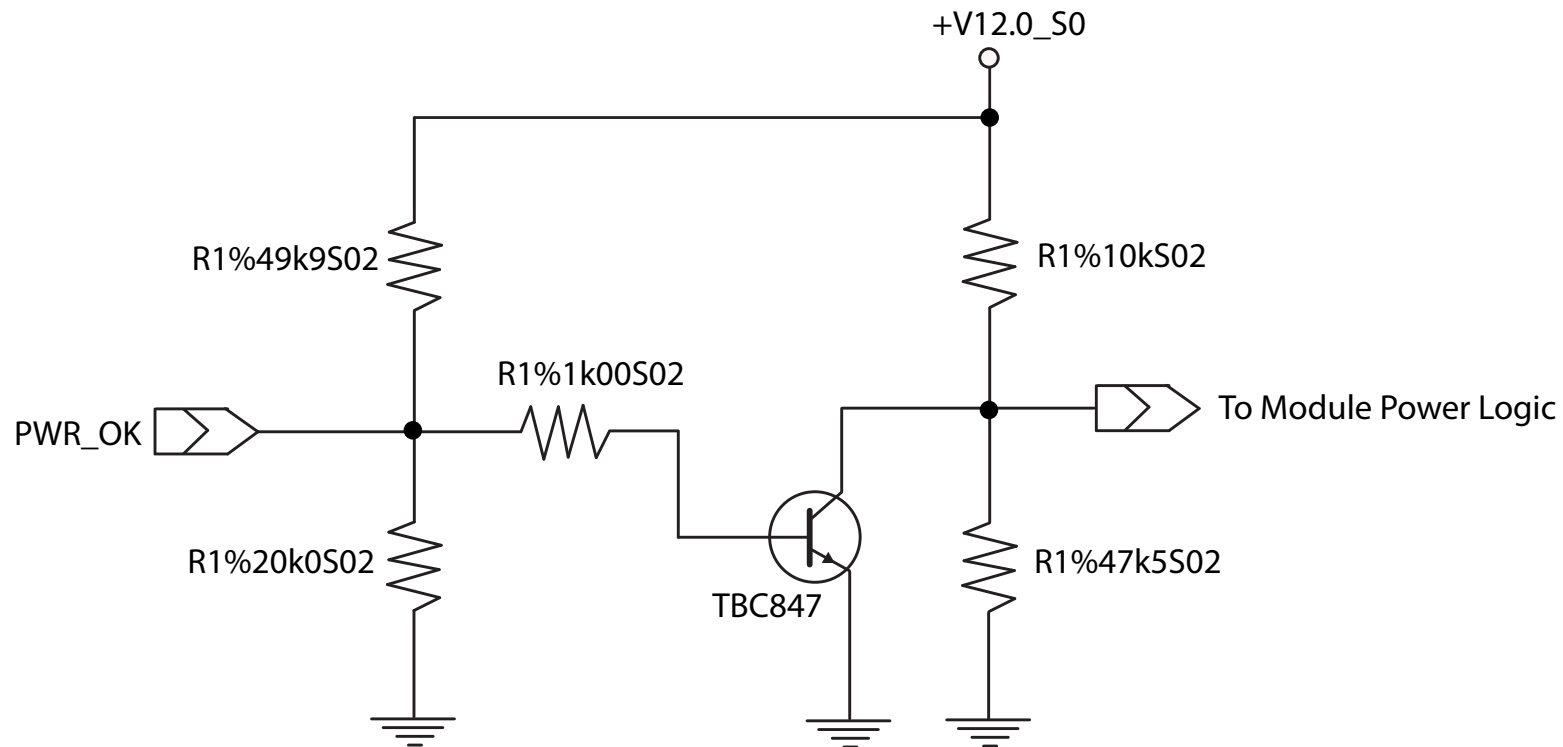
Carrier board hardware must drive this signal low until all power rails and clocks are stable. Releasing PWR_OK too early or not driving it low at all can cause numerous boot up problems. It is a good design practice to delay the PWR_OK signal a little (typically 100ms) after all carrier board power rails are up, to ensure a stable system.

A sample screenshot is shown below:



The module is kept in reset as long as the PWR_OK is driven by carrier board hardware.

The conga-TC97 PWR_OK input circuitry is implemented as shown below:



The voltage divider ensures that the input complies with 3.3V CMOS characteristic and also allows for carrier board designs that are not driving PWR_OK. Although the PWR_OK input is not mandatory for the onboard power-up sequencing, it is strongly recommended that the carrier board hardware drives the signal low until it is safe to let the module boot-up.

When considering the above shown voltage divider circuitry and the transistor stage, the voltage measured at the PWR_OK input pin may be only around 0.8V when the 12V is applied to the module. Actively driving PWR_OK high is compliant to the COM Express specification but this can cause back driving. Therefore, congatec recommends driving the PWR_OK low to keep the module in reset and tri-state PWR_OK when the carrier board hardware is ready to boot.

The three typical usage scenarios for a carrier board design are:

- Connect PWR_OK to the “power good” signal of an ATX type power supply.

-
- Connect PWR_OK to the last voltage regulator in the chain on the carrier board.
 - Simply pull PWR_OK with a 1k resistor to the carrier board 3.3V power rail.

With this solution, it must be ensured that by the time the 3.3V is up, all carrier board hardware is fully powered and all clocks are stable.

The conga-TC97 provides support for controlling ATX-style power supplies. When not using an ATX power supply then the conga-TC97's pins SUS_S3/PS_ON, 5V_SB, and PWRBTN# should be left unconnected.

SUS_S3#/PS_ON#

The SUS_S3#/PS_ON# (pin A15 on the A-B connector) signal is an active-low output that can be used to turn on the main outputs of an ATX-style power supply. In order to accomplish this the signal must be inverted with an inverter/transistor that is supplied by standby voltage and is located on the carrier board.

PWRBTN#

When using ATX-style power supplies PWRBTN# (pin B12 on the A-B connector) is used to connect to a momentary-contact, active-low debounced push-button input while the other terminal on the push-button must be connected to ground. This signal is internally pulled up to 3V_SB using a 10k resistor. When PWRBTN# is asserted it indicates that an operator wants to turn the power on or off. The response to this signal from the system may vary as a result of modifications made in BIOS settings or by system software.

Power Supply Implementation Guidelines

12 volt input power is the sole operational power source for the conga-TC97. The remaining necessary voltages are internally generated on the module using onboard voltage regulators. A carrier board designer should be aware of the following important information when designing a power supply for a conga-TC97 application:

- It has also been noticed that on some occasions, problems occur when using a 12V power supply that produces non monotonic voltage when powered up. The problem is that some internal circuits on the module (e.g. clock-generator chips) will generate their own reset signals when the supply voltage exceeds a certain voltage threshold. A voltage dip after passing this threshold may lead to these circuits becoming confused resulting in a malfunction. It must be mentioned that this problem is quite rare but has been observed in some mobile power supply applications. The best way to ensure that this problem is not encountered is to observe the power supply rise waveform through the use of an oscilloscope to determine if the rise is indeed monotonic and does not have any dips. This should be done during the power supply qualification phase therefore ensuring that the above mentioned problem doesn't arise in the application. For more information about this issue visit www.formfactors.org and view page 25 figure 7 of the document "ATX12V Power Supply Design Guide V2.2".

5.1.13 Power Management

ACPI

The conga-TC97 supports Advanced Configuration and Power Interface (ACPI) specification, revision 4.0a. It also supports Suspend to RAM (S3). For more information, see section 7.3 "ACPI Suspend Modes and Resume Events".

DEEP Sx

The Deep Sx is a lower power state employed to minimize the power consumption while in S3/S4/S5. In the Deep Sx state, the system entry condition determines if the system context is maintained or not. All power is shut off except for minimal logic which supports limited set of wake events for Deep Sx. The Deep Sx on resumption, puts system back into the state it is entered from. In other words, if Deep Sx state was entered from S3 state, then the resume path will place system back into S3.

5.2 Secondary Connector Rows C and D

The following subsystems can be found on the secondary connector rows C and D.

5.2.1 PCI Express™

The conga-TC97 does not offer PCI Express lanes on the CD connector. For more information on supported PCIe lanes, see section 5.1.7.

5.2.2 PCI Express Graphics (PEG)

The Intel® ULT SoC does not support PEG interface.

5.2.3 Digital Display Interface

The conga-TC97 supports two Digital Display Interfaces. These interfaces can be configured as DisplayPort, HDMI/DVI. On conga-TC97 rev C.x and later, the DDI digital port C is used for optional VGA support.

The processor on the conga-TC97 supports High-bandwidth Digital Content Protection (HDCP) for playing high definition content over digital interfaces. Integrated in the processor is a dedicated Mini HD audio controller which drives audio on integrated digital display interfaces such as HDMI and DisplayPort.

The conga-TC97 offers the Digital Display Interface on the CD connector and supports up to three independent displays. The display combination must be 2 DDI and 1 eDP. For revisions equipped with optional VGA, the combination must be 1x DDI (Port B), 1x VGA (via Port C) and 1x eDP. The table below shows the supported display combinations. This table applies only to revisions without optional VGA interface.

Table 3 Display Combination (U-processor line)

Display 1 (DDI Port B)	Display 2 (DDI Port C)	Display 3	Display 1 Max. Resolution	Display 2 Max. Resolution	Display 3 Max. Resolution
HDMI	HDMI	eDP	4096x2304 @24Hz	4096x2304 @24Hz	3200x2000 @60Hz
DP	DP	eDP	3200x2000 @60Hz	3200x2000 @60Hz	3200x2000 @60Hz
HDMI	DP	eDP	4096x2304 @24Hz	3200x2000 @60Hz	3200x2000 @60Hz



The DP and eDP resolutions in the table above are supported for 4 lanes with link data rate HBR2 at 24 bits per pixel and single stream mode of operation. The DisplayPort Aux CH, DDC channel, panel power sequencing and HPD are supported through the PCH.

5.2.3.1 HDMI

The conga-TC97 offers two HDMI ports on the CD connector via the Digital Display Interfaces supported by the processor. The HDMI interfaces are based on HDMI 1.4 specification with support for 3D, 4K, Deep Color and x.v Color. These interfaces are multiplexed onto the Digital Display Interface of the COM Express connector.

Supported audio formats are AC-3 Dolby Digital, Dolby Digital Plus, DTS-HD, LPCM, 192 KHz/24 bit, 8 channel, Dolby TrueHD, DTS-HD Master Audio (Lossless Blu-Ray Disc Audio Format).



Note

The conga-TC97 supports a maximum of 2 independent HDMI displays. Revisions equipped with optional VGA interface support only 1 HDMI interface. See table 2 above for possible display combinations. Consumer electronics control (CEC) is not supported.

5.2.3.2 DVI

The conga-TC97 offers two DVI ports on the CD connector. The DVI interfaces are multiplexed onto the Digital Display Interface of the COM Express connector.



Note

The conga-TC97 supports a maximum of 2 independent DVI displays. Revisions equipped with optional VGA interface support only 1 DVI interface. See table 2 above for possible display combinations.

5.2.3.3 DisplayPort (DP)

The conga-TC97 offers two DP ports, each capable of supporting data rate of 1.62 GT/s, 2.97 GT/s and 5.4 GT/s on 1, 2 or 4 data lanes. The DP is multiplexed onto the Digital Display Interface (DDI) of the COM Express connector and can support up to 3200x2000 resolutions at 60Hz.

The DisplayPort specification is a VESA standard aimed at consolidating internal and external connection methods to reduce device complexity, supporting key cross industry applications, and providing performance scalability to enable the next generation of displays. See section 8.5 of this document for more information about enabling DisplayPort peripherals.



Note

The conga-TC97 supports a maximum of 2 independent DisplayPort displays. Revisions equipped with optional VGA interface support only 1 DP interface. See table 2 above for possible display combinations.

5.2.4 USB 3.0

The conga-TC97 offers two SuperSpeed USB 3.0 ports on the CD connector. These ports are controlled by an xHCI host controller provided by the Intel® 9 Series PCH-LP integrated in the Multi-Chip Package. The host controller allows data transfers of up to 5 Gb/s and supports SuperSpeed, high-speed, full-speed and low-speed traffic.



The xHCI controller supports USB 3.0 debugging.

6 Additional Features

6.1 congatec Board Controller (cBC)

The conga-TC97 is equipped with Texas Instruments Tiva™ TM4E1231H6ZRB microcontroller. This onboard microcontroller plays an important role for most of the congatec embedded/industrial PC features. It fully isolates some of the embedded features such as system monitoring or the I²C bus from the x86 core architecture, which results in higher embedded feature performance and more reliability, even when the x86 processor is in a low power mode. It also ensures that the congatec embedded feature set is fully compatible amongst all congatec modules.

6.2 Board Information

The cBC provides a rich data-set of manufacturing and board information such as serial number, EAN number, hardware and firmware revisions, and so on. It also keeps track of dynamically changing data like runtime meter and boot counter.

6.3 Watchdog

The conga-TC97 is equipped with a multi stage watchdog solution that is triggered by software. The COM Express™ Specification does not provide support for external hardware triggering of the Watchdog, which means the conga-TC97 does not support external hardware triggering. For more information about the Watchdog feature, see the BIOS setup description in section 10.4.2 of this document and application note AN3_Watchdog.pdf on the congatec AG website at www.congatec.com.



Note

The conga-TC97 module does not support the watchdog NMI mode.

6.4 I²C Bus

The conga-TC97 supports I²C bus. Thanks to the I²C host controller in the cBC, the I²C bus is multi-master capable and runs at fast mode.

6.5 Power Loss Control

The cBC has full control of the power-up of the module and therefore can be used to specify the behavior of the system after an AC power loss condition. Supported modes are "Always On", "Remain Off" and "Last State".

6.6 OEM BIOS Customization

The conga-TC97 is equipped with congatec Embedded BIOS, which is based on American Megatrends Inc. Aptio UEFI firmware. The congatec Embedded BIOS allows system designers to modify the BIOS. For more information about customizing the congatec Embedded BIOS, refer to the congatec System Utility user's guide, which is called CGUTLm1x.pdf and can be found on the congatec website at www.congatec.com or contact technical support.

The customization features supported are described below:

6.6.1 OEM Default Settings

This feature allows system designers to create and store their own BIOS default configuration. Customized BIOS development by congatec for OEM default settings is no longer necessary because customers can easily perform this configuration by themselves using the congatec system utility CGUTIL. See congatec application note AN8_Create_OEM_Default_Map.pdf on the congatec website for details on how to add OEM default settings to the congatec Embedded BIOS.

6.6.2 OEM Boot Logo

This feature allows system designers to replace the standard text output displayed during POST with their own BIOS boot logo. Customized BIOS development by congatec for OEM Boot Logo is no longer necessary because customers can easily perform this configuration by themselves using the congatec system utility CGUTIL. See congatec application note AN8_Create_And_Add_Bootlogo.pdf on the congatec website for details on how to add OEM boot logo to the congatec Embedded BIOS.

6.6.3 OEM POST Logo

This feature allows system designers to replace the congatec POST logo displayed in the upper left corner of the screen during BIOS POST with their own BIOS POST logo. Use the congatec system utility CGUTIL 1.5.4 or later to replace/add the OEM POST logo.

6.6.4 OEM BIOS Code/Data

With the congatec embedded BIOS it is possible for system designers to add their own code to the BIOS POST process. The congatec Embedded BIOS first calls the OEM code before handing over control to the OS loader.

Except for custom specific code, this feature can also be used to support Win XP SLP installation, Window 7 SLIC table (OA2.0), Windows 8 OEM activation (OA3.0), verb tables for HDA codecs, PCI/PCIe opROMs, bootloaders, rare graphic modes and Super I/O controller initialization.



Note

The OEM BIOS code of the new UEFI based firmware is only called when the CSM (Compatibility Support Module) is enabled in the BIOS setup menu. Contact congatec technical support for more information on how to add OEM code.

6.6.5 OEM DXE Driver

This feature allows designers to add their own UEFI DXE driver to the congatec embedded BIOS. Contact congatec technical support for more information on how to add an OEM DXE driver.

6.7 congatec Battery Management Interface

In order to facilitate the development of battery powered mobile systems based on embedded modules, congatec AG has defined an interface for the exchange of data between a CPU module (using an ACPI operating system) and a Smart Battery system. A system developed according to the congatec Battery Management Interface Specification can provide the battery management functions supported by an ACPI capable operating system (e.g. charge state of the battery, information about the battery, alarms/events for certain battery states, ...) without the need for any additional modifications to the system BIOS.

In addition to the ACPI-Compliant Control Method Battery mentioned above, the latest versions of the conga-TC97 BIOS and board controller firmware also support LTC1760 battery manager from Linear Technology and a battery only solution (no charger). All three battery solutions are supported on the I2C bus and the SMBus. This gives the system designer more flexibility when choosing the appropriate battery sub-system.

For more information about this subject visit the congatec website and view the following documents:

- congatec Battery Management Interface Specification
- Battery System Design Guide
- conga-SBM³ User's Guide

6.8 API Support (CGOS)

In order to benefit from the above mentioned non-industry standard feature set, congatec provides an API that allows application software developers to easily integrate all these features into their code. The CGOS API (congatec Operating System Application Programming Interface) is the congatec proprietary API that is available for all commonly used Operating Systems such as Win32, Win64, Win CE, Linux. The architecture of the CGOS API driver provides the ability to write application software that runs unmodified on all congatec CPU modules. All the hardware related code is contained within the congatec embedded BIOS on the module. See section 1.1 of the CGOS API software developers guide, which is available on the congatec website .

6.9 Security Features

The conga-TC97 can be equipped optionally with a “Trusted Platform Module” (TPM 1.2/2.0). This TPM 1.2/2.0 includes coprocessors to calculate efficient hash and RSA algorithms with key lengths up to 2,048 bits as well as a real random number generator. Security sensitive applications like gaming and e-commerce will benefit also with improved authentication, integrity and confidence levels.

6.10 Suspend to Ram

The Suspend to RAM feature is available on the conga-TC97.

7 conga Tech Notes

The conga-TC97 has some technological features that require additional explanation. The following section will give the reader a better understanding of some of these features. This information will also help to gain a better understanding of the information found in the System Resources section of this user's guide as well as some of the setup nodes found in the BIOS Setup Program description section.

7.1 Intel® PCH-LP Features

7.1.1 Intel® Rapid Storage Technology

The Intel® 9 Series PCH-LP provides support for Intel® Rapid Storage Technology, allowing AHCI functionality and RAID 0/1/5/10 support.

7.1.1.1 AHCI

The Intel® 9 Series PCH-LP provides hardware support for Advanced Host Controller Interface (AHCI), a standardized programming interface for SATA host controllers. Platforms supporting AHCI may take advantage of performance features such as port independent DMA engines (each device is treated as a master) and hardware-assisted native command queuing. AHCI also provides usability enhancements such as Hot-Plug and advanced power management.

7.1.1.2 RAID

The industry-leading RAID capability provides high performance RAID 0, 1, 5, and 10 functionality on the 4 SATA ports of Intel® 9 Series PCH-LP. Software components include an Option ROM for pre-boot configuration and boot functionality, a Microsoft* Windows* compatible driver, and a user interface for configuration and management of the RAID capability of the Intel® 9 Series PCH-LP.

7.1.1.3 Intel® Smart Response Technology

Intel® Smart Response Technology is a disk caching solution that can provide improved computer system performance with improved power savings. It allows configuration of a computer systems with the advantage of having HDDs for maximum storage capacity with system performance at or near SSD performance levels.



This feature requires an Intel® Core Processor

7.1.2 Intel® Rapid Start Technology

Intel® Rapid Start Technology enables systems to quickly resume from deep sleep. With this feature enabled, the system resumes smoothly and faster than with fresh Start Up or Resume from Hibernate, while maintaining the previous activity of the user.



Note

This feature requires an Intel® Core Processor

7.2 Intel® Processor Features

7.2.1 Intel® Turbo Boost Technology

Intel® Turbo Boost Technology allows processor cores to run faster than the base operating frequency if it's operating below power, current, and temperature specification limits. Intel® Turbo Boost Technology is activated when the Operating System (OS) requests the highest processor performance state. The maximum frequency of Intel® Turbo Boost Technology is dependent on the number of active cores. The amount of time the processor spends in the Intel Turbo Boost 2 Technology state depends on the workload and operating environment. Any of the following can set the upper limit of Intel® Turbo Boost Technology on a given workload:

- Number of active cores
- Estimated current consumption
- Estimated power consumption
- Processor temperature

When the processor is operating below these limits and the user's workload demands additional performance, the processor frequency will dynamically increase by 100 MHz on short and regular intervals until the upper limit is met or the maximum possible upside for the number of active cores is reached. For more information about Intel® Turbo Boost 2 Technology visit the Intel® website.



Note

Only conga-TC97 module variants that feature the Core™ i7 and i5 processors support Intel® Turbo Boost 2 Technology. Refer to the power consumption tables in section 2.5 of this document for information about the maximum turbo frequency available for each variant of the conga-TC97.

7.2.2 Thermal Monitor and Catastrophic Thermal Protection

Intel® Core™ i7/i5/i3 and Celeron® processors have a thermal monitor feature that helps to control the processor temperature. The integrated TCC (Thermal Control Circuit) activates if the processor silicon reaches its maximum operating temperature. The activation temperature that the Intel® Thermal Monitor uses to activate the TCC can be slightly modified via TCC Activation Offset in BIOS setup submenu "CPU submenu".

The Thermal Monitor can control the processor temperature through the use of two different methods defined as TM1 and TM2. TM1 method consists of the modulation (starting and stopping) of the processor clocks at a 50% duty cycle. The TM2 method initiates an Enhanced Intel Speedstep transition to the lowest performance state once the processor silicon reaches the maximum operating temperature.



The maximum operating temperature for Intel® Core™ i7/i5/i3 and Celeron® processors is 100°C.

To ensure that the TCC is active for only short periods of time, thus reducing the impact on processor performance to a minimum, it is necessary to have a properly designed thermal solution. The Intel® Core™ i7/i5/i3 and Celeron® processor's respective datasheet can provide you with more information about this subject.

THERMTRIP# signal is used by Intel®'s Core™ i7/i5/i3 and Celeron® processors for catastrophic thermal protection. If the processor's silicon reaches a temperature of approximately 125°C then the processor signal THERMTRIP# will go active and the system will automatically shut down to prevent any damage to the processor as a result of overheating. The THERMTRIP# signal activation is completely independent from processor activity and therefore does not produce any bus cycles.



In order for THERMTRIP# to be able to automatically switch off the system, it is necessary to use an ATX style power supply.

7.2.3 Processor Performance Control

Intel® Core™ i7/i5/i3 processors found on the conga-TC97 run at different voltage/frequency states (performance states), which is referred to as Enhanced Intel® SpeedStep® technology (EIST). Operating systems that support performance control take advantage of microprocessors that use several different performance states in order to efficiently operate the processor when it's not being fully used. The operating system will determine the necessary performance state that the processor should run at so that the optimal balance between performance and power consumption can be achieved during runtime.

The Windows family of operating systems links its processor performance control policy to the power scheme setting. You must ensure that the power scheme setting you choose has the ability to support Enhanced Intel® SpeedStep® technology.

7.2.4 Intel® 64 Architecture

The formerly known Intel® Extended Memory 64 Technology is an enhancement to Intel®'s IA-32 architecture. Intel® 64 is only available on Intel® Core™ i7/i5/i3 and Celeron® processors and is designed to run with newly written 64-bit code and access more than 4GB of memory. Processors with Intel® 64 architecture support 64-bit-capable operating systems from Microsoft, Red Hat and SuSE. Processors running in legacy mode remain fully compatible with today's existing 32-bit applications and operating systems

Platforms with Intel® 64 can be run in three basic ways :

1. **Legacy Mode:** 32-bit operating system and 32-bit applications. In this mode no software changes are required, however the benefits of Intel® 64 are not utilized.
2. **Compatibility Mode:** 64-bit operating system and 32-bit applications. This mode requires all device drivers to be 64-bit. The operating system will see the 64-bit extensions but the 32-bit application will not. Existing 32-bit applications do not need to be recompiled and may or may not benefit from the 64-bit extensions. The application will likely need to be re-certified by the vendor to run on the new 64-bit extended operating system.
3. **64-bit Mode:** 64-bit operating system and 64-bit applications. This usage requires 64-bit device drivers. It also requires applications to be modified for 64-bit operation and then recompiled and validated.

Intel® 64 supports:

- 64-bit flat virtual address space
- 64-bit pointers
- 64-bit wide general purpose registers
- 64-bit integer support
- Up to one Terabyte (TB) of platform address space

You can find more information about Intel® 64 Technology at: <http://developer.intel.com/technology/intel64/index.htm>

7.2.5 Intel® Virtualization Technology

Virtualization solutions enhanced by Intel® VT will allow a Core™ i7/i5/i3 platform to run multiple operating systems and applications in independent partitions. When using virtualization capabilities, one computer system can function as multiple “virtual” systems. With processor and I/O enhancements to Intel®’s various platforms, Intel® Virtualization Technology can improve the performance and robustness of today’s software-only virtual machine solutions.

Intel® VT is a multi-generational series of extensions to Intel® processor and platform architecture that provides a new hardware foundation for virtualization, establishing a common infrastructure for all classes of Intel® based systems. The broad availability of Intel® VT makes it possible to create entirely new applications for virtualization in servers, clients as well as embedded systems thus providing new ways to improve system reliability, manageability, security, and real-time quality of service.

The success of any new hardware architecture is highly dependent on the system software that puts its new features to use. In the case of virtualization technology, that support comes from the virtual machine monitor (VMM), a layer of software that controls the underlying physical platform resources sharing them between multiple “guest” operating systems. Intel® VT is already incorporated into most commercial and open-source VMMs including those from VMware, Microsoft, XenSource, Parallels, Virtual Iron, Jaluna and TenAsys.

You can find more information about Intel® Virtualization Technology at: <http://developer.intel.com/technology/virtualization/index.htm>



Note

congatec does not offer virtual machine monitor (VMM) software. All VMM software support questions and queries should be directed to the VMM software vendor and not congatec technical support.

7.2.6 Thermal Management

ACPI is responsible for allowing the operating system to play an important part in the system’s thermal management. This results in the operating system having the ability to take control of the operating environment by implementing cooling decisions according to the demands put on the CPU by the application.

The conga-TC97 supports Critical Trip Point. This cooling policy ensures that the operating system shuts down properly if the temperature in the thermal zone reaches a critical point, in order to prevent damage to the system as a result of high temperatures. Use the “critical trip point” setup node in the BIOS setup program to determine the temperature threshold that the operating system will use to shut down the system.



Note

The end user must determine the cooling preferences for the system by using the setup nodes in the BIOS setup program to establish the appropriate trip points.

7.3 ACPI Suspend Modes and Resume Events

conga-TC97 supports S3 (STR= Suspend to RAM). For more information about S3 wake events, see section 10.4.5 "ACPI Configuration Submenu".

S4 (Suspend to Disk) is not supported by the BIOS (S4_BIOS) but it is supported by the following operating systems (S4_OS= Hibernate):

- Windows 8, Windows 7, Windows Vista, Linux.

Table 4 **Wake Events**

This table lists the "Wake Events" that resume the system from S3 unless otherwise stated in the "Conditions/Remarks" column:

Wake Event	Conditions/Remarks
Power Button	Wakes unconditionally from S3-S5.
Onboard LAN Event	Device driver must be configured for Wake On LAN support.
SMBALERT#	Wakes unconditionally from S3-S5.
PCI Express WAKE#	Wakes unconditionally from S3-S5.
WAKE#	Wakes unconditionally from S3.
PME#	Activate the wake up capabilities of a PCI device using Windows Device Manager configuration options for this device OR set Resume On PME# to Enabled in the Power setup menu.
USB Mouse/Keyboard Event	When Standby mode is set to S3, USB hardware must be powered by standby power source. Set USB Device Wakeup from S3/S4 to ENABLED in the ACPI setup menu (if setup node is available in BIOS setup program). In Device Manager look for the keyboard/mouse devices. Go to the Power Management tab and check 'Allow this device to bring the computer out of standby'.
RTC Alarm	Activate and configure Resume On RTC Alarm in the Power setup menu. Only available in S5.
Watchdog Power Button Event	Wakes unconditionally from S3-S5.

7.4 Low Voltage Memory (DDR3L)

The Intel Broadwell ULT processor featured on the conga-TC97 supports low voltage system memory interface. The memory interface I/O voltage is 1.35V and supports non-ECC, unbuffered DDR3L SO-DIMMs. With this low voltage system memory interface on the processor, the conga-TC97 offers a system optimized for lowest possible power consumption. The reduction in power consumption due to lower voltage subsequently reduces the heat generated.



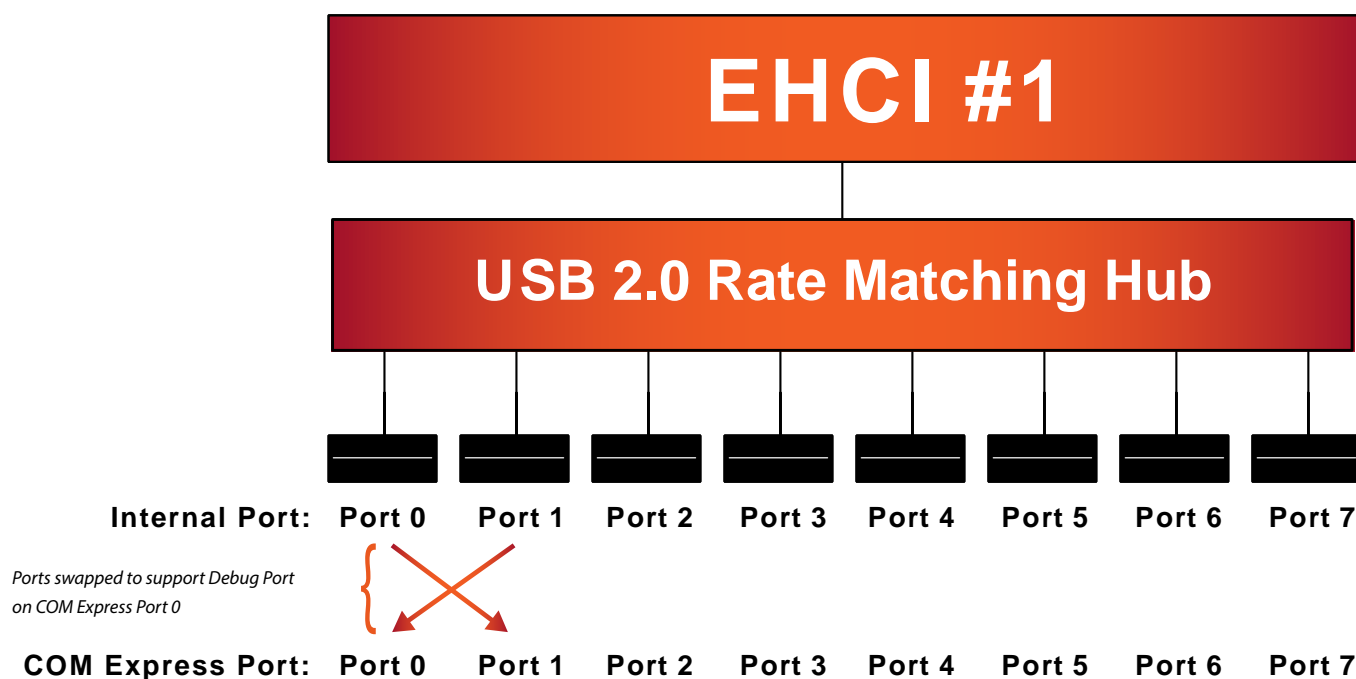
Caution

The usage of DDR3@1.5V SO-DIMM modules may affect the stability or boot-up of the conga-TC97. Therefore use only non-ECC, unbuffered DDR3L SO-DIMM memory modules up to 1600 MT/s on the conga-TC97.

7.5 USB 2.0 EHCI Host Controller Support

The 8 available USB ports are provided by a USB 2.0 Rate Matching Hub (RMH) integrated within the Intel® 9 Series PCH-LP. The EHCI controller is connected to the hub as shown below. The Hub convert low and full-speed traffic into high-speed traffic. When the RMHs are enabled, they will appear to software like an external hub is connected to Port 0 of the EHCI controller. In addition, port 1 of the RMH is multiplexed with Port 1 of the EHCI controller and is able to bypass the RMH for use as the Debug Port. The hub operates like any USB 2.0 Discrete Hub and will consume one tier of hubs allowed by the USB 2.0 Spec. A maximum of four additional non-root hubs can be supported on any of the PCH USB Ports. The RMH will report the following Vendor ID = 8087h and Product ID = 8000h.

Routing Diagram



8 Signal Descriptions and Pinout Tables

The following section describes the signals found on COM Express™ Type VI connectors used for congatec AG modules. The pinout of the modules complies with COM Express Type 6 Rev. 2.1.

Table 3 describes the terminology used in this section for the Signal Description tables. The PU/PD column indicates if a COM Express™ module pull-up or pull-down resistor has been used. If the field entry area in this column for the signal is empty, then no pull-up or pull-down resistor has been implemented by congatec.

The “#” symbol at the end of the signal name indicates that the active or asserted state occurs when the signal is at a low voltage level. When “#” is not present, the signal is asserted when at a high voltage level.



Note

The Signal Description tables do not list internal pull-ups or pull-downs implemented by the chip vendors, only pull-ups or pull-downs implemented by congatec are listed. For information about the internal pull-ups or pull-downs implemented by the chip vendors, refer to the respective chip's datasheet.

Table 5 Signal Tables Terminology Descriptions

Term	Description
PU	congatec implemented pull-up resistor
PD	congatec implemented pull-down resistor
I/O 3.3V	Bi-directional signal 3.3V tolerant
I/O 5V	Bi-directional signal 5V tolerant
I 3.3V	Input 3.3V tolerant
I 5V	Input 5V tolerant
I/O 3.3VSB	Input 3.3V tolerant active in standby state
O 3.3V	Output 3.3V signal level
O 5V	Output 5V signal level
OD	Open drain output
P	Power Input/Output
DDC	Display Data Channel
PCIE	In compliance with PCI Express Base Specification, Revision 2.0
PEG	PCI Express Graphics
SATA	In compliance with Serial ATA specification Revision 2.6 and 3.0.
REF	Reference voltage output. May be sourced from a module power plane.
PDS	Pull-down strap. A module output pin that is either tied to GND or is not connected. Used to signal module capabilities (pinout type) to the Carrier Board.

8.1 A-B Connector Signal Descriptions

Table 6 Intel® High Definition Audio Link Signals Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
AC/HDA_RST#	A30	Intel® High Definition Audio Reset: This signal is the master hardware reset to external codec(s).	O 3.3VSB		AC'97 codecs are not supported.
AC/HDA_SYNC	A29	Intel® High Definition Audio Sync: This signal is a 48 kHz fixed rate sample sync to the codec(s). It is also used to encode the stream number.	O 3.3VSB		AC'97 codecs are not supported.
AC/HDA_BITCLK	A32	Intel® High Definition Audio Bit Clock Output: This signal is a 24.000MHz serial data clock generated by the Intel® High Definition Audio controller.	O 3.3VSB		AC'97 codecs are not supported.
AC/HDA_SDOUT	A33	Intel® High Definition Audio Serial Data Out: This signal is the serial TDM data output to the codec(s). This serial output is double-pumped for a bit rate of 48 Mb/s for Intel® High Definition Audio.	O 3.3VSB	PU 1K 3.3VSB	AC'97 codecs are not supported. AC/HDA_SDOUT is a boot strap signal (see note below)
AC/HDA_SDIN[2:0]	B28-B30	Intel® High Definition Audio Serial Data In [0]: These signals are serial TDM data inputs from the three codecs. The serial input is single-pumped for a bit rate of 24 Mb/s for Intel® High Definition Audio.	I 3.3VSB		AC'97 codecs are not supported.



Note

Some signals have special functionality during the reset process. They may bootstrap some basic important functions of the module.

For more information refer to section 8.5 of this user's guide.

Table 7 Gigabit Ethernet Signal Descriptions

Gigabit Ethernet	Pin #	Description	I/O	PU/PD	Comment																				
GBE0_MDI0+ GBE0_MDI0- GBE0_MDI1+ GBE0_MDI1- GBE0_MDI2+ GBE0_MDI2- GBE0_MDI3+ GBE0_MDI3-	A13 A12 A10 A9 A7 A6 A3 A2	<div>Gigabit Ethernet Controller 0: Media Dependent Interface Differential Pairs 0, 1, 2, 3. The MDI can operate in 1000, 100, and 10Mbit/sec modes. Some pairs are unused in some modes according to the following:</div> <table><tr><td></td><td>1000</td><td>100</td><td>10</td></tr><tr><td>MDI[0]+/-</td><td>B1_DA+/-</td><td>TX+/-</td><td>TX+/-</td></tr><tr><td>MDI[1]+/-</td><td>B1_DB+/-</td><td>RX+/-</td><td>RX+/-</td></tr><tr><td>MDI[2]+/-</td><td>B1_DC+/-</td><td></td><td></td></tr><tr><td>MDI[3]+/-</td><td>B1_DD+/-</td><td></td><td></td></tr></table>		1000	100	10	MDI[0]+/-	B1_DA+/-	TX+/-	TX+/-	MDI[1]+/-	B1_DB+/-	RX+/-	RX+/-	MDI[2]+/-	B1_DC+/-			MDI[3]+/-	B1_DD+/-			I/O Analog		Twisted pair signals for external transformer.
	1000	100	10																						
MDI[0]+/-	B1_DA+/-	TX+/-	TX+/-																						
MDI[1]+/-	B1_DB+/-	RX+/-	RX+/-																						
MDI[2]+/-	B1_DC+/-																								
MDI[3]+/-	B1_DD+/-																								
GBE0_ACT#	B2	Gigabit Ethernet Controller 0 activity indicator, active low.	O 3.3VSB																						
GBE0_LINK#	A8	Gigabit Ethernet Controller 0 link indicator, active low.	O 3.3VSB																						
GBE0_LINK100#	A4	Gigabit Ethernet Controller 0 100Mbit/sec link indicator, active low.	O 3.3VSB																						
GBE0_LINK1000#	A5	Gigabit Ethernet Controller 0 1000Mbit/sec link indicator, active low.	O 3.3VSB																						

Gigabit Ethernet	Pin #	Description	I/O	PU/PD	Comment
GBE0_CTREF	A14	Reference voltage for Carrier Board Ethernet channel 0 magnetics center tap. The reference voltage is determined by the requirements of the module PHY and may be as low as 0V and as high as 3.3V. The reference voltage output shall be current limited on the module. In the case in which the reference is shorted to ground, the current shall be limited to 250mA or less.			Not connected



The GBE0_LINK# output is only active during a 100Mbit or 1Gbit connection, it is not active during a 10Mbit connection. This is a limitation of Ethernet controller since it only has 3 LED outputs, ACT#, LINK100# and LINK1000#. The GBE0_LINK# signal is a logic AND of the GBE0_LINK100# and GBE0_LINK1000# signals on the conga-TC97 module.

Table 8 Serial ATA Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
SATA0_RX+ SATA0_RX-	A19 A20	Serial ATA channel 0, Receive Input differential pair.	I SATA		Supports Serial ATA specification, Revision 3.0
SATA0_TX+ SATA0_TX-	A16 A17	Serial ATA channel 0, Transmit Output differential pair.	O SATA		Supports Serial ATA specification, Revision 3.0
SATA1_RX+ SATA1_RX-	B19 B20	Serial ATA channel 1, Receive Input differential pair.	I SATA		Supports Serial ATA specification, Revision 3.0
SATA1_TX+ SATA1_TX-	B16 B17	Serial ATA channel 1, Transmit Output differential pair.	O SATA		Supports Serial ATA specification, Revision 3.0
SATA2_RX+ SATA2_RX-	A25 A26	Serial ATA channel 2, Receive Input differential pair.	I SATA		Supports Serial ATA specification, Revision 3.0
SATA2_TX+ SATA2_TX-	A22 A23	Serial ATA channel 2, Transmit Output differential pair.	O SATA		Supports Serial ATA specification, Revision 3.0
SATA3_RX+ SATA3_RX-	B25 B26	Serial ATA channel 3, Receive Input differential pair.	I SATA		Supports Serial ATA specification, Revision 3.0
SATA3_TX+ SATA3_TX-	B22 B23	Serial ATA channel 3, Transmit Output differential pair.	O SATA		Supports Serial ATA specification, Revision 3.0
(S)ATA_ACT#	A28	ATA (parallel and serial) or SAS activity indicator, active low.	I/O 3.3v		

Table 9 PCI Express Signal Descriptions (general purpose)

Signal	Pin #	Description	I/O	PU/PD	Comment
PCIE_RX0+ PCIE_RX0-	B68 B69	PCI Express channel 0, Receive Input differential pair.	I PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_TX0+ PCIE_TX0-	A68 A69	PCI Express channel 0, Transmit Output differential pair.	O PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_RX1+ PCIE_RX1-	B64 B65	PCI Express channel 1, Receive Input differential pair.	I PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_TX1+ PCIE_TX1-	A64 A65	PCI Express channel 1, Transmit Output differential pair.	O PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_RX2+ PCIE_RX2-	B61 B62	PCI Express channel 2, Receive Input differential pair.	I PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_TX2+ PCIE_TX2-	A61 A62	PCI Express channel 2, Transmit Output differential pair.	O PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_RX3+ PCIE_RX3-	B58 B59	PCI Express channel 3, Receive Input differential pair.	I PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_TX3+ PCIE_TX3-	A58 A59	PCI Express channel 3, Transmit Output differential pair.	O PCIE		Supports PCI Express Base Specification, Revision 2.0
PCIE_RX4+ PCIE_RX4-	B55 B56	PCI Express channel 4, Receive Input differential pair.	I PCIE		Not supported
PCIE_TX4+ PCIE_TX4-	A55 A56	PCI Express channel 4, Transmit Output differential pair.	O PCIE		Not supported
PCIE_RX5+ PCIE_RX5-	B52 B53	PCI Express channel 5, Receive Input differential pair.	I PCIE		Not supported
PCIE_TX5+ PCIE_TX5-	A52 A53	PCI Express channel 5, Transmit Output differential pair.	O PCIE		Not supported
PCIE_CLK_REF+ PCIE_CLK_REF-	A88 A89	PCI Express Reference Clock output for all PCI Express and PCI Express Graphics Lanes.	O PCIE		A PCI Express Gen2/3 compliant clock buffer chip must be used on the carrier board if the design involves more than one PCI Express device.

Table 10 ExpressCard Support Pins Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
EXCD0_CPPE# EXCD1_CPPE#	A49 B48	ExpressCard capable card request.	I 3.3V	PU 10k 3.3V	
EXCD0_PERST# EXCD1_PERST#	A48 B47	ExpressCard Reset	O 3.3V	PU 10k 3.3V	

Table 11 LPC Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
LPC_AD[0:3]	B4-B7	LPC multiplexed address, command and data bus	I/O 3.3V		
LPC_FRAME#	B3	LPC frame indicates the start of an LPC cycle	O 3.3V		
LPC_DRQ[0:1]#	B8-B9	LPC serial DMA request	I 3.3V	PU 10k 3.3V	
LPC_SERIRQ	A50	LPC serial interrupt	I/O OD 3.3V	PU 10k 3.3V	
LPC_CLK	B10	LPC clock output - 24 MHz nominal	O 3.3V		

Table 12 USB Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
USB0+	B46	USB Port 0, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB0-	B45	USB Port 0, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB1+	A46	USB Port 1, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB1-	A45	USB Port 1, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB2+	A43	USB Port 2, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB2-	A42	USB Port 2, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB3+	B43	USB Port 3, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB3-	B42	USB Port 3, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB4+	A40	USB Port 4, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB4-	A39	USB Port 4, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB5+	B40	USB Port 5, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB5-	B39	USB Port 5, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB6+	A37	USB Port 6, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB6-	A36	USB Port 6, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB7+	B37	USB Port 7, data + or D+	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB7-	B36	USB Port 7, data - or D-	I/O		USB 2.0 compliant. Backwards compatible to USB 1.1
USB_0_1_OC#	B44	USB over-current sense, USB ports 0 and 1. A pull-up for this line shall be present on the module. An open drain driver from a USB current monitor on the carrier board may drive this line low.	I 3.3VSB	PU 10k 3.3VSB	Do not pull this line high on the carrier board.
USB_2_3_OC#	A44	USB over-current sense, USB ports 2 and 3. A pull-up for this line shall be present on the module. An open drain driver from a USB current monitor on the carrier board may drive this line low. .	I 3.3VSB	PU 10k 3.3VSB	Do not pull this line high on the carrier board.
USB_4_5_OC#	B38	USB over-current sense, USB ports 4 and 5. A pull-up for this line shall be present on the module. An open drain driver from a USB current monitor on the carrier board may drive this line low.	I 3.3VSB	PU 10k 3.3VSB	Do not pull this line high on the carrier board.
USB_6_7_OC#	A38	USB over-current sense, USB ports 6 and 7. A pull-up for this line shall be present on the module. An open drain driver from a USB current monitor on the carrier board may drive this line low.	I 3.3VSB	PU 10k 3.3VSB	Do not pull this line high on the carrier board.

Table 13 CRT Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
VGA_RED	B89	Red for monitor. Analog DAC output, designed to drive a 37.5-Ohm equivalent load.	O Analog	PD 150R	Optional only on rev. C.x and later
VGA_GRN	B91	Green for monitor. Analog DAC output, designed to drive a 37.5-Ohm equivalent load.	O Analog	PD 150R	Optional only on rev. C.x and later
VGA_BLU	B92	Blue for monitor. Analog DAC output, designed to drive a 37.5-Ohm equivalent load.	O Analog	PD 150R	Optional only on rev. C.x and later
VGA_HSYNC	B93	Horizontal sync output to VGA monitor	O 3.3V		Optional only on rev. C.x and later
VGA_VSYNC	B94	Vertical sync output to VGA monitor	O 3.3V		Optional only on rev. C.x and later
VGA_I2C_CK	B95	DDC clock line (I ² C port dedicated to identify VGA monitor capabilities)	I/O OD 5V	PU 1k2 3.3V	Optional only on rev. C.x and later
VGA_I2C_DAT	B96	DDC data line.	I/O OD 5V	PU 1k2 3.3V	Optional only on rev. C.x and later

Table 14 LVDS Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
LVDS_A0+	A71	LVDS Channel A differential pairs	O LVDS		
LVDS_A0-	A72				
LVDS_A1+	A73				
LVDS_A1-	A74				
LVDS_A2+	A75				
LVDS_A2-	A76				
LVDS_A3+	A78				
LVDS_A3-	A79				
LVDS_A_CK+	A81	LVDS Channel A differential clock	O LVDS		
LVDS_A_CK-	A82				
LVDS_B0+	B71	LVDS Channel B differential pairs	O LVDS		
LVDS_B0-	B72				
LVDS_B1+	B73				
LVDS_B1-	B74				
LVDS_B2+	B75				
LVDS_B2-	B76				
LVDS_B3+	B77				
LVDS_B3-	B78				
LVDS_B_CK+	B81	LVDS Channel B differential clock	O LVDS		
LVDS_B_CK-	B82				
LVDS_VDD_EN	A77	LVDS panel power enable	O 3.3V	PD 10k	
LVDS_BKLT_EN	B79	LVDS panel backlight enable	O 3.3V	PD 10k	
LVDS_BKLT_CTRL	B83	LVDS panel backlight brightness control	O 3.3V		
LVDS_I2C_CK	A83	DDC lines used for flat panel detection and control.	O 3.3V	PU 2k2 3.3V	
LVDS_I2C_DAT	A84	DDC lines used for flat panel detection and control.	I/O 3.3V	PU 2k2 3.3V	.

Table 15 Embedded DisplayPort Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
eDP_TX3+ eDP_TX3- eDP_TX2+ eDP_TX2- eDP_TX1+ eDP_TX1- eDP_TX0+ eDP_TX0-	A81 A82 A71 A72 A73 A74 A75 A76	eDP differential pairs.	AC coupled off module.		
eDP_VDD_EN	A77	eDP power enable.	O 3.3V	PD 10k	
eDP_BKLT_EN	B79	eDP backlight enable.	O 3.3V	PD 10k	
eDP_BKLT_CTRL	B83	eDP backlight brightness control.	O 3.3V		
eDP_AUX+	A83	eDP AUX+.	AC coupled off module.		
eDP_AUX-	A84	eDP AUX-.	AC coupled off module.		
eDP_HPD	A87	Detection of Hot Plug / Unplug and notification of the link layer.	I 3.3V		

Table 16 SPI BIOS Flash Interface Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
SPI_CS#	B97	Chip select for Carrier Board SPI BIOS Flash.	O 3.3VSB		Carrier shall pull to SPI_POWER when external SPI provided but not used.
SPI_MISO	A92	Data in to module from carrier board SPI BIOS flash.	I 3.3VSB		
SPI_MOSI	A95	Data out from module to carrier board SPI BIOS flash.	O 3.3VSB		
SPI_CLK	A94	Clock from module to carrier board SPI BIOS flash.	O 3.3VSB		
SPI_POWER	A91	Power source for carrier board SPI BIOS flash. SPI_POWER shall be used to power SPI BIOS flash on the carrier only.	+ 3.3VSB		
BIOS_DIS0#	A34	Selection strap to determine the BIOS boot device.	I 3.3VSB	PU 10K 3.3VSB	Carrier shall be left as no-connect.
BIOS_DIS1#	B88	Selection strap to determine the BIOS boot device.	I 3.3VSB	PU 10K 3.3VSB	Carrier shall be left as no-connect

Table 17 Miscellaneous Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
I2C_CLK	B33	General purpose I ² C port clock output/input	I/O 3.3V	PU 2K2 3.3VSB	
I2C_DAT	B34	General purpose I ² C port data I/O line	I/O 3.3V	PU 2K2 3.3VSB	
SPKR	B32	Output for audio enunciator, the “speaker” in PC-AT systems	O 3.3V		SPEAKER is a boot strap signal (see note below)
WDT	B27	Output indicating that a watchdog time-out event has occurred.	O 3.3V	PD 10K	
FAN_PWNOUT	B101	Fan speed control. Uses the Pulse Width Modulation (PWM) technique to control the fan's RPM.	O OD 3.3V	PU 10K 3.3V	
FAN_TACHIN	B102	Fan tachometer input.	I OD	PU 10K 3.3V	Requires a fan with a two pulse output.
TPM_PP	A96	Physical Presence pin of Trusted Platform Module (TPM). Active high. TPM chip has an internal pull-down. This signal is used to indicate Physical Presence to the TPM.	I 3.3V		Trusted Platform Module chip is optional.



Note
Some signals have special functionality during the reset process. They may bootstrap some basic important functions of the module. For more information refer to section 8.5 of this user's guide.

Table 18 General Purpose I/O Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
GPO0	A93	General purpose output pins. Shared with SD_CLK. Output from COM Express, input to SD	O 3.3V		SDIO interface is not supported on the conga-TC97
GPO1	B54	General purpose output pins. Shared with SD_CMD. Output from COM Express, input to SD	O 3.3V		SDIO interface is not supported on the conga-TC97
GPO2	B57	General purpose output pins. Shared with SD_WP. Output from COM Express, input to SD	O 3.3V		SDIO interface is not supported on the conga-TC97
GPO3	B63	General purpose output pins. Shared with SD_CD. Output from COM Express, input to SD	O 3.3V		SDIO interface is not supported on the conga-TC97
GPI0	A54	General purpose input pins. Pulled high internally on the module. Shared with SD_DATA0. Bidirectional signal	I 3.3V	PU 10K 3.3V	SDIO interface is not supported on the conga-TC97
GPI1	A63	General purpose input pins. Pulled high internally on the module. Shared with SD_DATA1. Bidirectional signal	I 3.3V	PU 10K 3.3V	SDIO interface is not supported on the conga-TC97
GPI2	A67	General purpose input pins. Pulled high internally on the module. Shared with SD_DATA2. Bidirectional signal	I 3.3V	PU 10K 3.3V	SDIO interface is not supported on the conga-TC97
GPI3	A85	General purpose input pins. Pulled high internally on the module. Shared with SD_DATA3. Bidirectional signal.	I 3.3V	PU 10K 3.3V	SDIO interface is not supported on the conga-TC97

Table 19 Power and System Management Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
PWRBTN#	B12	Power button to bring system out of S5 (soft off), active on falling edge.	I 3.3VSB	PU 10k 3.3VSB	
SYS_RESET#	B49	Reset button input. Active low input. Edge triggered. System will not be held in hardware reset while this input is kept low.	I 3.3VSB	PU 10k 3.3VSB	
CB_RESET#	B50	Reset output from module to Carrier Board. Active low. Issued by module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the module software.	O 3.3V	PD 100k	
PWR_OK	B24	Power OK from main power supply. A high value indicates that the power is good.	I 3.3V		Set by resistor divider to accept 3.3V.
SUS_STAT#	B18	Indicates imminent suspend operation; used to notify LPC devices.	O 3.3VSB	PU 10k 3.3VSB	
SUS_S3#	A15	Indicates system is in Suspend to RAM state. Active-low output. An inverted copy of SUS_S3# on the carrier board (also known as "PS_ON") may be used to enable the non-standby power on a typical ATX power supply.	O 3.3VSB		
SUS_S4#	A18	Indicates system is in Suspend to Disk state. Active low output.	O 3.3VSB		Not supported
SUS_S5#	A24	Indicates system is in Soft Off state.	O 3.3VSB		
WAKE0#	B66	PCI Express wake up signal.	I 3.3VSB	PU 1k 3.3VSB	
WAKE1#	B67	General purpose wake up signal. May be used to implement wake-up on PS/2 keyboard or mouse activity.	I 3.3VSB	PU 10k 3.3VSB	
BATLOW#	A27	Battery low input. This signal may be driven low by external circuitry to signal that the system battery is low, or may be used to signal some other external power-management event.	I 3.3VSB	PU 10k 3.3VSB	
THRM#	B35	Input from off-module temp sensor indicating an over-temp situation.	I 3.3V	PU 10k 3.3V	
THERMTRIP#	A35	Active low output indicating that the CPU has entered thermal shutdown.	O 3.3V	PU 10k 3.3V	
SMB_CK	B13	System Management Bus bidirectional clock line.	I/O 3.3VSB	PU 2k2 3.3VSB	
SMB_DAT#	B14	System Management Bus bidirectional data line.	I/O OD 3.3VSB	PU 2k2 3.3VSB	
SMB_ALERT#	B15	System Management Bus Alert – active low input can be used to generate an SMI# (System Management Interrupt) or to wake the system.	I 3.3VSB	PU 10k 3.3VSB	
LID#	A103	Lid button. Used by the ACPI operating system for a LID switch.	I OD 3.3V	PU 10k 3.3VSB	
SLEEP#	B103	Sleep button. Used by the ACPI operating system to bring the system to sleep state or to wake it up again.	I OD 3.3V	PU 10k 3.3VSB	

Table 20 General Purpose Serial Interface Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
SER0_TX	A98	General purpose serial port transmitter	O 3.3V		
SER1_TX	A101	General purpose serial port transmitter	O 3.3V		
SER0_RX	A99	General purpose serial port receiver	I 3.3V	PU 50k 3.3V	
SER1_RX	A102	General purpose serial port receiver	I 3.3V	PU 50k 3.3V	

Table 21 Power and GND Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
VCC_12V	A104-A109 B104-B109	Primary power input: +12V nominal. All available VCC_12V pins on the connector(s) shall be used.	P		
VCC_5V_SBY	B84-B87	Standby power input: +5.0V nominal. If VCC5_SBY is used, all available VCC_5V_SBY pins on the connector(s) shall be used. Only used for standby and suspend functions. May be left unconnected if these functions are not used in the system design.	P		
VCC_RTC	A47	Real-time clock circuit-power input. Nominally +3.0V.	P		
GND	A1, A11, A21, A31, A41, A51, A57, A60, A66, A70, A80, A90, A100, A110, B1, B11, B21, B31, B41, B51, B60, B70, B80, B90, B100, B110	Ground - DC power and signal and AC signal return path. All available GND connector pins shall be used and tied to Carrier Board GND plane.	P		

8.2 A-B Connector Pinout

Table 22 Connector A-B Pinout

Pin	Row A	Pin	Row B	Pin	Row A	Pin	Row B
A1	GND (FIXED)	B1	GND (FIXED)	A56	PCIE_TX4- (*)	B56	PCIE_RX4- (*)
A2	GBE0_MDI3-	B2	GBE0_ACT#	A57	GND	B57	GPO2
A3	GBE0_MDI3+	B3	LPC_FRAME#	A58	PCIE_TX3+	B58	PCIE_RX3+
A4	GBE0_LINK100#	B4	LPC_AD0	A59	PCIE_TX3-	B59	PCIE_RX3-
A5	GBE0_LINK1000#	B5	LPC_AD1	A60	GND (FIXED)	B60	GND (FIXED)
A6	GBE0_MDI2-	B6	LPC_AD2	A61	PCIE_TX2+	B61	PCIE_RX2+
A7	GBE0_MDI2+	B7	LPC_AD3	A62	PCIE_TX2-	B62	PCIE_RX2-
A8	GBE0_LINK#	B8	LPC_DRQ0#	A63	GPI1	B63	GPO3
A9	GBE0_MDI1-	B9	LPC_DRQ1#	A64	PCIE_TX1+	B64	PCIE_RX1+
A10	GBE0_MDI1+	B10	LPC_CLK	A65	PCIE_TX1-	B65	PCIE_RX1-
A11	GND (FIXED)	B11	GND (FIXED)	A66	GND	B66	WAKE0#
A12	GBE0_MDI0-	B12	PWRBTN#	A67	GPI2	B67	WAKE1#
A13	GBE0_MDI0+	B13	SMB_CK	A68	PCIE_TX0+	B68	PCIE_RX0+
A14	GBE0_CTREF (*)	B14	SMB_DAT	A69	PCIE_TX0-	B69	PCIE_RX0-
A15	SUS_S3#	B15	SMB_ALERT#	A70	GND (FIXED)	B70	GND (FIXED)
A16	SATA0_TX+	B16	SATA1_TX+	A71	eDP_TX2+/LVDS_A0+	B71	LVDS_B0+
A17	SATA0_TX-	B17	SATA1_TX-	A72	eDP_TX2-/LVDS_A0-	B72	LVDS_B0-
A18	SUS_S4#	B18	SUS_STAT#	A73	eDP_TX1+/LVDS_A1+	B73	LVDS_B1+
A19	SATA0_RX+	B19	SATA1_RX+	A74	eDP_TX1-/LVDS_A1-	B74	LVDS_B1-
A20	SATA0_RX-	B20	SATA1_RX-	A75	eDP_TX0+/LVDS_A2+	B75	LVDS_B2+
A21	GND (FIXED)	B21	GND (FIXED)	A76	eDP_TX0-/LVDS_A2-	B76	LVDS_B2-
A22	SATA2_TX+	B22	SATA3_TX+	A77	eDP/LVDS_VDD_EN	B77	LVDS_B3+
A23	SATA2_TX-	B23	SATA3_TX-	A78	LVDS_A3+	B78	LVDS_B3-
A24	SUS_S5#	B24	PWR_OK	A79	LVDS_A3-	B79	eDP/LVDS_BKLT_EN
A25	SATA2_RX+	B25	SATA3_RX+	A80	GND (FIXED)	B80	GND (FIXED)
A26	SATA2_RX-	B26	SATA3_RX-	A81	eDP_TX3+/LVDS_A_CK+	B81	LVDS_B_CK+
A27	BATLOW#	B27	WDT	A82	eDP_TX3-/LVDS_A_CK-	B82	LVDS_B_CK-
A28	(S)ATA_ACT#	B28	AC/HDA_SDIN2	A83	eDP_AUX+/LVDS_I2C_CK	B83	eDP/LVDS_BKLT_CTRL
A29	AC/HDA_SYNC	B29	AC/HDA_SDIN1	A84	eDP_AUX-/LVDS_I2C_DAT	B84	VCC_5V_SBY
A30	AC/HDA_RST#	B30	AC/HDA_SDIN0	A85	GPI3	B85	VCC_5V_SBY
A31	GND (FIXED)	B31	GND (FIXED)	A86	RSVD	B86	VCC_5V_SBY
A32	AC/HDA_BITCLK	B32	SPKR	A87	eDP_HPD	B87	VCC_5V_SBY
A33	AC/HDA_SDOUT	B33	I2C_CK	A88	PCIE0_CK_REF+	B88	BIOS_DIS1#
A34	BIOS_DIS0#	B34	I2C_DAT	A89	PCIE0_CK_REF-	B89	VGA_RED (*)
A35	THRMTRIP#	B35	THRM#	A90	GND (FIXED)	B90	GND (FIXED)
A36	USB6-	B36	USB7-	A91	SPI_POWER	B91	VGA_GRN (*)

Pin	Row A	Pin	Row B	Pin	Row A	Pin	Row B
A37	USB6+	B37	USB7+	A92	SPI_MISO	B92	VGA_BLU (*)
A38	USB_6_7_OC#	B38	USB_4_5_OC#	A93	GPO0	B93	VGA_HSYNC (*)
A39	USB4-	B39	USB5-	A94	SPI_CLK	B94	VGA_VSYNC (*)
A40	USB4+	B40	USB5+	A95	SPI_MOSI	B95	VGA_I2C_CK (*)
A41	GND (FIXED)	B41	GND (FIXED)	A96	TPM_PP	B96	VGA_I2C_DAT (*)
A42	USB2-	B42	USB3-	A97	TYPE10#	B97	SPI_CS#
A43	USB2+	B43	USB3+	A98	SER0_TX	B98	RSVD
A44	USB_2_3_OC#	B44	USB_0_1_OC#	A99	SER0_RX	B99	RSVD
A45	USB0-	B45	USB1-	A100	GND (FIXED)	B100	GND (FIXED)
A46	USB0+	B46	USB1+	A101	SER1_TX	B101	FAN_PWMOUT
A47	VCC_RTC	B47	EXCD1_PERST#	A102	SER1_RX	B102	FAN_TACHIN
A48	EXCD0_PERST#	B48	EXCD1_CPPE#	A103	LID#	B103	SLEEP#
A49	EXCD0_CPPE#	B49	SYS_RESET#	A104	VCC_12V	B104	VCC_12V
A50	LPC_SERIRQ	B50	CB_RESET#	A105	VCC_12V	B105	VCC_12V
A51	GND (FIXED)	B51	GND (FIXED)	A106	VCC_12V	B106	VCC_12V
A52	PCIE_TX5+ (*)	B52	PCIE_RX5+ (*)	A107	VCC_12V	B107	VCC_12V
A53	PCIE_TX5- (*)	B53	PCIE_RX5- (*)	A108	VCC_12V	B108	VCC_12V
A54	GPIO	B54	GPO1	A109	VCC_12V	B109	VCC_12V
A55	PCIE_TX4+ (*)	B55	PCIE_RX4+ (*)	A110	GND (FIXED)	B110	GND (FIXED)



Note

The signals marked with asterisk symbol (*) are not supported on the conga TC97.

8.3 C-D Connector Signal Descriptions

Table 23 PCI Express Signal Descriptions (general purpose)

Signal	Pin #	Description	I/O	PU/PD	Comment
PCIE_RX6+ PCIE_RX6-	C19 C20	PCI Express channel 6, Receive Input differential pair.	I PCIE		Not supported
PCIE_TX6+ PCIE_TX6-	D19 D20	PCI Express channel 6, Transmit Output differential pair.	O PCIE		Not supported
PCIE_RX7+ PCIE_RX7-	C22 C23	PCI Express channel 7, Receive Input differential pair.	I PCIE		Not supported
PCIE_TX7+ PCIE_TX7-	D22 D23	PCI Express channel 7, Transmit Output differential pair.	O PCIE		Not supported

Table 24 USB 3.0 Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
USB_SSRX0+	C4	Additional receive signal differential pairs for the Superspeed USB data path	I		
USB_SSRX0-	C3		I		
USB_SSTX0+	D4	Additional transmit signal differential pairs for the Superspeed USB data path	O		
USB_SSTX0-	D3		O		
USB_SSRX1+	C7	Additional receive signal differential pairs for the Superspeed USB data path	I		
USB_SSRX1-	C6		I		
USB_SSTX1+	D7	Additional transmit signal differential pairs for the Superspeed USB data path	O		
USB_SSTX1-	D6		O		
USB_SSRX2+	C10	Additional receive signal differential pairs for the Superspeed USB data path	I		Not supported.
USB_SSRX2-	C9		I		Not supported.
USB_SSTX2+	D10	Additional transmit signal differential pairs for the Superspeed USB data path	O		Not supported.
USB_SSTX2-	D9		O		Not supported.
USB_SSRX3+	C13	Additional receive signal differential pairs for the Superspeed USB data path	I		Not supported.
USB_SSRX3-	C12		I		Not supported.
USB_SSTX3+	D13	Additional transmit signal differential pairs for the Superspeed USB data path	O		Not supported.
USB_SSTX3-	D12		O		Not supported.

Table 25 PCI Express Signal Descriptions (x16 Graphics)

Signal	Pin #	Description	I/O	PU/PD	Comment
PEG_RX0+	C52	PCI Express Graphics Receive Input differential pairs. <i>Note: Can also be used as PCI Express Receive Input differential pairs 16 through 31 known as PCIE_RX[16-31] + and -.</i>	I PCIE		Not supported.
PEG_RX0-	C53				
PEG_RX1+	C55				
PEG_RX1-	C56				
PEG_RX2+	C58				
PEG_RX2-	C59				
PEG_RX3+	C61				
PEG_RX3-	C62				
PEG_RX4+	C65				
PEG_RX4-	C66				
PEG_RX5+	C68				
PEG_RX5-	C69				
PEG_RX6+	C71				
PEG_RX6-	C72				
PEG_RX7+	C74				
PEG_RX7-	C75				
PEG_RX8+	C78				
PEG_RX8-	C79				
PEG_RX9+	C81				
PEG_RX9-	C82				
PEG_RX10+	C85				
PEG_RX10-	C86				
PEG_RX11+	C88				
PEG_RX11-	C89				
PEG_RX12+	C91				
PEG_RX12-	C92				
PEG_RX13+	C94				
PEG_RX13-	C95				
PEG_RX14+	C98				
PEG_RX14-	C99				
PEG_RX15+	C101				
PEG_RX15-	C102				

Signal	Pin #	Description	I/O	PU/PD	Comment
PEG_TX0+	D52	PCI Express Graphics Transmit Output differential pairs. <i>Note: Can also be used as PCI Express Transmit Output differential pairs 16 through 31 known as PCIE_TX[16-31] + and -.</i>	O PCIE		Not supported.
PEG_TX0-	D53				
PEG_TX1+	D55				
PEG_TX1-	D56				
PEG_TX2+	D58				
PEG_TX2-	D59				
PEG_TX3+	D61				
PEG_TX3-	D62				
PEG_TX4+	D65				
PEG_TX4-	D66				
PEG_TX5+	D68				
PEG_TX5-	D69				
PEG_TX6+	D71				
PEG_TX6-	D72				
PEG_TX7+	D74				
PEG_TX7-	D75				
PEG_TX8+	D78				
PEG_TX8-	D79				
PEG_TX9+	D81				
PEG_TX9-	D82				
PEG_TX10+	D85				
PEG_TX10-	D86				
PEG_TX11+	D88				
PEG_TX11-	D89				
PEG_TX12+	D91				
PEG_TX12-	D92				
PEG_TX13+	D94				
PEG_TX13-	D95				
PEG_TX14+	D98				
PEG_TX14-	D99				
PEG_TX15+	D101				
PEG_TX15-	D102				
PEG_LANE_RV#	D54	PCI Express Graphics lane reversal input strap. Pull low on the carrier board to reverse lane order.	I	PU 10k 3.3V	Not supported.

Note

The PCI Express Graphics interface is not supported on the conga-TC97.

Table 26 DDI Signal Description

Signal	Pin #	Description	I/O	PU/PD	Comment
DDI1_PAIR0+	D26	Multiplexed with DP1_LANE0+ and TMDS1_DATA2+.	O PCIE		
DDI1_PAIR0-	D27	Multiplexed with DP1_LANE0- and TMDS1_DATA2-.			
DDI1_PAIR1+	D29	Multiplexed with DP1_LANE1+ and TMDS1_DATA1+.	O PCIE		
DDI1_PAIR1-	D30	Multiplexed with DP1_LANE1- and TMDS1_DATA1-.			
DDI1_PAIR2+	D32	Multiplexed with DP1_LANE2+ and TMDS1_DATA0+.	O PCIE		
DDI1_PAIR2-	D33	Multiplexed with DP1_LANE2- and TMDS1_DATA0-.			
DDI1_PAIR3+	D36	Multiplexed with DP1_LANE3+ and TMDS1_CLK+.	O PCIE		
DDI1_PAIR3-	D37	Multiplexed with DP1_LANE3- and TMDS1_CLK-.			
DDI1_PAIR4+	C25	Multiplexed with SDVO1_INT+.			Not supported
DDI1_PAIR4-	C26	Multiplexed with SDVO1_INT-.			
DDI1_PAIR5+	C29	Multiplexed with SDVO1_TVCLKIN+.			Not supported
DDI1_PAIR5-	C30	Multiplexed with SDVO1_TVCLKIN-.			
DDI1_PAIR6+	C15	Multiplexed with SDVO1_FLDSTALL+.			Not supported
DDI1_PAIR6-	C16	Multiplexed with SDVO1_FLDSTALL-.			
DDI1_HPD	C24	Multiplexed with DP1_HPD and HDMI1_HPD.	I 3.3V	PD 1M	
DDI1_CTRLCLK_AUX+	D15	Multiplexed with DP1_AUX+ and HDMI1_CTRLCLK. DP AUX+ function if DDI1_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLCLK if DDI1_DDC_AUX_SEL is pulled high	I/O PCIE I/O OD 3.3V	PD100k	
DDI1_CTRLDATA_AUX-	D16	Multiplexed with DP1_AUX- and HDMI1_CTRLDATA. DP AUX- function if DDI1_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLDATA if DDI1_DDC_AUX_SEL is pulled high	I/O PCIE I/O OD 3.3V	PU 100k 3.3V	DDI1_CTRLDATA_AUX- is a boot strap signal (see not below). DDI enable strap already populated.
DDI1_DDC_AUX_SEL	D34	Selects the function of DDI1_CTRLCLK_AUX+ and DDI1_CTRLDATA_AUX-. This pin shall have a 1M pull-down to logic ground on the module. If this input is floating, the AUX pair is used for the DP AUX+/- signals. If pulled-high, the AUX pair contains the CTRLCLK and CTRLDATA signals.	I 3.3V	PD 1M	
DDI2_PAIR0+	D39	Multiplexed with DP2_LANE0+ and TMDS2_DATA2+.	O PCIE		
DDI2_PAIR0-	D40	Multiplexed with DP2_LANE0- and TMDS2_DATA2-.			
DDI2_PAIR1+	D42	Multiplexed with DP2_LANE1+ and TMDS2_DATA1+.	O PCIE		
DDI2_PAIR1-	D43	Multiplexed with DP2_LANE1- and TMDS2_DATA1-.			
DDI2_PAIR2+	D46	Multiplexed with DP2_LANE2+ and TMDS2_DATA0+.	O PCIE		
DDI2_PAIR2-	D47	Multiplexed with DP2_LANE2- and TMDS2_DATA0-.			
DDI2_PAIR3+	D49	Multiplexed with DP2_LANE3+ and TMDS2_CLK+.	O PCIE		
DDI2_PAIR3-	D50	Multiplexed with DP2_LANE3- and TMDS2_CLK-.			
DDI2_HPD	D44	Multiplexed with DP2_HPD and HDMI2_HPD.	I 3.3V	PD 1M	
DDI2_CTRLCLK_AUX+	C32	Multiplexed with DP2_AUX+ and HDMI2_CTRLCLK. DP AUX+ function if DDI2_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLCLK if DDI2_DDC_AUX_SEL is pulled high	I/O PCIE I/O OD 3.3V	PD 100k	
DDI2_CTRLDATA_AUX-	C33	Multiplexed with DP2_AUX- and HDMI2_CTRLDATA. DP AUX- function if DDI2_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLDATA if DDI2_DDC_AUX_SEL is pulled high.	I/O PCIE I/O OD 3.3V	PU 100k 3.3V	DDI2_CTRLCLK_AUX- is a boot strap signal (see note below). DDI enable strap already populated.

Signal	Pin #	Description	I/O	PU/PD	Comment
DDI2_DDC_AUX_SEL	C34	Selects the function of DDI2_CTRLCLK_AUX+ and DDI2_CTRLDATA_AUX-. This pin shall have a 1M pull-down to logic ground on the module. If this input is floating, the AUX pair is used for the DP AUX+/- signals. If pulled-high, the AUX pair contains the CTRLCLK and CTRLDATA signals	I 3.3V		
DDI3_PAIR0+	C39	Multiplexed with DP3_LANE0+ and TMDS3_DATA2+.	O PCIE		Not supported
DDI3_PAIR0-	C40	Multiplexed with DP3_LANE0- and TMDS3_DATA2-.			
DDI3_PAIR1+	C42	Multiplexed with DP3_LANE1+ and TMDS3_DATA1+.	O PCIE		Not supported
DDI3_PAIR1-	C43	Multiplexed with DP3_LANE1- and TMDS3_DATA1-.			
DDI3_PAIR2+	C46	Multiplexed with DP3_LANE2+ and TMDS3_DATA0+.	O PCIE		Not supported
DDI3_PAIR2-	C47	Multiplexed with DP3_LANE2- and TMDS3_DATA0-.			
DDI3_PAIR3+	C49	Multiplexed with DP3_LANE3+ and TMDS3_CLK+.	O PCIE		Not supported
DDI3_PAIR3-	C50	Multiplexed with DP3_LANE3- and TMDS3_CLK-.			
DDI3_HPD	C44	Multiplexed with DP3_HPD and HDMI3_HPD.	I 3.3V		Not supported
DDI3_CTRLCLK_AUX+	C36	Multiplexed with DP3_AUX+ and HDMI3_CTRLCLK. DP AUX+ function if DDI3_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLCLK if DDI3_DDC_AUX_SEL is pulled high	I/O PCIE I/O OD 3.3V		Not supported
DDI3_CTRLDATA_AUX-	C37	Multiplexed with DP3_AUX- and HDMI3_CTRLDATA. DP AUX- function if DDI3_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLDATA if DDI3_DDC_AUX_SEL is pulled high.	I/O PCIE I/O OD 3.3V		Not supported
DDI3_DDC_AUX_SEL	C38	Selects the function of DDI3_CTRLCLK_AUX+ and DDI3_CTRLDATA_AUX-. This pin shall have a 1M pull-down to logic ground on the module. If this input is floating, the AUX pair is used for the DP AUX+/- signals. If pulled-high, the AUX pair contains the CTRLCLK and CTRLDATA signals	I 3.3V		Not supported



Note

Some signals have special functionality during the reset process. They may bootstrap some basic important functions of the module. For more information refer to section 8.5 of this user's guide.

The Digital Display Interface (DDI) signals are multiplexed with HDMI and DisplayPort (DP). The signals for these interfaces are routed to the DDI interface of the COM Express connector. Refer to the HDMI and DisplayPort signal description tables in this section for information about the signals routed to the DDI interface of the COM Express connector.

Table 27 HDMI Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
TMDS1_CLK + TMDS1_CLK -	D36 D37	HDMI/DVI TMDS Clock output differential pair. Multiplexed with DDI1_PAIR3+ and DDI1_PAIR3-.	O PCIE		
TMDS1_DATA0+ TMDS1_DATA0-	D32 D33	HDMI/DVI TMDS differential pair. Multiplexed with DDI1_PAIR2+ and DDI1_PAIR2-.	O PCIE		
TMDS1_DATA1+ TMDS1_DATA1-	D29 D30	HDMI/DVI TMDS differential pair. Multiplexed with DDI1_PAIR1+ and DDI1_PAIR1-..	O PCIE		
TMDS1_DATA2+ TMDS1_DATA2-	D26 D27	HDMI/DVI TMDS differential pair. Multiplexed with DDI1_PAIR0+ and DDI1_PAIR0-.	O PCIE		
HDMI1_HPD	C24	HDMI/DVI Hot-plug detect. Multiplexed with DDI1_HPD.	I PCIE	PD 1M	
HDMI1_CTRLCLK	D15	HDMI/DVI I ² C Control Clock Multiplexed with DDI1_CTRLCLK_AUX+	I/O OD 3.3V	PD 100k	
HDMI1_CTRLDATA	D16	HDMI/DVI I ² C Control Data Multiplexed with DDI1_CTRLDATA_AUX-	I/O OD 3.3V	PU 100k 3.3V	HDMI1_CTRLDATA is a boot strap signal (see note below). HDMI enable strap already populated
TMDS2_CLK + TMDS2_CLK -	D49 D50	HDMI/DVI TMDS Clock output differential pair.. Multiplexed with DDI2_PAIR3+ and DDI2_PAIR3-.	O PCIE		
TMDS2_DATA0+ TMDS2_DATA0-	D46 D47	HDMI/DVI TMDS differential pair. Multiplexed with DDI2_PAIR2+ and DDI2_PAIR2-.	O PCIE		
TMDS2_DATA1+ TMDS2_DATA1-	D42 D43	HDMI/DVI TMDS differential pair. Multiplexed with DDI2_PAIR1+ and DDI2_PAIR1-.	O PCIE		
TMDS2_DATA2+ TMDS2_DATA2-	D39 D40	HDMI/DVI TMDS differential pair. Multiplexed with DDI2_PAIR0+ and DDI2_PAIR0-..	O PCIE		
HDMI2_HPD	D44	HDMI/DVI Hot-plug detect. Multiplexed with DDI2_HPD	I PCIE	PD 1M	
HDMI2_CTRLCLK	C32	HDMI/DVI I ² C Control Clock Multiplexed with DDI2_CTRLCLK_AUX+	I/O OD 3.3V	PD 100k	
HDMI2_CTRLDATA	C33	HDMI/DVI I ² C Control Data Multiplexed with DDI2_CTRLDATA_AUX-	I/O OD 3.3V	PU 100k 3.3V	HDMI2_CTRLDATA is a boot strap signal (see note below). HDMI enable strap is already populated.
TMDS3_CLK + TMDS3_CLK -	C49 C50	HDMI/DVI TMDS Clock output differential pair.. Multiplexed with DDI3_PAIR3+ and DDI3_PAIR3-.	O PCIE		Not supported
TMDS3_DATA0+ TMDS3_DATA0-	C46 C47	HDMI/DVI TMDS differential pair. Multiplexed with DDI3_PAIR2+ and DDI3_PAIR2-.	O PCIE		Not supported
TMDS3_DATA1+ TMDS3_DATA1-	C42 C43	HDMI/DVI TMDS differential pair. Multiplexed with DDI3_PAIR1+ and DDI3_PAIR1-..	O PCIE		Not supported
TMDS3_DATA2+ TMDS3_DATA2-	C39 C40	HDMI/DVI TMDS differential pair. Multiplexed with DDI3_PAIR0+ and DDI3_PAIR0-.	O PCIE		Not supported
HDMI3_HPD	C44	HDMI/DVI Hot-plug detect. Multiplexed with DDI3_HPD.	I PCIE		Not supported
HDMI3_CTRLCLK	C36	HDMI/DVI I ² C Control Clock Multiplexed with DDI3_CTRLCLK_AUX+	I/O OD 3.3V		Not supported

Signal	Pin #	Description	I/O	PU/PD	Comment
HDMI3_CTRLDATA	C37	HDMI/DVI I ² C Control Data Multiplexed with DDI3_CTRLDATA_AUX-	I/O OD 3.3V		Not supported



Some signals have special functionality during the reset process. They may bootstrap some basic important functions of the module. For more information refer to section 8.5 of this user's guide.

Table 28 DisplayPort (DP) Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
DP1_LANE3+ DP1_LANE3-	D36 D37	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI1_PAIR3+ and DDI1_PAIR3-.	O PCIE		
DP1_LANE2+ DP1_LANE2-	D32 D33	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI1_PAIR2+ and DDI1_PAIR2-.	O PCIE		
DP1_LANE1+ DP1_LANE1-	D29 D30	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI1_PAIR1+ and DDI1_PAIR1-.	O PCIE		
DP1_LANE0+ DP1_LANE0-	D26 D27	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI1_PAIR0+ and DDI1_PAIR0-.	O PCIE		
DP1_HPD	C24	Detection of Hot Plug / Unplug and notification of the link layer. Multiplexed with DDI1_HPD.	I 3.3V	PD 1M	
DP1_AUX+	D15	Half-duplex bi-directional AUX channel for services such as link configuration or maintenance and EDID access.	I/O PCIE	PD 100k	
DP1_AUX-	D16	Half-duplex bi-directional AUX channel for services such as link configuration or maintenance and EDID access.	I/O PCIE	PU 100k 3.3V	DP1_AUX- is a boot strap signal (see note below). DP enable strap is already populated.
DP2_LANE3+ DP2_LANE3-	D49 D50	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI2_PAIR3+ and DDI2_PAIR3-	O PCIE		
DP2_LANE2+ DP2_LANE2-	D46 D47	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI2_PAIR2+ and DDI2_PAIR2-	O PCIE		
DP2_LANE1+ DP2_LANE1-	D42 D43	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI2_PAIR1+ and DDI2_PAIR1-	O PCIE		
DP2_LANE0+ DP2_LANE0-	D39 D40	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI2_PAIR0+ and DDI1_PAIR0-	O PCIE		

Signal	Pin #	Description	I/O	PU/PD	Comment
DP2_HPD	D44	Detection of Hot Plug / Unplug and notification of the link layer. Multiplexed with DDI2_HPD.	I 3.3V	PD 1M	
DP2_AUX+	C32	Half-duplex bi-directional AUX channel for services such as link configuration or maintenance and EDID access.	I/O PCIE	PD 100k	
DP2_AUX-	C33	Half-duplex bi-directional AUX channel for services such as link configuration or maintenance and EDID access.	I/O PCIE	PU 100k 3.3V	DP2_AUX- is a boot strap signal (see note below). DP enable strap already populated.
DP3_LANE3+ DP3_LANE3-	C49 C50	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI3_PAIR3+ and DDI3_PAIR3-.	O PCIE		Not supported
DP3_LANE2+ DP3_LANE2-	C46 C47	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI3_PAIR2+ and DDI3_PAIR2-.	O PCIE		Not supported
DP3_LANE1+ DP3_LANE1-	C42 C43	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI3_PAIR1+ and DDI3_PAIR1-.	O PCIE		Not supported
DP3_LANE0+ DP3_LANE0-	C39 C40	Uni-directional main link for the transport of isochronous streams and secondary data. Multiplexed with DDI3_PAIR0+ and DDI3_PAIR0-.	O PCIE		Not supported
DP3_HPD	C44	Detection of Hot Plug / Unplug and notification of the link layer. Multiplexed with DDI3_HPD.	I 3.3V		Not supported
DP3_AUX+	C36	Half-duplex bi-directional AUX channel for services such as link configuration or maintenance and EDID access.	I/O PCIE		Not supported
DP3_AUX-	C37	Half-duplex bi-directional AUX channel for services such as link configuration or maintenance and EDID access.	I/O PCIE		Not supported



Note

Some signals have special functionality during the reset process. They may bootstrap some basic important functions of the module. For more information refer to section 8.5 of this user's guide.

Table 29 Module Type Definition Signal Description

Signal	Pin #	Description				I/O	Comment
TYPE0# TYPE1# TYPE2#	C54 C57 D57	The TYPE pins indicate to the Carrier Board the Pin-out Type that is implemented on the module. The pins are tied on the module to either ground (GND) or are no-connects (NC). For Pinout Type 1, these pins are don't care (X).				PDS	TYPE[0:2]# signals are available on all modules following the Type 2-6 Pinout standard. The conga-TC97 is based on the COM Express Type 6 pinout therefore the pins 0 and 1 are not connected and pin 2 is connected to GND.
TYPE2#	TYPE1#	TYPE0#					
X	X	X	Pinout Type 1				
NC	NC	NC	Pinout Type 2				
NC	NC	GND	Pinout Type 3 (no IDE)				
NC	GND	NC	Pinout Type 4 (no PCI)				
NC	GND	GND	Pinout Type 5 (no IDE, no PCI)				
GND	NC	NC	Pinout Type 6 (no IDE, no PCI)				
The Carrier Board should implement combinatorial logic that monitors the module TYPE pins and keeps power off (e.g deactivates the ATX_ON signal for an ATX power supply) if an incompatible module pin-out type is detected. The Carrier Board logic may also implement a fault indicator such as an LED.							
TYPE10#	A97	Dual use pin. Indicates to the carrier board that a Type 10 module is installed. Indicates to the carrier that a Rev. 1.0/2.0 module is installed.				PDS	Not connected to indicate "Pinout R2.0".
TYPE10#							
NC			Pinout R2.0				
PD			Pinout Type 10 pull down to ground with 4.7k resistor				
12V			Pinout R1.0				
This pin is reclaimed from VCC_12V pool. In R1.0 modules this pin will connect to other VCC_12V pins. In R2.0 this pin is defined as a no-connect for Types 1-6. A carrier can detect a R1.0 module by the presence of 12V on this pin. R2.0 module Types 1-6 will no-connect this pin. Type 10 modules shall pull this pin to ground through a 4.7k resistor.							

Table 30 Power and GND Signal Descriptions

Signal	Pin #	Description	I/O	PU/PD	Comment
VCC_12V	C104-C109 D104-D109	Primary power input: +12V nominal. All available VCC_12V pins on the connector(s) shall be used.	P		
GND	C1, C2, C5, C8, C11, C14, C21, C31, C41, C51, C60, C70, C73, C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, D1, D2, D5, D8, D11, D14, D21, D31, D41, D51, D60, D67, D70, D73, D76, D80, D84, D87, D90, D93, D96, D100, D103, D110	Ground - DC power and signal and AC signal return path. All available GND connector pins shall be used and tied to carrier board GND plane.	P		

8.4 C-D Connector Pinout

Table 31 Connector C-D Pinout

Pin	Row C	Pin	Row D	Pin	Row C	Pin	Row D
C1	GND (FIXED)	D1	GND (FIXED)	C56	PEG_RX1- (*)	D56	PEG_TX1- (*)
C2	GND	D2	GND	C57	TYPE1#	D57	TYPE2#
C3	USB_SSRX0-	D3	USB_SSTX0-	C58	PEG_RX2+ (*)	D58	PEG_TX2+ (*)
C4	USB_SSRX0+	D4	USB_SSTX0+	C59	PEG_RX2- (*)	D59	PEG_TX2- (*)
C5	GND	D5	GND	C60	GND (FIXED)	D60	GND (FIXED)
C6	USB_SSRX1-	D6	USB_SSTX1-	C61	PEG_RX3+ (*)	D61	PEG_TX3+ (*)
C7	USB_SSRX1+	D7	USB_SSTX1+	C62	PEG_RX3- (*)	D62	PEG_TX3- (*)
C8	GND	D8	GND	C63	RSVD	D63	RSVD
C9	USB_SSRX2- (*)	D9	USB_SSTX2- (*)	C64	RSVD	D64	RSVD
C10	USB_SSRX2+ (*)	D10	USB_SSTX2+ (*)	C65	PEG_RX4+ (*)	D65	PEG_TX4+ (*)
C11	GND (FIXED)	D11	GND (FIXED)	C66	PEG_RX4- (*)	D66	PEG_TX4- (*)
C12	USB_SSRX3- (*)	D12	USB_SSTX3- (*)	C67	RSVD	D67	GND
C13	USB_SSRX3+ (*)	D13	USB_SSTX3+ (*)	C68	PEG_RX5+ (*)	D68	PEG_TX5+ (*)
C14	GND	D14	GND	C69	PEG_RX5- (*)	D69	PEG_TX5- (*)
C15	DDI1_PAIR6+ (*)	D15	DDI1_CTRLCLK_AUX+	C70	GND (FIXED)	D70	GND (FIXED)
C16	DDI1_PAIR6- (*)	D16	DDI1_CTRLDATA_AUX-	C71	PEG_RX6+ (*)	D71	PEG_TX6+ (*)
C17	RSVD	D17	RSVD	C72	PEG_RX6- (*)	D72	PEG_TX6- (*)
C18	RSVD	D18	RSVD	C73	GND	D73	GND
C19	PCIE_RX6+ (*)	D19	PCIE_TX6+ (*)	C74	PEG_RX7+ (*)	D74	PEG_TX7+ (*)
C20	PCIE_RX6- (*)	D20	PCIE_TX6- (*)	C75	PEG_RX7- (*)	D75	PEG_TX7- (*)
C21	GND (FIXED)	D21	GND (FIXED)	C76	GND	D76	GND
C22	PCIE_RX7+ (*)	D22	PCIE_TX7+ (*)	C77	RSVD	D77	RSVD
C23	PCIE_RX7- (*)	D23	PCIE_TX7- (*)	C78	PEG_RX8+ (*)	D78	PEG_TX8+ (*)
C24	DDI1_HPD	D24	RSVD	C79	PEG_RX8- (*)	D79	PEG_TX8- (*)
C25	DDI1_PAIR4+ (*)	D25	RSVD	C80	GND (FIXED)	D80	GND (FIXED)
C26	DDI1_PAIR4- (*)	D26	DDI1_PAIR0+	C81	PEG_RX9+ (*)	D81	PEG_TX9+ (*)
C27	RSVD	D27	DDI1_PAIR0-	C82	PEG_RX9- (*)	D82	PEG_TX9- (*)
C28	RSVD	D28	RSVD	C83	RSVD	D83	RSVD
C29	DDI1_PAIR5+ (*)	D29	DDI1_PAIR1+	C84	GND	D84	GND
C30	DDI1_PAIR5- (*)	D30	DDI1_PAIR1-	C85	PEG_RX10+ (*)	D85	PEG_TX10+ (*)
C31	GND (FIXED)	D31	GND (FIXED)	C86	PEG_RX10- (*)	D86	PEG_TX10- (*)
C32	DDI2_CTRLCLK_AUX+	D32	DDI1_PAIR2+	C87	GND	D87	GND
C33	DDI2_CTRLDATA_AUX-	D33	DDI1_PAIR2-	C88	PEG_RX11+ (*)	D88	PEG_TX11+ (*)
C34	DDI2_DDC_AUX_SEL	D34	DDI1_DDC_AUX_SEL	C89	PEG_RX11- (*)	D89	PEG_TX11- (*)
C35	RSVD	D35	RSVD	C90	GND (FIXED)	D90	GND (FIXED)
C36	DDI3_CTRLCLK_AUX+ (*)	D36	DDI1_PAIR3+	C91	PEG_RX12+ (*)	D91	PEG_TX12+ (*)

Pin	Row C	Pin	Row D	Pin	Row C	Pin	Row D
C37	DDI3_CTRLDATA_AUX- (*)	D37	DDI1_PAIR3-	C92	PEG_RX12- (*)	D92	PEG_TX12- (*)
C38	DDI3_DDC_AUX_SEL (*)	D38	RSVD	C93	GND	D93	GND
C39	DDI3_PAIR0+ (*)	D39	DDI2_PAIR0+	C94	PEG_RX13+ (*)	D94	PEG_TX13+ (*)
C40	DDI3_PAIR0- (*)	D40	DDI2_PAIR0-	C95	PEG_RX13- (*)	D95	PEG_TX13- (*)
C41	GND (FIXED)	D41	GND (FIXED)	C96	GND	D96	GND
C42	DDI3_PAIR1+ (*)	D42	DDI2_PAIR1+	C97	RVSD	D97	RSVD
C43	DDI3_PAIR1- (*)	D43	DDI2_PAIR1-	C98	PEG_RX14+ (*)	D98	PEG_TX14+ (*)
C44	DDI3_HPD	D44	DDI2_HPD	C99	PEG_RX14- (*)	D99	PEG_TX14- (*)
C45	RSVD	D45	RSVD	C100	GND (FIXED)	D100	GND (FIXED)
C46	DDI3_PAIR2+ (*)	D46	DDI2_PAIR2+	C101	PEG_RX15+ (*)	D101	PEG_TX15+ (*)
C47	DDI3_PAIR2- (*)	D47	DDI2_PAIR2-	C102	PEG_RX15- (*)	D102	PEG_TX15- (*)
C48	RSVD	D48	RSVD	C103	GND	D103	GND
C49	DDI3_PAIR3+ (*)	D49	DDI2_PAIR3+	C104	VCC_12V	D104	VCC_12V
C50	DDI3_PAIR3- (*)	D50	DDI2_PAIR3-	C105	VCC_12V	D105	VCC_12V
C51	GND (FIXED)	D51	GND (FIXED)	C106	VCC_12V	D106	VCC_12V
C52	PEG_RX0+ (*)	D52	PEG_TX0+ (*)	C107	VCC_12V	D107	VCC_12V
C53	PEG_RX0- (*)	D53	PEG_TX0- (*)	C108	VCC_12V	D108	VCC_12V
C54	TYPE0#	D54	PEG_LANE_RV# (*)	C109	VCC_12V	D109	VCC_12V
C55	PEG_RX1+ (*)	D55	PEG_TX1+ (*)	C110	GND (FIXED)	D110	GND (FIXED)



The signals marked with an asterisk symbol () are not supported on the conga-TC97.*

8.5 Boot Strap Signals

Table 32 Boot Strap Signal Descriptions

Signal	Pin #	Description of Boot Strap Signal	I/O	PU/PD	Comment
AC/HDA_SDOUT	A33	High Definition Audio Serial Data Out: This signal is the serial TDM data output to the codec(s). This serial output is double-pumped for a bit rate of 48 Mb/s for High Definition Audio.	O 3.3VSB	PU 1K 3.3VSB	AC/HDA_SDOUT is a boot strap signal (see caution statement below)
SPKR	B32	Output for audio enunciator, the "speaker" in PC-AT systems	O 3.3V		SPKR is a boot strap signal (see caution statement below)
DDI1_CTRLDATA_AUX- DP1_AUX- HDMI_CTRLDATA	D16	Multiplexed with DP1_AUX- and HDMI1_CTRLDATA. DP AUX- function if DDI1_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLDATA if DDI1_DDC_AUX_SEL is pulled high.	I/O PCIE I/O OD 3.3V	PU100k 3.3V	DDI1_CTRLDATA_AUX- is a boot strap signal (see not below).
DDI2_CTRLDATA_AUX- DP2_AUX- HDM2_CTRLDATA	C33	Multiplexed with DP2_AUX- and HDMI2_CTRLDATA. DP AUX- function if DDI2_DDC_AUX_SEL is no connect. HDMI/DVI I2C CTRLDATA if DDI2_DDC_AUX_SEL is pulled high.	I/O PCIE I/O OD 3.3V	PU100k 3.3V	DDI2_CTRLDATA_AUX- is a boot strap signal (see not below).



Caution

The signals listed in the table above are used as chipset configuration straps during system reset. In this condition (during reset), they are inputs that are pulled to the correct state by either COM Express™ internally implemented resistors or chipset internally implemented resistors that are located on the module. No external DC loads or external pull-up or pull-down resistors should change the configuration of the signals listed in the above table. External resistors may override the internal strap states and cause the COM Express™ module to malfunction and/or cause irreparable damage to the module.

9 System Resources

9.1 I/O Address Assignment

The I/O address assignment of the conga-TC97 module is functionally identical with a standard PC/AT.



The BIOS assigns PCI and PCI Express I/O resources from FFF0h downwards. Non PnP/PCI/PCI Express compliant devices must not consume I/O resources in that area.

9.1.1 LPC Bus

On the conga-TC97, the PCI Express Bus acts as the subtractive decoding agent. All I/O cycles that are not positively decoded are forwarded to the internal PCI Bus not the LPC Bus. Only specified I/O ranges are forwarded to the LPC Bus. In the congatec Embedded BIOS, the following I/O address ranges are sent to the LPC Bus:

2Eh – 2Fh

4Eh – 4Fh

60h, 64h

A00h – AFFh

C00h – CFFh (always used internally)

Parts of these ranges are not available if a Super I/O is used on the carrier board. If a Super I/O is not implemented on the carrier board, then these ranges are available for customer use. If you require additional LPC Bus resources other than those mentioned above, or more information about this subject, contact congatec technical support for assistance.

9.2 PCI Configuration Space Map

Table 33 PCI Configuration Space Map

Bus Number (hex)	Device Number (hex)	Function Number (hex)	Description
00h	00h	00h	Host Bridge
00h	02h	00h	Graphics
00h	03h	00h	Intel High Definition Audio controller
00h	14h	00h	XHCI Host Controller
00h(Note1)	16h	00h	Management Engine (ME) Interface 1
00h(Note1)	16h	01h	Intel ME Interface 2
00h(Note1)	16h	02h	ME IDE Redirection (IDE-R) Interface
00h(Note1)	16h	03h	ME KT (Remote Keyboard and Text)
00h	19h	00h	Onboard Gigabit LAN Controller
00h (Note2)	1Ch	00h	PCI Express Root Port 0
00h (Note2)	1Ch	01h	PCI Express Root Port 1
00h (Note2)	1Ch	02h	PCI Express Root Port 2
00h (Note2)	1Ch	03h	PCI Express Root Port 3
00h	1Dh	00h	EHCI Host Controller
00h	1Fh	00h	PCI to LPC Bridge
00h	1Fh	02h	Serial ATA Controller
00h	1Fh	03h	SMBus Host Controller
00h	1Fh	06h	Thermal Subsystem
01h (Note3)	00h	00h	PCI Express Port 0
02h (Note3)	00h	00h	PCI Express Port 1
03h (Note3)	00h	00h	PCI Express Port 2
04h (Note3)	00h	00h	PCI Express Port 3



- Note**
1. In the standard configuration, the Intel Management Engine (ME) related devices are partly present or not present at all.
 2. The PCI Express Ports are visible only if a device is attached behind them to the PCI Express Slot on the carrier board.
 3. The table represents a case when a single function PCI/PCIe device is connected to all possible slots on the carrier board. The given bus numbers will change based on actual hardware configuration.

9.3 PCI Interrupt Routing Map

Table 34 PCI Interrupt Routing Map

PIRQ	PCI BUS INT Line ¹	APIC Mode IRQ	Graphic	HDA	XHCI	EHCI	SMBus + Thermal	LAN	SATA	PCI-EX Root Port 0	PCI-EX Root Port 1	PCI-EX Root Port 2	PCI-EX Root Port 3	PCI- EX Port 0	PCI-EX Port 1	PCI-EX Port 2	PCI-EX Port 3
A	INTA	16	x	x	x					x				x ²	x ⁵	x ⁴	x ³
B	INTB	17									x			x ³	x ²	x ⁵	x ⁴
C	INTC	18					x					x		x ⁴	x ³	x ²	x ⁵
D	INTD	19							x				x	x ⁵	x ⁴	x ³	x ²
E		20						x									
F		21															
G		22															
H		23				x											



Note

¹ These interrupt lines are virtual (message based).

² Interrupt used by single function PCI Express devices (INTA).

³ Interrupt used by multifunction PCI Express devices (INTB).

⁴ Interrupt used by multifunction PCI Express devices (INTC).

⁵ Interrupt used by multifunction PCI Express devices (INTD).

9.4 I²C Bus

There are no onboard resources connected to the I²C bus. Address 16h is reserved for congatec Battery Management solutions.

9.5 SM Bus

System Management (SM) bus signals are connected to the Intel® 9 Series PCH-LP and the SM bus is not intended to be used by off-board non-system management devices. For more information about this subject, contact congatec technical support.

10 BIOS Setup Description

The following section describes the BIOS setup program. The BIOS setup program can be used to view and change the BIOS settings for the module. Only experienced users should change the default BIOS settings.

10.1 Entering the BIOS Setup Program.

The BIOS setup program can be accessed by pressing the or <F2> key during POST.

10.1.1 Boot Selection Popup

Press the <F11> key during POST to access the Boot Selection Popup menu. A selection menu displays immediately after POST, allowing the operator to select either the boot device that should be used or an option to enter the BIOS setup program.

10.2 Setup Menu and Navigation

The congatec BIOS setup screen is composed of the menu bar, left frame and right frame. The menu bar is shown below:

Main	Advanced	Chipset	Security	Boot	Save & Exit
------	----------	---------	----------	------	-------------

The left frame displays all the options that can be configured in the selected menu. Grayed-out options cannot be configured. Only the blue options can be configured. When an option is selected, it is highlighted in white.

The right frame displays the key legend. Above the key legend is an area reserved for text messages. These text messages explain the options and the possible impacts when changing the selected option in the left frame.



Note

Entries in the option column that are displayed in bold indicate BIOS default values.

The setup program uses a key-based navigation system. Most of the keys can be used at any time while in setup. The table below explains the supported keys:

Key	Description
← → Left/Right	Select a setup menu (e.g. Main, Boot, Exit).
↑ ↓ Up/Down	Select a setup item or sub menu.
+ - Plus/Minus	Change the field value of a particular setup item.
Tab	Select setup fields (e.g. in date and time).
F1	Display General Help screen.
F2	Load previous settings.
F9	Load optimal default settings.
F10	Save changes and exit setup.
ESC	Discard changes and exit setup.
ENTER	Display options of a particular setup item or enter submenu.

10.3 Main Setup Screen

When you first enter the BIOS setup, you will enter the main setup screen. The main setup screen reports BIOS, processor, memory and board information and is for configuring the system date and time. You can always return to the main setup screen by selecting the 'Main' tab.

Feature	Options	Description
Main BIOS Version	No option	Displays the main BIOS version.
OEM BIOS Version	No option	Displays the additional OEM BIOS version.
Build Date	No option	Displays the date the BIOS was built.
Product Revision	No option	Displays the hardware revision of the board.
Serial Number	No option	Displays the serial number of the board.
BC Firmware Revision	No option	Displays the firmware revision of the congatec board controller.
MAC Address	No option	Displays the MAC address of the onboard i218 Ethernet controller.
Boot Counter	No option	Displays the number of boot-ups. (max. 16777215).
Running Time	No option	Displays the time the board is running [in hours max. 65535].
► Platform Information	Submenu	Opens the platform information submenu.
System Date	Day of week, month/ day/year	Specifies the current system date Note: The date is in month/day/year format.
System Time	Hour:Minute:Second	Specifies the current system time. Note: The time is in 24 hour format.

10.3.1 Platform Information Submenu

The platform information submenu offers additional hardware and software information.

Feature	Options	Description
Processor Information	No option	Subtitle.
Processor Type	No option	Displays the processor ID string. The 'Processor Type' text is not displayed.
Codename	No option	Displays the processor codename
Processor Speed	No option	Displays the processor speed.
Processor Signature	No option	Displays the processor signature.
Stepping	No option	Displays the processor stepping.
Processor Cores	No option	Displays the number of processor cores.
Microcode Revision	No option	Displays the processor microcode revision .
IGD HW Version	No option	Displays the version of the graphics controller.
IGD VBIOS Version	No option	Displays the video BIOS version.
Total Memory	No option	Displays the total amount of installed memory.
PCH Information	No option	Subtitle.
Codename	No option	Displays the codename of the platform controller hub (PCH).
PCH SKU	No option	Displays the SKU name of the PCH.
Stepping	No option	Displays the PCH stepping
ME FW Version	No option	Displays the ME FW version when available
ME Firmware SKU	No option	Displays the ME Firmware SKU when available

10.4 Advanced Setup

Select the advanced tab from the setup menu to enter the advanced BIOS setup screen. The menu is used for setting advanced features and only features described within this user's guide are listed.

Main	Advanced	Chipset	Boot	Security	Save & Exit
	Graphics				
	Watchdog				
	Hardware Health Monitoring				
	Module Serial Ports				
	CPU				
	Trusted Computing				
	RTC Wake				
	ACPI				
	PCH-FW ¹				
	AMT ¹				
	Acoustic Management				
	SMART Settings				
	Super IO				
	Serial Port Console Redirection				
	SATA				
	PCI & PCI Express				
	UEFI Network Stack				
	CSM & Option ROM Control				
	USB				
	PC Speaker				
	GPIO Configuration				
	Diagnostics Settings				
	Intel® Ethernet Connection I218-LM				
	Intel® Rapid Storage Technology ²				



¹ Not displayed if disabled in the BIOS.

² Displays only if the SATA Mode Selection feature in SATA submenu is set to "RAID" and the Storage Option ROM Launch Policy feature in the CSM & Option ROM Control submenu is set to "UEFI ROM Only".

10.4.1 Graphics Submenu

Feature	Options	Description
Primary Graphics Device	Auto IGD PCI/PCIe	Select the primary graphics adapter used during boot up: 'Auto' - BIOS selects it automatically. 'IGD' - Internal Graphics Device (IGD) located in chipset. 'PCI/PCIe' - PCI/PCIe graphics card attached to some other (not PEG) PCI/PCIe port.
Internal Graphics Device	Auto Disabled Enabled	Configure Internal Graphics Device (IGD).
IGD Pre-Allocated Graphics Memory	32M , 64M, 96M, 128M, 160M, 192M, 224M, 256M, 288M, 320M, 352M, 384M, 416M, 448M, 480M, 512M, 1024M, 2016M	Select amount of pre-allocated / fixed graphics memory used by the IGD.
IGD Total Graphics Memory	128MB 256MB MAX	Select amount of total graphics memory that may be used by the IGD. The graphics driver dynamically allocates memory that is above the fixed memory according to DVMT 5.0 specification. 'MAX' - Uses as much graphics memory as possible. The actual memory allocation depends on total system memory installed and the operating system in use (see DVMT 5.0 specification).
Primary IGD Boot Display Device	Auto LFP EFP EFP2	Select the primary IGD display device(s) used for boot up: 'LFP' - Uses a LVDS panel connected to the integrated LVDS port. 'EFPx' - Uses a HDMI/DVI or DisplayPort device connected to the DDI1 and DDI2. Note: EFP selections are only valid when at least one DDI is enabled. The first enabled DDI is assigned to EFP. Therefore, EFP and DDI numbering do not necessarily match.
Secondary IGD Boot Display Device	Disabled LFP EFP EFP2	Select the secondary IGD display device(s) used for boot up.
Active LFP Configuration	No Local Flat Panel Integrated LVDS eDP	Select the active LFP configuration.
Always Try Auto Panel Detect	No Yes	If set to 'Yes', the BIOS will use the EDID™ data set in an external EEPROM to configure the LFP. In case it cannot be found, the data set selected under 'Local Flat Panel Type' is used.

Feature	Options	Description
Local Flat Panel Type	Auto VGA 640x480 1x18 (002h) VGA 640x480 1x18 (013h) WVGA 800x480 1x18 (01Fh) WVGA 800x480 1x24 (01Bh) SVGA 800x600 1x18 (01Ah) XGA 1024x768 1x18 (006h) XGA 1024x768 2x18 (007h) XGA 1024x768 1x24 (008h) XGA 1024x768 2x24 (012h) WXGA 1280x800 1x18 (01Eh) WXGA 1280x768 1x24 (01Ch) SXGA 1280x1024 2x24 (00Ah) SXGA 1280x1024 2x24 (018h) UXGA 1600x1200 2x24 (00Ch) HD 1920x1080 2x24 (01Dh) WUXGA 1920x1200 2x18 (015h) WUXGA 1920x1200 2x24 (00Dh) Customized EDID™ 1 Customized EDID™ 2 Customized EDID™ 3	Select a predefined LFP type or choose 'Auto' to let the BIOS automatically detect and configure the attached LVDS panel. Auto detection is performed by reading an EDID™ data set via the video I²C bus. The number in brackets specifies the congatec internal number of the respective panel data set. Note: Customized EDID™ utilizes an OEM defined EDID™ data set stored in the BIOS flash device.
Backlight Inverter Type	None PWM I2C	Select the type of backlight inverter: 'PWM' - IGD PWM signal. 'I2C' - I2C backlight inverter device connected to the video I²C bus.
PWM Inverter Polarity	Normal Inverted	Set the PWM inverter polarity. Note: This feature is only visible if 'Backlight Inverter Type' is set to 'PWM'.
PWM Inverter Frequency (Hz)	200 - 40000	Set the PWM inverter frequency in Hertz. Note: This feature is only visible if 'Backlight Inverter Type' is set to 'PWM'.
Backlight Setting	0%, 10%, 25%, 40%, 50%, 60%, 75%, 90%, 100%	Select the backlight value in percentage of the maximum setting.
Force Backlight Enable	No Yes	If set to 'Yes', forces backlight enable signal active. Note: Use this feature if the operating system driver does not activate the backlight enable signal.
Inhibit Backlight	No Permanent Until End Of POST	Select whether the backlight enable signal should be activated when the panel is activated, remain inhibited until the end of BIOS POST, or remain inhibited permanently.
Backlight Delay	No Delay 100ms Delay 250ms Delay 500ms Delay 1s Delay	Set a delay to adjust the LVDS panel timings. The congatec board controller will add the delay to the backlight signal coming from the SoC according this setup node. Note: Please try this feature if your panel is flickering.
Invert Backlight Setting	No Yes	Allow to invert backlight control values if required for the actual I2C type backlight hardware controller.

Feature	Options	Description
LVDS SSC	Disabled 0.5%, 1.0%, 1.5%, 2.0%, 2.5%	Select the LVDS spread-spectrum clock modulation depth. Note: This feature performs center spreading with a fixed modulation frequency of 32.9kHz.
Digital Display Interface 1 (DDI1)	Auto Selection Disabled Display Port HDMI/DVI	Select the output type of the DDI1.
Digital Display Interface 2 (DDI2)	Auto Selection Disabled Display Port HDMI/DVI	Select the output type of the DDI2.
Intel® GOP Driver	No option	Note: The Intel® (GOP) driver, output device and BIST enable features are only visible if GOP driver is configured to be used in the 'Video Option ROM Launch Policy' setup node.
Output Device	Options depend on detected display devices	Configure graphics output interface when using the UEFI GOP driver instead of the legacy video BIOS.
BIST Enable	Disabled Enabled	Enable or disable the Built-in Self-Test (BIST) on the integrated display panel.

10.4.2 Watchdog Submenu

Feature	Options	Description
POST Watchdog	Disabled 30sec, 1min, 2min, 5min, 10min, 30min	Select the timeout value for the POST watchdog. Note: The watchdog is only active during the system POST and provides a facility to prevent errors during boot up by performing a reset.
Stop Watchdog for User Interaction	No Yes	Select whether the POST watchdog should be stopped during the popup of the boot selection menu or while waiting for setup password insertion.
Runtime Watchdog	Disabled One-time Trigger Single Event Repeated Event	Select the operating mode of the runtime watchdog: 'One-time Trigger' - Disables watchdog after the first trigger. 'Single Event' - Executes every stage once before the watchdog is disabled. 'Repeated Event' - Executes the last stage repeatedly until reset. Note: This watchdog will be initialized just before the operating system starts booting.
Delay	Disabled 10sec, 30sec, 1min, 2min 5min, 10min, 30min	The runtime watchdog is delayed for the selected time. Note: Use this feature to ensure that the operating system has enough time to load.
Event 1	ACPI Event Reset Power Button	Select the type of event that will be generated when timeout 1 is reached.
Event 2	Disabled ACPI Event Reset Power Button	Select the type of event that will be generated when timeout 2 is reached.

Feature	Options	Description
Event 3	Disabled ACPI Event Reset Power Button	Select the type of event that will be generated when timeout 3 is reached.
Timeout 1	1sec, 2sec, 5sec, 10sec, 30sec , 1min, 2min, 5min, 10min, 30min	Select the timeout value for the first stage watchdog event.
Timeout 2	Same as 'Timeout 1'	Same as 'Timeout 1'.
Timeout 3	Same as 'Timeout 1'	Same as 'Timeout 2'.
Watchdog ACPI Event	Shutdown Restart	Select the operating system event that is initiated by the watchdog ACPI event. This feature perform a critical but orderly operating system shutdown or restart.



In ACPI mode, it is not possible for a "Watchdog ACPI Event" handler to directly restart or shutdown the operating system. For this reason the congatec BIOS will do one of the following:

For Shutdown: An over temperature notification is executed. This causes the operating system to shut down in an orderly fashion.

For Restart: An ACPI fatal error is reported to the operating system.

10.4.3 Hardware Health Monitoring Submenu

Feature	Options	Description
CPU Temperature	No option	Displays the CPU temperature in °C.
Board Temperature	No option	Displays the board temperature in °C.
12V Standard	No option	Displays the actual 12V standard voltage.
5V Standby	No option	Displays the actual 5V standby voltage.
Input Current (12V Standard)	No option	Displays the actual input current of 12V standard power plane.
CPU Fan Speed	No option	Displays the CPU fan speed in RPM.
Fan PWM Frequency Mode	Low Frequency High Frequency	Select the fan PWM base frequency mode: Low Frequency 11.0 to 88.2Hz. High Frequency 1k to 63kHz.
Fan PWM Frequency	11.0 Hz, 14.7 Hz, 22.1 Hz, 29.4 Hz, 35.3 Hz , 44.1 Hz 58.8 Hz, 88.2 Hz	Select fan PWM base frequency. Note: Only visible in low frequency mode.

Feature	Options	Description
Fan PWM Frequency (kHz)	1 - 63	Select fan PWM base frequency (1kHz-63kHz). Default: 31 Note: This feature is only visible in high frequency mode.
Default Fan Speed	0%, 10%, 25%, 40%, 50%, 60%, 75%, 90%, 100%	Select the percentage of the maximum supported fan speed to use when the automatic fan speed control feature is disabled.
Automatic Fan Speed Control	Disabled Enabled	Enable or disable automatic fan speed control.
Fan Control Temperature	CPU Temperature Board Temperature	Choose the temperature sensor used for automatic fan speed control.
Lower Temperature Limit	10 C, 20 C, 30 C, 40 C, 50 C , 60 C, 70 C, 80 C, 90 C	Set the temperature which defines the lower limit of the control range.
Upper Temperature Limit	20 C, 30 C, 40 C, 50 C, 60 C, 70 C, 80 C , 90 C, 100 C	Set the temperature which defines the upper limit of the control range.
Minimum Fan Speed	Fan Off, 10%, 15%, 20%, 25%, 30%, 35%, 40% , 45%, 50%, 55%, 60%, 65%, 70%, 75%, 80%, 85%, 90%, 95%	Choose the fan speed to be set if the temperature is below the lower temperature limit.
Mid Range Bottom Fan Speed	Fan Off, 10%, 15%, 20%, 25%, 30%, 35%, 40%, 45%, 50%, 55%, 60% , 65%, 70%, 75%, 80%, 85%, 90%, 95%	Choose the fan speed to be set if the temperature is within the lower area of the control range.
Mid Range Top Fan Speed	Fan Off, 10%, 15%, 20%, 25%, 30%, 35%, 40%, 45%, 50%, 55%, 60%, 65%, 70%, 75%, 80% , 85%, 90%, 95%	Choose the fan speed to be set if the temperature is within the upper area of the control range.
Maximum Fan Speed	10%, 15%, 20%, 25%, 30%, 35%, 40%, 45%, 50%, 55%, 60%, 65%, 70%, 75%, 80%, 85%, 90%, 95%, 100%	Choose the fan speed to be set if the temperature exceeds the upper temperature limit.

10.4.4 Module Serial Ports Submenu

Feature	Options	Description
Serial Port 0	Disabled Enabled	Enable or disable module's serial port 0.
I/O Base Address	3F8h, 2F8h, 220h, 228h, 238h, 2E8h, 338h, 3E8h	Set serial port base address.
Interrupt	None IRQ3, IRQ4, IRQ5, IRQ6, IRQ10 , IRQ11, IRQ14, IRQ15	Set serial port interrupt.
PNP ID	None PNP0501 CGT0501	Set serial port ACPI ID.
Baudrate	2400 , 4800, 9600, 19200, 38400, 57600, 115200	Set serial port initial baudrate.
Serial Port 1	Disabled Enabled	Enable or disable module serial port 1.
I/O Base Address	3F8h, 2F8h, 220h, 228h, 238h, 2E8h , 338h, 3E8h	Set serial port base address.
Interrupt	None IRQ3, IRQ4, IRQ5, IRQ6, IRQ10, IRQ11 , IRQ14, IRQ15	Set serial port interrupt.
PNP ID	None PNP0501 CGT0501 CGT0502	Set serial port ACPI ID.
Baudrate	2400 , 4800, 9600, 19200, 38400, 57600, 115200	Set serial port initial baudrate.

10.4.5 CPU Submenu

Feature	Options	Description
Processor Type	No option	Displays the processor ID string. The "Processor Type" is not displayed.
CPU Signature	No option	Displays the CPU signature.
Microcode Patch	No option	Displays the revision of the microcode patch.
Max CPU Speed	No option	Displays the maximum CPU speed.
Min CPU Speed	No option	Displays the minimum CPU speed.
CPU Speed	No option	Displays the current CPU speed.

Feature	Options	Description
Processor Cores	No option	Displays the number of the processor cores.
Intel HT Technology	No option	Displays whether the Intel® HT technology is supported.
Intel VT-x Technology	No option	Displays whether the Intel® VT-x technology is supported.
Intel SMX Technology	No option	Displays whether the Intel® SMX technology is supported.
64-bit	No option	Displays whether 64-bit is supported.
EIST Technology	No option	Displays whether the Enhanced Intel SpeedStep Technology (EIST) is supported.
CPU C3 State	No option	Displays whether the CPU C3 state is supported.
CPU C6 State	No option	Displays whether the CPU C6 state is supported.
CPU C7 State	No option	Displays whether the CPU C7 state is supported.
L1 Data Cache	No option	Displays the size of the L1 data cache.
L1 Code Cache	No option	Displays the size of the L1 code cache.
L2 Cache	No option	Displays the size of the L2 cache.
L3 Cache	No option	Displays the size of the L3 cache.
L4 Cache	No option	Displays the size of the L4 cache.
Hyper-Threading	Disabled Enabled	Enable or disable Hyper-Threading technology.
Active Processor Cores	All 1, 2, 3	Enable the required number of cores.
Overclocking Lock	Disabled Enabled	FLEX_RATIO(194) MSR.
Limit CPUID Maximum	Disabled Enabled	If set to 'Enabled', the processor limits the maximum CPUID input value to 03h when queried, even if the processor supports a higher CPUID input value. If set to 'Disabled', the processor returns the actual maximum CPUID input value of the processor when queried. Note: Limiting the CPUID input value might be required for older operating systems that cannot handle the extra CPUID information returned when using the full CPUID input value.
Execute Disable Bit	Disabled Enabled	If set to 'Enabled', this feature helps to prevent certain classes of malicious buffer overflow attacks. Note: Please ensure that your operating system supports this feature if you want to use it.
Intel Virtualization Technology	Disabled Enabled	Enable or disable support for the Intel virtualization technology.
Hardware Prefetcher	Disabled Enabled	Enable or disable the Mid Level Cache (L2) streamer prefetcher.
Adjacent Cache Line Prefetch	Disabled Enabled	Enable or disable the Mid Level Cache (L2) prefetching of adjacent cache lines.
CPU AES	Disabled Enabled	Enable or disable CPU Advanced Encryption Standard (AES) instructions.

Feature	Options	Description
Boot Performance Mode	Max Non-Turbo Performance Max Battery Turbo Performance	Select the performance state the BIOS will set before operating system handoff.
EIST	Disabled Enabled	Enable or disable Enhanced Intel® SpeedStep Technology (EIST).
Turbo Mode	Disabled Enabled	Enable or disable Turbo Mode.
Energy Performance	Performance Balanced Perform. Balanced Energy Energy Efficient	Select energy preference setting.
Package Power Limit Lock	Disabled Enabled	If enabled, PACKAGE_POWER_LIMIT MSR is locked and a reset will be required to unlock the register.
Platform Power Limit Lock	Disabled Enabled	If enabled, PLATFORM_POWER_LIMIT MSR is locked and a reset will be required to unlock the register.
CPU Power Limit3	0 - 255	Select CPU Power Limit3 value
CPU Power Limit3 Time	0 - 255	Select time window during which the Power Limit3 is maintained.
CPU Power Limit3 Duty Cycle	0 - 100	Select the duty cycle in percentage the CPU is required to maintain over the configured Power Limit 3 time windows..
DDR Power Limit1	0 - 255	Select DDR Power Limit1 value
DDR Power Limit1 Time	0 - 255	Select time window in which the DDR Power Limit1 is maintained.
DDR Power Limit2	0 - 255	Select DDR Power Limit2 value
1-Core Ratio Limit	0 - 255	Select limit for 1 active core. 0 means using the factory-configured value.
2-Core Ratio Limit	0 - 255	Select limit for 2 active cores. 0 means using the factory-configured value.
3-Core Ratio Limit	0 - 255	Select limit for 3 active cores. 0 means using the factory-configured value.
4-Core Ratio Limit	0 - 255	Select limit for 4 active cores. 0 means using the factory-configured value.
VR Current Value Lock	Disabled Enabled	Enable this feature to lock the VR current value from further writes until reset.
VR Current Value	0 - 8191	Select the voltage regulator current limit. '0' means automatic.
CPU C States	Disabled Enabled	Enable or disable CPU C states.
Enhanced C1 State	Disabled Enabled	Enable or disable enhanced C1 state.
CPU C3 Report	Disabled Enabled	Enable or disable CPU C3 report to operating system.
CPU C6 Report	Disabled Enabled	Enable or disable CPU C6 report to operating system.

Feature	Options	Description
C6 Latency	Short Long	Select latency for C6.
CPU C7 Report	Disabled CPU C7 CPU C7s	Enable or disable CPU C7 report to operating system.
C7 Latency	Short Long	Select latency for C7.
CPU C8 Report	Disabled Enabled	Enable or disable CPU C8 report to operating system. Note: This feature is not displayed/supported on all processors types.
CPU C9 Report	Disabled Enabled	Enable or disable CPU C9 report to operating system. Note: This feature is not displayed/supported on all processors types.
CPU C10 Report	Disabled Enabled	Enable or disable CPU C10 report to operating system. Note: This feature is not displayed/supported on all processors types.
C9/C10 Voltage Override	Disabled 0.7V, 0.8V, 0.9V, 1.0V	Enable or disable C9/C10 override for BDW C9/C10 hard hang issue. Note: If this feature is enabled, it ensures that the Vccin voltage reduction actions for C9/C10 are maintained to the selected voltage level (instead of default of 0V) on BDW U and Y SKUs.
C1 State Auto Demotion	Disabled Enabled	If this feature is enabled, the processor will conditionally demote C3/C6/C7 requests to C1 based on uncore auto-demote information.
C3 State Auto Demotion	Disabled Enabled	If this feature is enabled, the processor will conditionally demote C6/C7 requests to C3 based on uncore auto-demote information.
Package C State Demotion	Disabled Enabled	Enable or disable package C state demotion.
C1 State Auto Undemotion	Disabled Enabled	Enable or disable un-demotion from demoted C1.
C3 State Auto Undemotion	Disabled Enabled	Enable or disable un-demotion from demoted C3.
Package C State Undemotion	Disabled Enabled	Enable or disable package C state un-demotion.
C State Pre-Wake	Disabled Enabled	Enable or disable C state pre-wake feature.
CFG Lock	Disabled Enabled	Enable or disable MSR 0xE2[15], CFG lock bit.
Package C State Limit	C0/C1, C2, C3, C6 , C7, C7s, C8, C9, C10, AUTO	Select package C state limit
Lake Tiny Feature	Disabled Enabled	Enable or disable lake tiny feature for C state configuration.
ACPI CTDP BIOS	Disabled Enabled	Enable or disable ACPI CTDP BIOS support.

Feature	Options	Description
Configurable TDP Level	TDP NOMINAL TDP DOWN TDP UP Disabled	Select configurable TDP level base.
Config TDP Lock	Disabled Enabled	Enable this feature to lock the config TDP control register.
TCC Activation Offset	0 - 50	Set the offset from the Intel® factory Thermal Control Circuit (TCC) activation temperature. For example: If the factory TCC activation temperature is 100C, enter 10 to activate TCC at 90C. Note: When active, the TCC lowers the CPU core and graphics core frequency, voltage or both.
Intel TXT(LT) Support	Disabled Enabled	Enable or disable Intel® TXT(LT) support.
IOOUT Offset Sign	0 1	'0' - Positive offset. '1' - Negative offset.
IOOUT Offset	0 - 625	Select VR IOOUT offset
IOOUT Slope	0 - 1023	Select VR IOOUT slope.
Debug Interface	Disabled Enabled	Enable or disable CPU debug interface.
Debug Interface Lock	Disabled Enabled	Enable to lock CPU debug interface setting.

10.4.6 Trusted Computing Submenu

Feature	Options	Description
Security Device Support	Disabled Enabled	Enable or disable BIOS support for the security device. Note: If enabled, the operating system will not display the security device. The TCG EFI protocol and INT1A interface are unavailable.
Device Select	TPM 1.2 TPM 2.0 Auto	'TPM 1.2' - Restricts support to TPM 1.2 devices. 'TPM 2.0' - Restricts support to TPM 2.0 devices. 'Auto' - Default set to TPM 2.0 but if no such device is found TPM 1.2 devices are enumerated.
TPM State	Disabled Enabled	Enable or disable TPM chip. Note: The system may restart several times during POST to acquire the target state.
Pending operation	None Enable Take Ownership Disable Take Ownership TPM Clear	Select TPM chip operation. Note: The system may restart several times during POST to perform the selected operation.

10.4.7 RTC Wake Submenu

Feature	Options	Description
Wake System At Fixed Time	Disabled Wake from S5 only Wake from S4 and S5 Wake from S3, S4 and S5	Set system wake mode on alarm event. When enabled, system will wake from the specified Sx states on the hr::min::sec as specified.
Wake up hour		Specify the wake up hour. For example: Enter "3" for 3am and "15" for 3pm.
Wake up minute		Specify the wake up minute.
Wake up second		Specify the wake up second.

10.4.8 ACPI Submenu

Feature	Options	Description
Hibernation Support	Disabled Enabled	Enable or disable the system's ability to hibernate (OS S4 sleep state). Note: If you want to use this feature, please ensure that the operating system supports it.
ACPI Sleep State	Suspend Disabled S1 (CPU Stop Clock) S3 (Suspend to RAM) Both S1 and S3 available for OS to choose from	Select the state for ACPI system sleep/suspend.
Lock Legacy Resources	Disabled Enabled	Enable this feature to lock legacy resources.
S3 Video Repost	Disabled Enabled	Enable or disable video BIOS re-post on S3 resume. Note: Please check if your operating system requires this feature to be enabled.
ACPI Low Power S0 Idle	Disabled Enabled	Enable or disable ACPI low power S0 idle support.
Native PCI Express Support	Disabled Enabled	Enable or disable native operating system PCIe support.
Native ASPM	Disabled Enabled	'Enabled' - The operating system controls the ASPM support of the PCIe device. 'Disabled' - The BIOS controls the ASPM support of the PCIe device.
ACPI Debug	Disabled Enabled	Enable this feature to open a memory buffer for storing debug strings. Note: Use method ADBG to write strings to buffer.
ACPI 5.0 CPPC Support	Disabled Enabled	Enable this feature to expose Collaborative Processor Performance Control (CPPC) interfaces to the operating system. Disable this feature to expose legacy (non-CPPC) processor interfaces to the operating system.
ACPI 5.0 CPPC Platform SCI	Disabled Enabled	Select ACPI 5.0 platform generation of SCI on CPPC command completion: If enabled, the platform generates GPE/SCI. If disabled, the platform does not generate GPE/SCI and the operating system polls for command completion.

Feature	Options	Description
Automatic Critical Trip Point	Disabled Enabled	Enable this feature to set the critical trip point (temperature threshold) to the recommended value at which the ACPI aware operating system performs a critical shutdown automatically. Disable this feature to configure the critical trip point manually.
Critical Trip Point Value	71 °C, 79 °C, 87 °C, 95 °C, 103 °C, 106 °C , 111 °C, 119 °C, 127 °C	Select the temperature threshold at which the ACPI aware operating system performs a critical shutdown.
Lid Support	Disabled Enabled	If enabled, the COM Express LID# signal acts as ACPI lid.
Sleep Button Support	Disabled Enabled	If enabled, the COM Express SLEEP# signal acts as ACPI sleep button.

10.4.9 PCH-FW Submenu

Feature	Options	Description
ME FW Version	No option	Displays ME FW Version.
ME Firmware Mode	No option	Displays ME Firmware Mode.
ME Firmware Type	No option	Displays ME Firmware Type.
ME Firmware SKU	No option	Displays ME Firmware SKU.
PTT Capability / State	No option	Displays PTT Capability / State.
NFC Support	No option	Displays NFC Support.
MDES BIOS Status Code	Disabled Enabled	Enable or disable MDES BIOS status code.
ME Unconfig on RTC Clear State	Disabled Enabled	Enable or disable ME firmware un-configuration on RTC clear state.
fTPM Switch Selection	GPDMA Work-Around MSFT QFE Solution	Select the desired fTPM solution.
TPM Device Selection	dTPM 1.2 PTT	Select TPM device: 'PTT' - Enables PTT and disables dTPM in SkuMgr. 'dTPM 1.2' - Enables dTPM 1.2 and disables PTT in SkuMgr. Warning: If you enable PTT, dTPM will be disabled and all data saved on it will be lost. Likewise, if you enable dTPM, PTT will be disabled and all data saved on it will be lost.
► Firmware Update Configuration	Submenu	Opens the submenu to configure Management Engine technology parameters.
ME FW Image Re-Flash	Disabled Enabled	Enable or disable ME FW image re-flash function.

10.4.10 AMT Submenu

Feature	Options	Description
Intel AMT	Disabled Enabled	Enable or disable Intel® Active Management Technology (AMT) BIOS extension. Note: iAMT H/W is always enabled/just controls the BIOS extension execution. If you enabled this feature, please ensure the additional firmware is in the SPI device.
BIOS Hotkey Pressed	Disabled Enabled	OEMFlag Bit 1: Enable or disable BIOS hotkey press.
MEBx Selection Screen	Disabled Enabled	OEMFlag Bit 2: Enable or disable MEBx selection screen.
Hide Un-Configure ME Confirmation Prompt	Disabled Enabled	OEMFlag Bit 6: Hide un-configure ME without password confirmation prompt.
MEBx Debug Message Output	Disabled Enabled	OEMFlag Bit 14: Enable or disable MEBx debug message output.
Un-Configure ME	Disabled Enabled	OEMFlag Bit 15: Un-configure ME without password.
AMT Wait Timer	0 - 65535	Set timer to wait before sending ASF_GET_BOOT_OPTIONS.
Disable ME	Disabled Enabled	Enable or disable 'Disable ME'.
ASF	Disabled Enabled	Enable or disable Alert Specification Format (ASF).
Activate Remote Assistance Process	Disabled Enabled	Enable or disable trigger CIRA boot.
USB Configure	Disabled Enabled	Enable or disable USB configure function.
PET Progress	Disabled Enabled	Enable PET Events progress to receive PET events.
AMT CIRA Timeout	0 - 255	Select OEM defined timeout for MPS connection to establish: '0' - Default timeout value of 60 seconds. '255' - MEBX waits until the connection succeeds.
WatchDog	Disabled Enabled	Enable or disable watchdog timer
OS Timer	0 - 65535	Set the operating system watchdog timer.
BIOS Timer	0 - 65535	Set the BIOS watchdog timer.



The AMT submenu is only displayed if the feature is enabled.

10.4.11 Acoustic Management Submenu

Feature	Options	Description
Automatic Acoustic Management	Enabled Disabled	Enable or disable Automatic Acoustic Management (AAM) on optical or hard disk drives.
SATA Port 0 Disk drive name Acoustic Mode	Bypass Quiet Max Performance	Select Acoustic noise level and performance optimization of optical or hard disk drives: 'Bypass' - Uses drive's preset value. 'Quiet' - Reduces the drive speed. 'Max' - Maximizes the drive speed.
SATA Port 1 Disk drive name Acoustic Mode	Bypass Quiet Max Performance	Same as at SATA port 0.
SATA Port 2 Disk drive name Acoustic Mode	Bypass Quiet Max Performance	Same as at SATA port 0.
SATA Port 3 Disk drive name Acoustic Mode	Bypass Quiet Max Performance	Same as at SATA port 0.



Note

This menu displays only if the SATA ports optical or hard disk driver is detected.

10.4.12 SMART Settings Submenu

Feature	Options	Description
SMART Self Test	Disabled Enabled	Enable this feature to run SMART self test on all hard disk drives during POST. Note: The Self-Monitoring, Analysis and Reporting Technology (SMART) predicts hard disk drives degradation and/or faults.

10.4.13 Super I/O Submenu

Feature	Options	Description
Super IO Chip	No options	Displays the Super IO Chip type which is Windbond W83627
SIO Clock	24MHz 48MHz	Set Super I/O base clock.
► Serial Port 0	Submenu	
Serial Port	Disabled Enabled	Enable or disable serial port (COM).
Device Settings	No option	Displays the currently used settings.
Change Settings	Auto IO=3F8h; IRQ=4 IO=3F8h; IRQ=3,4,5,7,9,10,11,12 IO=2F8h; IRQ=3,4,5,7,9,10,11,12 IO=3E8h; IRQ=3,4,5,7,9,10,11,12 IO=2E8h; IRQ=3,4,5,7,9,10,11,12	Select the optimal setting for Super IO device.
► Serial Port 1	Submenu	
Serial Port	Disabled Enabled	Enable or disable serial port (COM).
Device Settings	No option	Displays the currently used settings.
Change Settings	Auto IO=2F8h; IRQ=3 IO=3F8h; IRQ=3,4,5,7,9,10,11,12 IO=2F8h; IRQ=3,4,5,7,9,10,11,12 IO=3E8h; IRQ=3,4,5,7,9,10,11,12 IO=2E8h; IRQ=3,4,5,7,9,10,11,12	Select the optimal setting for Super IO device
Device Mode	Standard Serial Port Mode IrDA Active pulse 1.6 uS IrDA Active pulse 3/16 bit time ASKIR Mode	Select the serial port mode.
► Parallel Port	Submenu	
Parallel Port	Disabled Enabled	Enable or disable parallel port (LPT/LPTE).
Device Settings	No option	Displays the currently used settings.
Change Settings	Auto IO=378h; IRQ=5; IO=378h; IRQ=5,6,7,9,10,11,12; IO=278h; IRQ=5,6,7,9,10,11,12; IO=3BCh; IRQ=5,6,7,9,10,11,12;	Select the optimal setting for Super IO device.

Feature	Options	Description
Device Mode	STD Printer Mode SPP Mode EPP-1.9 and SPP Mode EPP-1.7 and SPP Mode ECP Mode ECP and EPP 1.9 Mode ECP and EPP 1.7 Mode	Select the mode for the parallel port.



This setup menu is available only if an external Winbond W83627 Super I/O has been implemented on the carrier board.

10.4.14 Serial Port Console Redirection Submenu

Feature	Options	Description
COM0 Console Redirection	Disabled Enabled	Enable or disable serial port 0 console redirection.
► Console Redirection Settings	Submenu	Opens the console redirection configuration submenu.
COM1 Console Redirection	Disabled Enabled	Enable or disable serial port 1 console redirection.
► Console Redirection Settings	Submenu	Opens console redirection configuration submenu.
► Legacy Console Redirection Settings	Submenu	Opens legacy console redirection submenu.
Legacy Serial Redirection Port	COM0 COM1	Select a COM port to display redirection of legacy operating system and legacy OPROM messages.
Serial Port for Out-of-Band Management/ Windows Emergency Management Services (EMS) Console Redirection	Disabled Enabled	Enable or disable serial port for Out-of-Band Management/ Windows Emergency Management Services (EMS) Console Redirection
► Console Redirection Settings	Submenu	Opens the console redirection configuration sub menu.



The Serial Port Console Redirection can be enabled (functional) only if an external Super I/O offering UARTs has been implemented on the carrier board

10.4.14.1 Console Redirection Settings Submenu

Feature	Options	Description
Terminal Type	VT100 VT100+ VT-UTF8 ANSI	Set terminal type.
Baudrate	9600 19200 38400 57600 115200	Set the baud rate.
Data Bits	7 8	Set the number of data bits.
Parity	None Even Odd Mark Space	Set the parity.
Stop Bits	1 2	Set the number of stop bits.
Flow Control	None Hardware RTS/CTS	Set the flow control.
VT-UTF8 Combo Key Support	Disabled Enabled	Enable VT-UTF8 combination key support for ANSI/VT100 terminals.
Recorder Mode	Disabled Enabled	If the recorder mode is enabled, only text output will be sent over the terminal. Note: This feature is helpful to capture and record terminal data.
Resolution 100x31	Disabled Enabled	Enable or disable extended terminal resolution.
Legacy OS Redirection Resolution	80x24 80x25	Set number of rows and columns for the legacy operating system redirection.
Putty KeyPad	VT100 LINUX XTERMR6 SCO ESCN VT400	Set function key and keypad for Putty.
Redirection After BIOS POST	Enabled Disabled	Enable this feature to continue serial redirection after POST.



Note

The 'Serial Port Console Redirection' submenu in section 10.4.13 has three console redirection submenus - 'COM 0', 'COM 1' and 'Out of Band Management/Windows EMS console redirection' submenus. Section 10.4.13.1 shows the console redirection submenu for 'COM 0' and 'COM 1'. The 'Out of Band Management/Windows EMS console redirection' submenu does not have all the features listed above. It however contains an 'Out-of-Band Management Port Selection' feature which is not listed above.

10.4.15 SATA Submenu

Feature	Options	Description
SATA Controller(s)	Enabled Disabled	Enable or disable the onboard SATA controller(s).
SATA Mode Selection	AHCI RAID	Select the SATA controller mode. Note: Please ensure RAID is supported on the chipset before selecting it.
PCIe NAND Configuration	Disabled Enabled	Enable or disable PCIe NAND remapping. Note: This feature is only displayed in RAID SATA mode.
PCIe NAND Port Selection	Auto Port 1 Port 5 Port 6	Select PCIe NAND port. Note: This feature is only displayed in RAID SATA mode.
PCIe NAND Config Access Lockdown	Disabled Enabled	Enable or disable PCIe NAND remapping configuration access index/data lockdown. Note: This feature is only displayed in RAID SATA mode.
SATA Test Mode	Enabled Disabled	Enable this feature during verification measurements only.
Aggressive LPM Support	Enabled Disabled	Enable this feature for PCH to aggressively enter link power state.
SATA Controller Speed	Default Gen1 Gen2 Gen3	'Default' - Uses maximum speed supported by the chipset. 'Gen1' - 1.5 Gbit/s. 'Gen2' - 3 Gbit/s. 'Gen3' - 6 Gbit/s.
► Software Feature Mask Configuration	Submenu	RAID option ROM and Intel® Rapid Storage Technology driver will refer to this submenu to enable or disable the storage features.
Alternate ID	Enabled Disabled	Enable this feature to report alternate device ID. Note: This feature is only displayed in 'RAID SATA' mode.
Serial ATA Port 0, 1	No option	Displays the name of the connected Hard Disk or DVDROM when the port is enabled. Nothing is displayed if the port is disabled or the port is enabled but without a connected device.
Software Preserve	No option	Displays whether the detected drive supports software settings preservation.
SATA Port	Disabled Enabled	Enable or disable the relevant SATA port. Note: This feature is not available in native IDE mode.

Feature	Options	Description
Hot Plug	Disabled Enabled	Select hot plug support for relevant SATA port. Note: This feature is not available in native IDE mode.
External SATA	Disabled Enabled	Enable or disable external SATA support on relevant SATA port. Note: This feature is not available in native IDE mode.
SATA Device Type	Hard Disk Drive Solid State Drive	Select whether the relevant SATA port is connected to SSD or HDD. Note: This feature is not available in native IDE mode.
Spin Up Device	Disabled Enabled	If enabled, the controller runs an initialization sequence during startup at the relevant SATA port. Note: Please enable this feature if your HDD or SSD requires it. Not available in native IDE mode.

10.4.15.1 Software Feature Mask Configuration Submenu

Feature	Options	Description
RAID0	Disabled Enabled	Enable or disable RAID0 feature.
RAID1	Disabled Enabled	Enable or disable RAID1 feature.
RAID10	Disabled Enabled	Enable or disable RAID10 feature.
RAID5	Disabled Enabled	Enable or disable RAID5 feature.
Intel Rapid Recovery Technology	Disabled Enabled	Enable or disable Intel® Rapid Recovery Technology.
Option ROM UI and Banner	Disabled Enabled	If enabled, the option ROM user interface is shown. Otherwise, no option ROM banner or information will be displayed if all disks and RAID volumes are normal.
HDD Unlock	Disabled Enabled	If enabled, indicates that the HDD password unlock in the operating system is enabled.
LED Locate	Disabled Enabled	Enable or disable LED locate.
IRRT Only on eSATA	Disabled Enabled	If enabled, only Intel® Rapid Recovery Technology (IRRT) volumes can span internal and external SATA (eSATA) drives. If disabled, any RAID volume can span internal and eSATA drives.
Intel Smart Response Technology	Disabled Enabled	Enable or disable Intel Smart Response Technology.
Option ROM UI Delay	2 Seconds 4 Seconds 6 Seconds 8 Seconds	If enabled, this feature indicates the delay of the option ROM user interface splash screen in a normal status.

10.4.16 PCI & PCI Express Submenu

Feature	Options	Description
PCI Settings		
PCI Latency Timer	32 , 64, 96, 128, 160, 192, 224, 248 PCI Bus Clocks	Select value to be programmed into PCI latency timer register.
PCI-X Latency Timer	32, 64 , 96, 128, 160, 192, 224, 248 PCI Bus Clocks	Select value to be programmed into PCI latency timer register.
VGA Palette Snoop	Disabled Enabled	Enable or disable VGA palette registers snooping.
PERR# Generation	Disabled Enabled	Enable or disable PCI device to generate PERR#.
SERR# Generation	Disabled Enabled	Enable or disable PCI device to generate SERR#.
Above 4G Decoding	Disabled Enabled	Enable this feature to decode 64-bit capable devices in Above 4G address space. Note: Please ensure the system supports 64-bit PCI decoding if you want to enable this feature.
Don't Reset VC-TC Mapping	Disabled Enabled	If system the has virtual channels the software can reset traffic class mapping through virtual channels to its default state. Note: Enabling this option will not modify VC resources.
Generate EXCD0/1_PERST#	Disabled 1ms, 5ms, 10ms , 50ms, 100ms, 150ms, 200ms, 250ms	The COM Express EXCD0_PERST# and EXCD1_PERST# pins are driven low during POST for the set time.
► PCI Hot-Plug Settings	Submenu	Opens the PCI Express Hot-Plug and standard HP controller settings.
► PIRQ Routing & IRQ Reservation	Submenu	Opens the manual PIRQ routing and interrupt reservation submenu for legacy devices.
PCIE Root Port Function Swapping	Disabled Enabled	Enable or disable PCI Express root port function swapping. Its value is enabled if PCIe NAND Configuration is set to "Enabled".
Subtractive Decode	Disabled Enabled	Enable or disable PCIe subtractive decode.
► PCI Express Port 0	Submenu	Opens the PCI Express Port submenu.
► PCI Express Port 1	Submenu	Opens the PCI Express Port submenu.
► PCI Express Port 2	Submenu	Opens the PCI Express Port submenu.
► PCI Express Port 3	Submenu	Opens the PCI Express Port submenu.

10.4.16.1 PCI Hot-Plug Settings Submenu

Feature	Options	Description
BIOS Hot-Plug Support	Disabled Enabled	Enable this feature to support hot plug in BIOS. Note: Use this feature if the operating system does not natively support PCI Express and SHPC hot plug.
PCI Buses Padding	Disabled 1, 2, 3, 4, 5	Select Padd PCI buses behind the bridge for hot plug.
I/O Resources Padding	Disabled 4K, 8K, 16K, 32K	Select Padd PCI I/O resources behind the bridge for hot plug.
MMIO 32 bit Resources Padding	Disabled 1M, 2M, 4M, 8M, 16M, 32M, 64M, 128M	Select Padd PCI MMIO 32 bit resources behind the bridge for hot plug
PFMMIO 32 bit Resources Padding	Disabled 1M, 2M, 4M, 8M, 16M, 32M, 64M, 128M	Select Padd PCI MMIO 32 bit prefetchable resources behind the bridge for hot plug

10.4.16.2 PIRQ Routing & IRQ Reservation Submenu

Feature	Options	Description
PIRQA	Auto IRQ3, IRQ4, IRQ5, IRQ6, IRQ10 IRQ11, IRQ14, IRQ15	Set the interrupt for PIRQ. Note: These settings will only be effective while operating in PIC (non-IOAPIC) interrupt mode. Please refer to the board's resource list for a detailed list of devices connected to the respective IRQ.
PIRQB	Same as 'PIRQA'	Same as 'PIRQA'.
PIRQC	Same as 'PIRQA'	Same as 'PIRQA'.
PIRQD	Same as 'PIRQA'	Same as 'PIRQA'.
PIRQE	Same as 'PIRQA'	Same as 'PIRQA'.
PIRQF	Same as 'PIRQA'	Same as 'PIRQA'.
PIRQG	Same as 'PIRQA'	Same as 'PIRQA'.
PIRQH	Same as 'PIRQA'	Same as 'PIRQA'.
Reserve Legacy Interrupt 1	None IRQ3, IRQ4, IRQ5, IRQ6, IRQ10, IRQ11, IRQ14, IRQ15	Use this feature to reserve an interrupt for a legacy bus device. Note: The selected interrupt will not be assigned to any PCI/PCIe device.
Reserve Legacy Interrupt 2	Same as 'Reserve Legacy Interrupt 1'	Same as 'Reserve Legacy Interrupt 1'.

10.4.16.3 PCI Express Port Submenu

Feature	Options	Description
PCI Express Port x	Disabled Enabled	Enable this feature if the port should be enabled without a connected PCIe device.
ASPM	Disabled L0s L1 L0sL1 Auto	Set PCIe Active State Power Management (ASPM) settings.
L1 Substates	Disabled L1.1 L1.2 L1.1 & L1.2	Set PCIe L1 substates settings.
URR	Disabled Enabled	Enable or disable PCIe Unsupported Request Reporting (URR).
FER	Disabled Enabled	Enable or disable PCIe device Fatal Error Reporting (FER).
NFER	Disabled Enabled	Enable or disable PCIe device Non-Fatal Error Reporting (NFER).
CER	Disabled Enabled	Enable or disable PCIe device (Correctable Error Reporting).
CTO	Disabled Enabled	Enable or disable PCIe Completion Timeout (CTO) timer.
SEFE	Disabled Enabled	Enable or disable Root PCIe System Error on Fatal Error (SEFE).
SENEFE	Disabled Enabled	Enable or disable Root PCIe System Error on Non-Fatal Error (SENEF).
SECE	Disabled Enabled	Enable or disable Root PCI Express System Error on Correctable Error (SECE).
PME SCI	Disabled Enabled	Enable or disable PCIe Power Management Event (PME) SCI.
Always Enable Port	Disabled Enabled	Enable this feature to enable the internal PCIe interface even if no device is connected to the port.
PCIe Speed	Auto Gen1	Select maximum speed of the PCIe port: 'Auto' - Gen1 or Gen2 'Gen1' - 2.5GT/s Note: Some Gen2 devices start up in Gen1 mode and their operating system driver sets them to Gen2 mode. Some non-compliant PCIe devices only function properly if Gen1 is selected.
Detect Non-compliant Device	Disabled Enabled	Enable this feature to detect some non-compliant PCIe device(s). Note: POST time will be longer if this feature is enabled.

Feature	Options	Description
Extra Bus Reserved	0 - 7	Select extra bus reserved for bridges behind this root bridge.
Reserved Memory	1 - 20	Select reserved memory range for this root bridge. Default: 10
Prefetchable Memory	1 - 20	Select prefetchable memory range for this root bridge. Default: 10
Reserved I/O	0 - 20	Select reserved I/O range for this root bridge. Default: 4
PCIe LTR	Disabled Enabled	Enable or disable PCIe Latency Tolerance Reporting (LTR).
PCIe LTR Lock	Disabled Enabled	Enable or disable PCIe LTR configuration lock.
Snoop Latency Override	Disabled Manual Auto	Set snoop latency override for PCH PCIe.
Snoop Latency Multiplier	1 ns 32 ns 1024 ns 32768 ns 1048576 ns 33554432 ns	Set snoop latency multiplier for PCH PCIe.
Snoop Latency Value	0 - 252	Select snoop latency value for PCH PCIe. Default: 60
No-Snoop Latency Override	Disabled Manual Auto	Set no-snoop latency override for PCH PCIe.
No-Snoop Latency Multiplier	1 ns 32 ns 1024 ns 32768 ns 1048576 ns 33554432 ns	Select no-snoop latency multiplier for PCH PCIe.
No-Snoop Latency Value	0 - 255	Select no-snoop latency value for PCH PCIe. Default: 60

10.4.17 UEFI Network Stack Submenu

Feature	Options	Description
UEFI Network Stack	Disabled Enabled	Enable or disable the UEFI network stack.
IPv4 PXE Support	Disabled Enabled	If disabled, IPv4 PXE boot option will not be created.
IPv6 PXE Support	Disabled Enabled	If disabled, IPv6 PXE boot option will not be created.
PXE Boot Wait Time	0 - 5	Select wait time to press ESC and abort PXE Boot.
Media Detect Count	1 - 5	Select number of times to check for the presence of media.

10.4.18 CSM & Option ROM Control Submenu

Feature	Options	Description
CSM Support	Enabled Disabled	Enable or disable execution of the CSM module. Note: Only disable this feature for pure UEFI operating system support.
Gate A20 Active	Upon Request Always	Configure the Gate A20 behavior: 'Upon Request' - Allows BIOS services to disable Gate A20. 'Always' - Does not allow to disable Gate A20 Note: This feature is useful when runtime code above 1MB is executed.
Option ROM Messages	Force BIOS Keep Current	Set display mode for option ROMs.
Boot Option Filter	UEFI and Legacy Legacy Only UEFI Only	Select which devices / boot loaders the system should boot to.
PXE Option ROM Launch Policy	Do Not Launch UEFI ROM Only Legacy ROM Only	Select the execution of UEFI and legacy PXE option ROMs.
Storage Option ROM Launch Policy	Do Not Launch UEFI ROM Only Legacy ROM Only	Select the execution of UEFI and legacy mass storage device option ROMs.
Video Option ROM Launch Policy	Do Not Launch UEFI ROM Only Legacy ROM Only	Select the execution of UEFI and legacy video option ROMs.
Other Option ROM Launch Policy	Do Not Launch UEFI ROM Only Legacy ROM Only	Select the execution of option ROMs for PCI / PCI Express devices other than network, mass storage or video.

10.4.19 USB Submenu

Feature	Options	Description
USB Controllers	No option	Displays the number of enabled EHCI (USB2.0) and xHCI (USB3.0) controllers.
USB Devices	No option	Displays the detected USB devices.
xHCI Mode	Smart Auto Auto Enabled Disabled Manual	Select mode for all USB ports (0-3): 'Enabled' - USB ports will function in USB3.0 mode but require driver on the operating system. USB ports will not function in pre-operating system time if USB3.0 support in BIOS is disabled (see the USB3.0 support in BIOS item). 'Disabled' - USB ports will function in USB2.0 mode only and routed to the EHCI1 controller. 'Auto' - USB ports will initially function in USB2.0 mode but the operating system driver can switch them to USB 3.0. 'Smart Auto' - Identical to 'Auto', except the BIOS will take over the operating system driver setting after each restart.
EHCI (Ports USB0-7)	Disabled Enabled	Enable or disable EHCI (USB 2.0) controller. Note: One EHCI controller must be always enabled.
USB2.0 Pins Routing	Route Per-Pin Route all Pins to EHCI Route all Pins to xHCI	Route the USB2.0 pins to EHCI or xHCI controller.
USB2.0 Port 0 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 1 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 2 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 3 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 4 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 5 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 6 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB2.0 Port 7 Pins	Route to EHCI Route to xHCI	Route the respective USB2.0 port to EHCI or xHCI controller.
USB3.0 Pins	Select Per-Pin Disable all Pins Enable all Pins	Enable or disable xHCI SuperSpeed support.
USB3.0 Port 0 Pins	Disabled Enabled	Enable or disable the xHCI SuperSpeed support on respective USB port.
USB3.0 Port 1 Pins	Disabled Enabled	Enable or disable the xHCI SuperSpeed support on respective USB port.

Feature	Options	Description
Overcurrent Protection	Disabled Enabled	Enable or disable overcurrent protection on all USB ports.
► USB Ports Per-Port Disable Control	Submenu	Opens the submenu to individually disable USB ports
Legacy USB Support	Enabled Disabled Auto	Set legacy USB support: 'Enable' - Enables legacy USB support. 'Disable' - Keeps USB devices available only for EFI applications and BIOS setup. 'Auto' - Disables legacy support if no USB devices are connected.
External USB Controllers Support	Disabled Enabled	Enable or disable BIOS support for external USB controllers.
xHCI Hand-off	Disabled Enabled	This feature is a workaround for operating systems without xHCI hand-off support. Note: The xHCI ownership change should be claimed by xHCI operating system driver.
EHCI Hand-off	Disabled Enabled	This feature is a workaround for operating systems without EHCI hand-off support. Note: The EHCI ownership change should be claimed by EHCI operating system driver.
USB Mass Storage Driver Support	Disabled Enabled	Enable or disable USB mass storage driver support.
USB Transfer Timeout	1 sec 5 sec 10 sec 20 sec	Set the timeout value for control, bulk, and interrupt transfers.
Device Reset Timeout	10 sec 20 sec 30 sec 40 sec	Set USB mass storage device Start Unit command timeout.
Device Power -Up Delay Selection	Auto Manual	Select whether the delay time for a USB device to report itself properly to the host controller should be set automatically or manually. If set to 'Auto', the delay is 100ms for a root port or the value is derived from the hub descriptor for a hub port.
Device Power -Up Delay Value	1 - 40	Set power-up delay value in seconds. Default: 5
USB Mass Storage Device Name (Auto detected USB mass storage devices are listed here dynamically)	Auto Floppy Forced FDD Hard Disk CD-ROM	Every USB mass storage device that is enumerated by the BIOS will have an emulation type setup option. This option specifies the type of emulation the BIOS has to provide for the device: ¹ 'AUTO' - Lets the BIOS auto detect the current formatted media. 'Floppy' - Emulates the device as a floppy drive. 'Forced FDD' - Allows a HDD to be connected as a floppy image. ² 'Hard Disk' - Allows the hard disk to be emulated as a HDD. 'CD-ROM' - Assumes the CD-ROM is formatted as a bootable media. ³

Notes:

¹The device's formatted type and the emulation type provided by the BIOS must match for the device to boot properly.

²The drive must be formatted with FAT12, FAT16 or FAT32.

³As specified by the 'El Torito' Format Specification

10.4.19.1 USB Ports Per-Port Disable Control Submenu

Feature	Options	Description
USB Ports Per-Port Disable Control	Disabled Enabled	Set enabled to individually disable USB ports.
USB Port 0	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 1	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 2	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 3	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 4	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 5	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 6	Disabled Enabled	Enable or disable the respective USB2.0 port.
USB Port 7	Disabled Enabled	Enable or disable the respective USB2.0 port.

10.4.20 GPIO Configuration Submenu

Feature	Options	Description
Current GPO Configuration		
GPO 0 State	Low High	Set the state for GPO 0.
GPO 1 State	Low High	Set the state for GPO 1.
GPO 2 State	Low High	Set the state for GPO 2.
GPO 3 State	Low High	Set the state for GPO 3.
Current GPI Configuration	xxh	Each bit represents the state of the corresponding GPI.

10.4.21 Diagnostics Settings Submenu

Feature	Options	Description
POST Code Redirection Settings		
Relay Interface	Disabled I2C SMBus BC Diagnostics Console	Select the relay interface to which the POST code will be redirected.
Primary Port Addr. Lowbyte (Dec)	0-255 (128)	Set the address for the primary debug port. The usual address value is 0x80 (i.e. 128 dec lowbyte and 0 highbyte). However, any multiple of 8 is valid for a primary debug port address.
Primary Port Addr. Highbyte (Dec)	0-255 (0)	Set the address for the primary debug port. The usual address value is 0x80 (i.e. 128 dec lowbyte and 0 highbyte). However, any multiple of 8 is valid for a primary debug port address.
Relay Device Address (Dec)	0-255 (226)	Specify the I2C/SMBus device address of e.g. a 7-segment LCD for POST code display. The factory settings for the SparkFun device is 0xE2(226). However, any even device address can be specified.
BC Diagnostics Console Settings		
BC Diagnostics Console Interface	Disabled BC AUX Port BC COM Port 0 BC COM Port 1	Select the interface to be used for the congatec Board Controller Diagnostic Console output or disable the diagnostic output.
Parity Bit	No Parity Even Parity Odd Parity	Choose the parity bits for the BC Diagnostic Console interface.
Stop Bits	1 Stop Bit 2 Stop Bits	Choose the stop bits for the BC Diagnostic Console interface.
Data Bits	5 Data Bits 6 Data Bits 7 Data Bits 8 Data Bits	Choose the data bits for the BC Diagnostic Console interface.
Baudrate	1200 Baud 2400 Baud 4800 Baud 9600 Baud 19200 Baud 38400 Baud	Choose the baudrate for the BC Diagnostic Console interface.

10.4.22 PC Speaker Configuration Submenu

Feature	Options	Description
Debug Beeps	Disabled Enabled	Enable or disable general debug/status beep generation.
Input Device Debug Beeps	Disabled Enabled	Enable or disable input device debug beeps
Output Device Debug Beeps	Disabled Enabled	Enable or disable output device debug beeps
USB Driver Beeps	Disabled Enabled	Enable or disable USB driver beeps.

10.4.23 Intel® Ethernet Connection I218-LM Submenu

Feature	Options	Description
► NIC Configuration	Submenu	Opens the NIC Configuration submenu.
Blink LEDs	0 - 15	Set the number of seconds for the Ethernet LEDs to blink.
UEFI Driver	No option	Displays the UEFI Driver version.
Adapter PBA	No option	Displays the Adapter PBA.
Chip Type	No option	Displays the type of the Chip in which the Ethernet controller is integrated.
PCI Device ID	No option	Displays the PCI Device ID of the Ethernet controller.
PCI Address	No option	Displays the PCI Bus:Device:Function number of the Ethernet controller.
Link Status	No option	Displays the Link Status.
MAC Address	No option	Displays the MAC Address.



Note

The MAC address is also displayed in the submenu title.

10.4.23.1 NIC Configuration Submenu

Feature	Options	Description
Link Speed	Auto Negotiated 10 Mbps Half 10 Mbps Full 100 Mbps Half 100 Mbps Full	Select the port speed for the selected boot protocol.
Wake On LAN	Disabled Enabled	Enable this feature for the server to power on after receiving an in-band magic packet.

10.4.24 Intel® Rapid Storage Technology Submenu

Feature	Options	Description
Intel® Rapid Start Technology	Disabled Enabled	Enable or disable Intel® Rapid Start Technology.
No valid partition	No option	Warning message when the Intel® Rapid Start Technology is not completely set up.
Entry on S3 RTC Wake	Disabled Enabled	Enable or disable rapid Start invocation upon S3 RTC wake.
Entry After	0 - 120	RTC wake timer at S3 entry. Default: 10
Active Page Threshold Support	Disabled Enabled	Enable this feature to support RST with small partition.
Active Memory Threshold	0 - 65535	Enable this feature to try supporting RST if the partition size is larger (in MB) than the active page threshold size. '0' sets this feature to automatic mode.
Hybrid Hard Disk Support	Disabled Enabled	Enable or disable hybrid hard disk support.
Rapid Start Display Save/Restore	Disabled Enabled	Enable or disable rapid start display save/restore.
Rapid Start Display Type	BIOS Save/Restore Desktop Save/Restore	Set rapid start display type.

10.5 Chipset Setup

Select the Chipset tab from the setup menu to enter the Chipset BIOS Setup screen. The menu is used for setting chipset features.

Main	Advanced	Chipset	Boot	Security	Save & Exit
<hr/>					
Processor (Integrated Components)					
<hr/>					
Platform Controller Hub (PCH)					

10.5.1 Processor (Integrated Components) Submenu

Feature	Options	Description
Processor Codename	No option	Displays the Processor codename.
VT-d Capability	No option	Displays whether the VT-d is supported by the processor.
VT-d	Disabled Enabled	Enable or disable VT-d support. Note: This feature is only displayed if the processor supports VT-d capability.
Thermal Device (B0:D4:F0)	Enabled Disabled	Enable or disable thermal device.
Audio Device (B0:D3:F0)	Enabled Disabled	Enable or disable the integrated audio device in the processor.
Audio Vanilla Mode	Enabled Disabled	Enable or disable SA Audio Vanilla mode.
NB CRID	Disabled Enabled	Enable or disable northbridge compatible revision ID support.
Above 4GB MMIO BIOS Assignment	Enabled Disabled	Enable or disable Above 4GB memory-mapped I/O BIOS assignment.
BDAT ACPI Table Support	Enabled Disabled	Enable this feature to support the BDAT ACPI table.
Graphics Turbo IMON Current	14 - 31	Select graphics turbo IMON current value.
► DMI/OPI Configuration	Submenu	Opens the submenu to control various DMI functions. DMI link is the main, but exclusively internal bus between the processor and Platform Controller Hub (PCH).
► Memory Configuration	Submenu	Opens the submenu for memory configuration parameters.
► Memory Thermal Configuration	Submenu	Opens the submenu for memory thermal configuration options.
► GT - Power Management Control	Submenu	Opens the submenu for the Processor Graphics (GT) controller power management control options.

10.5.1.1 DMI/OPI Configuration Submenu

Feature	Options	Description
DMI	No option	Displays the DMI bus characteristics.
DMI Vc1 Control	Enabled Disabled	Enable or disable DMI Vc1.
DMI Vcp Control	Enabled Disabled	Enable or disable DMI Vcp.
DMI Vcm Control	Enabled Disabled	Enable or disable DMI Vcm.
DMI Link ASPM Processor Side	Disabled L0s L1 L0sL1	Set Active State Power Management (ASPM) of the DMI link on the processor side. The DMI link is the main bus between the Processor and Platform Controller Hub (PCH).
DMI Extended Synch Control	Enabled Disabled	Enable or disable DMI extended synchronization.
DMI Gen 2	Enabled Disabled	Enable or disable DMI Gen2.
DMI De-emphasis Control	-6 dB -3.5 dB	Set the de-emphasis control on DMI.
DMI IOT	Enabled Disabled	Enable or disable DMI IOT.

10.5.1.2 Memory Configuration Submenu

Feature	Options	Description
Memory Frequency	No option	Displays the memory frequency.
Total Memory	No option	Displays the total amount of installed memory.
Memory Voltage	No option	Displays the memory voltage.
DIMM#0 (Bottom)	No option	Displays bottom memory socket DIMM information.
DIMM#2 (Top)	No option	Displays top memory socket DIMM information.
CAS Latency (tCL)	No option	Displays the CAS Latency (tCL).
CAS to RAS (tRCDmin)	No option	Displays the CAS to RAS (tRCDmin).
Row Precharge (tRPmin)	No option	Displays the Row Precharge (tRPmin).
Active to Precharge (tRASmin)	No option	Displays the Active to Precharge (tRASmin).

Feature	Options	Description
DIMM Profile	Default DIMM Profile Custom Profile XMP Profile 1 XMP Profile 2	Select the DIMM timing profile. CAUTION: XMP profiles do not work on current modules and MUST not be selected. For congatec internal debugging only. DO NOT CHANGE.
► Custom Profile Control	Submenu	Opens submenu to select custom DIMM profiles. CAUTION: XMP profiles do not work on current modules and MUST not be selected. For congatec internal debugging only. DO NOT CHANGE.
Memory Frequency Limiter	Auto 1067, 1333, 1600, 1867, 2133, 2400, 2667, 2933, 3200	Set the maximum memory frequency selections in MHz. Note: This feature is hidden if DIMM profile is set to 'Custom Profile'.
Max TOLUD	Dynamic 1 GB, 1.25 GB, 1.5 GB, 1.75 GB, 2 GB, 2.25 GB, 2.5 GB, 2.75 GB, 3 GB, 3.25 GB	Select the maximum Top of Low Usable DRAM (TOLUD). Note: The dynamic assignment will adjust the TOLUD based on the largest MMIO length of the installed graphic controller.
Enh Interleave Support	Disabled Enabled	Enable or disable enhanced interleave support.
RI Support	Disabled Enabled	Enable or disable rank interleave support. Note: RI and HORI cannot be enabled at the same time.
DLL Weak Lock Support	Disabled Enabled	Enable or disable DLL weak lock support.
Enable RH Prevention	Disabled Enabled	Enable this feature to actively prevent Row Hammer (RH).
Row Hammer Solution	Hardware RHP 2x Refresh	Type of method used to prevent RH.
RH Activation Probability	1/2^14 1/2^13 1/2^12 1/2^11	Adjust MC for hardware Row Hammer Probability (RHP).
Enable RH Keep Seeds	Disabled Enabled	Enable this feature to keep LFSR seeds on warm boots for hardware RHP.
Mc Lock	Disabled Enabled	Enable this feature to lock MC registers.
Ch Hash Support	Disabled Enabled Auto	Enable or disable channel hash support. Note: This feature only in memory interleaved mode.
Ch Hash Mask	1 - 16383	Set the bit(s) to be included in the XOR function. Default: 12494 Note: Bit mask corresponds to bits [19:6].

Feature	Options	Description
Ch Hash Interleaved Bit	BIT06 BIT07 BIT08 BIT09	Select the bit for channel interleaved mode. Note: BIT07 interleaves the channels at a 2 cacheline granularity, BIT08 at 4 and BIT09 at 8.
NMode Support	Auto 1N Mode 2N Mode	Select NMode support.
Memory Scrambler	Enabled Disabled	Enable or disable memory scrambler support.
RMT Crosser Support	Enabled Disabled	Enable or disable RMT crosser support.
MRC Fast Boot	Enabled Disabled	Enable or disable MRC fast boot.
DIMM Exit Mode	Auto Slow Exit Fast Exit	DIMM Exit Mode control
Power Down Mode	No Power Down APD PPD PPD-DLLoff Auto	Select power down mode: 'PPD' - Sets DIMM exit mode for fast exit. 'Auto' - Sets DIMM exit mode for slow exit.
Memory Remap	Enabled Disabled	Enable or disable memory remap Above 4G.
GDXC Support	Enabled Disabled	Enable or disable GDXC support.

10.5.1.3 Memory Thermal Configuration

Feature	Options	Description
► Memory Power and Thermal Throttling	Submenu	Opens the submenu for memory power and thermal throttling options.
DDR PowerDown and Idle Counter	BIOS PCODE	'BIOS' - BIOS controls DDR CKE mode and idle timer value. 'PCODE' - PCODE manages the modes.
Refresh 2x Support	Disabled Enabled for WARM or HOT Enabled HOT Only	Select refresh 2x support.
LPDDR Thermal Sensor	Disabled Enabled	If this feature is enabled, MC uses MR4 to read LPDDR thermal sensors.
SelfRefresh Enable	Disabled Enabled	Enable or disable SelfRefresh.

Feature	Options	Description
SelfRefresh IdleTimer	512 - 65535	Select range for DLCK800s.
Throttler CKEMin Defeature	Disabled Enabled	Enable or disable Throttler CKEMin
Throttler CKEMin Timer	0 - 255	Set timer value for CKEMin. Default: 48
Memory Thermal Management	Disabled Enabled	Enable or disable memory thermal management.
Virtual Temperature Sensor (VTS)	Disabled Enabled	Enable or disable Virtual Temperature Sensor (VTS).

10.5.1.4 GT - Power Management Control Submenu

Feature	Options	Description
Processor Graphics Controller Info	No option	Displays the processor graphics controller info.
RC6 (Render Standby)	Disabled Enabled	Enable or disable render standby support.
GT Overclocking Support	Disabled Enabled	Enable or disable GT overclocking support.
GT Overclocking Frequency	0 - 255	Set RP0 overclocking frequency (MLCClk) in multiples of 50 MHz. Default: 22
GT Overclocking Voltage	0 - 255	Add voltage to the original RP0 voltage in is 1/256 volt steps.

10.5.2 Platform Controller Hub (PCH) Submenu

Feature	Options	Description
Intel PCH SKU Name	No option	Displays the SKU Name of the PCH.
PCI Express Clock Gating	Disabled Enabled	Enable or disable PCIe clock gating for each root port.
DMI Link ASPM PCH Side	Disabled Enabled	Enable or disable Active State Power Management (ASPM) of DMI link PCH side. DMI link is the main bus between the Processor and Platform Controller Hub (PCH).
DMI Link Extended Synch Control	Disabled Enabled	Disable or enable extended synch on PCH side of the DMI link.
Isolate SMBus Segments	Never During POST Always	Set to cut off the off-board SMBus segment. Note: This feature is a workaround for external SMBus devices that do not conform to specification.
PCIe-USB Glitch W/A	Disabled Enabled	Enable or disable PCIe-USB glitch W/A for bad USB device(s) connected behind PCIe/PEG port.
USB Precondition	Disabled Enabled	Enable or disable precondition work on USB host controller and root ports for faster enumeration.
BTCG	Enabled Disabled	Enable or disable USB related trunk clock gating.
HDA Controller	Disabled Enabled Auto	Select activation of the HDA controller device: 'Disabled' - Disables HDA controller unconditionally. 'Enabled' - Enables HDA controller unconditionally. 'Auto' - Enables HDA controller if codec present, disables otherwise.
HDA PME	Disabled Enabled	Enable or disable the power management capability of the audio controller.
PCH LAN Controller	Enabled Disabled	Enable or disable the onboard, PCH integrated Ethernet controller.
LAN PHY Drives GPIO27	Disabled Enabled	'Enabled' - Uses LAN Phy drives GPIO27. 'Disabled' - Uses platform drives GPIO27.
Wake on LAN	Enabled Disabled	Enable or disable the wake on LAN capability of the onboard, PCH integrated Ethernet controller.
SLP_LAN# Low on DC Power	Disabled Enabled	Enable or disable SLP_LAN# low on DC power.
Board Capability	SUS_PWR_DN_ACK DeepSx	'SUS_PWR_DN_ACK' - Sends disabled to PCH. 'DeepSx' - Shows DeepSx policies.

Feature	Options	Description
DeepSx Power Policies	Disabled Enabled in S5/Battery Enabled in S4-S5/Battery Enabled in S3-S4-S5/Battery Enabled in S5 Enabled in S4-S5 Enabled in S3-S4-S5	Select DeepSx mode. Note: Only enable DC/battery powered mode for selected Sx state.
GP27 Wake From DeepSx	Disabled Enabled	Enable this feature to wake from DeepSx by the assertion of GP27 pin.
PCIe Wake From DeepSx	Disabled Enabled	Enable this feature to wake from DeepSx by the assertion of PCIe.
Serial IRQ Mode	Quiet Continuous	Set serial IRQ mode.
X2APIC Support	Disabled Enabled	Enable or disable X2APIC interrupt controller support.
SB CRID	Disabled Enabled	Enable or disable southbridge compatible revision ID support.
PCH Cross Throttling	Disabled Enabled	Enable or disable the PCH corss throttling feature.
SLP_S4 Assertion Width	Disabled 1-2 Seconds 2-3 Seconds 3-4 Seconds 4-5 Seconds	Set a minimum assertion width of the SLP_S4# signal.
Port 80h Redirection	LPC Bus PCIe Bus	Select where to send port 80h cycles.

10.6 Security Setup

Select the Security tab from the setup menu to enter the Security setup screen.

10.6.1 Security Settings

Feature	Options	Description
BIOS Password	Enter password	Enter the BIOS and setup administrator password
BIOS Lock	Disabled Enabled	Enable or disable BIOS Lock Enable (BLE) and SMM BIOS Write Protect (SMM_BWP) bits. If enabled, BIOS flash write accesses are only possible via dedicated BIOS SMM interfaces.
BIOS Update & Write Protection	Disabled Enabled	If enabled, congatec flash software will require BIOS password to perform write or erase operations.
HDD Security Configuration		
List of all detected hard disks supporting the security feature set		Select device to open device security configuration submenu.
► Secure Boot Menu	Submenu	

10.6.1.1 BIOS Security Features

BIOS Password/ BIOS Write Protection

A BIOS password protects the BIOS setup program from unauthorized access. This ensures that end users cannot change the system configuration without authorization. With an assigned BIOS password, the BIOS prompts the user for a password on a setup entry. If the password entered is wrong, the BIOS setup program will not launch.

The congatec BIOS uses a SHA256 based encryption for the password, which is more secured than the original AMI encryption. The BIOS password is case sensitive with a minimum of 3 characters and a maximum of 20 characters. Once a BIOS password has been assigned, the BIOS activates the grayed out 'BIOS Update and Write Protection' option. If this option is set to 'enabled', only authorized users (users with the correct password) can update the BIOS. To update the BIOS, use the congatec system utility `cgutlcmd.exe` with the following syntax:

`CGUTLCMD BFLASH <BIOS file> /BP: <password>` where <password> is the assigned BIOS password.

For more information about "Updating the BIOS" refer to the congatec system utility user's guide, which is called `CGUTLm1x.pdf` and can be found on the congatec AG website at www.congatec.com.

With the BIOS password protection and the BIOS update and write protection, the system configuration is completely secured. If the BIOS is password protected, you cannot change the configuration of an end application without the correct password.



Note

Use `cgutlcmd.exe` version 1.5.3 or later.

Built in BIOS recovery is disabled in the congatec BIOS firmware to prevent the BIOS from updating itself due to the user pressing a special key combination or a corrupt BIOS being detected. congatec considers such a recovery update a security risk because the BIOS internal update process bypasses the implemented BIOS security explained above.

Only the congatec utility interface to the SMI handler of the BIOS flash update is enabled. Other interfaces to the SMI handler are disabled to prevent non congatec tools from writing to the BIOS flash. As a result of this restriction, flash utilities supplied by AMI or Intel will not work .

UEFI Secure Boot

Secure Boot is a security standard defined in UEFI specification 2.3.1 that helps prevent malicious software applications and unauthorized operating systems from loading during system start up process. Without secure boot enabled (not supported or disabled), the computer simply hands over control to the bootloader without checking whether it is a trusted operating system or malware. With secure boot supported and enabled, the UEFI firmware starts the bootloader only if the bootloader's signature has maintained integrity and also if one of the following conditions is true:

- The bootloader was signed by a trusted authority that is registered in the UEFI database.
- The user has added the bootloader's digital signature to the UEFI database. The BIOS provides the key management setup sub-menu for this purpose.



Note

The congatec BIOS by default enables CSM (Compatibility Support Module) and disables secure boot because most of the industrial computers today boot in legacy (non-UEFI) mode. Since secure boot is only enabled when booting in native UEFI mode, you must therefore disable the CSM (compatibility support module) in the BIOS setup to enable Secure Boot.

A full description of secure boot is beyond the scope of this users guide. For more information about how secure boot leverages signature databases and keys, see the secure boot overview in the windows deployment options section of the Microsoft TechNet Library at <http://technet.microsoft.com>.

10.6.1.2 Hard Disk Security Features

Hard Disk Security uses the Security Mode feature commands defined in the ATA specification. This functionality allows users to protect data using drive-level passwords. The passwords are kept within the drive, so data is protected even if the drive is moved to another computer system.

The BIOS provides the ability to 'lock' and 'unlock' drives using the security password. A 'locked' drive will be detected by the system, but no data can be accessed. Accessing data on a 'locked' drive requires the proper password to 'unlock' the disk.

The BIOS enables users to enable/disable hard disk security for each hard drive in setup. A master password is available if the user can not remember the user password. Both passwords can be set independently however the drive will only lock if a user password is installed. The max length of the passwords is 32 bytes.

During POST each hard drive is checked for security mode feature support. In case the drive supports the feature and it is locked, the BIOS prompts the user for the user password. If the user does not enter the correct user password within four attempts, the user is notified that the drive is locked and POST continues as normal. If the user enters the correct password, the drive is unlocked until the next reboot.

In order to ensure that the ATA security features are not compromised by viruses or malicious programs when the drive is typically unlocked, the BIOS disables the ATA security features at the end of POST to prevent their misuse. Without this protection it would be possible for viruses or malicious programs to set a password on a drive thereby blocking the user from accessing the data.



If the user enables password support, a power cycle must occur for the hard drive to lock using the new password. Both user and master password can be set independently however the drive will only lock if a user password is installed.

10.7 Boot Setup

Select the Boot tab from the setup menu to enter the Boot setup screen.

10.7.1 Boot Settings Configuration

Feature	Options	Description
Quiet Boot	Disabled Enabled	'Disabled' - Displays normal POST diagnostic messages. 'Enabled' - Displays OEM logo instead of POST messages. The default OEM logo is a dark screen.
Setup Prompt Timeout	1 0 - 65535	Set number of seconds to wait for setup activation key. '65535' - Waits indefinitely (0xFFFF). '0' - Does not wait (not recommended).
Bootup NumLock State	On Off	Select the keyboard numlock state.
Battery Support	Auto (Batt. Manager) Battery-Only On I2C Bus Battery-Only On SMBus	Select battery system support: 'Battery-Only On I2C Bus' - Uses I2C bus for battery-only systems. 'Battery-Only On SMBus' - Uses SMBus for battery-only systems. 'Auto' - Intended for systems equipped with a real battery system manager connected via I2C or SMBus.
System Off Mode	G3/Mech Off S5/Soft Off	Set system state after shutdown if a battery system is present.
Power Loss Control	Remain Off Turn On Last State	Select mode of operation if an AC power loss occurs: 'Remain Off' - Keeps the power off until the power button is pressed. 'Turn On' - Restores power to the computer. 'Last State' - Restores the previous power state before power loss occurred. Note: Only works with an ATX type power supply.
AT Shutdown Mode	System Reboot Hot S5	Select the behavior of an AT-powered system after a shutdown.
Enter Setup If No Boot Device	No Yes	Select whether the setup menu should be started if no boot device is connected.
Enable Popup Boot Menu	No Yes	Select whether the popup boot menu can be started.
Boot Priority Selection	UEFI Standard Type Based	Set boot priority: 'Device Based' - Select boot priority from a list of currently detected devices. 'Type Based' - Select boot priority from a list of device types even if they are not connected yet.
Boot Option Sorting Method	Legacy First UEFI First	Set boot option sorting method: 'Legacy First' - Tries all legacy boot option first before first UEFI boot option. 'UEFI First' - Tries all UEFI boot options before first legacy boot option.

Feature	Options	Description
1st, 2nd, 3rd, ... Boot Device (Up to 12 boot devices can be prioritized if UEFI Standard priority list control is selected. If "Type Based" priority list control is enabled only 8 boot devices can be prioritized.)	Disabled SATA 0 Drive SATA 1 Drive USB Harddisk USB CDROM Other USB Device Onboard SD Card Storage Onboard LAN External LAN Firmware-based UEFI Bootloader Other Device	This view is only available when in the default "Type Based" mode. When in 'UEFI Standard' mode, you will only see the devices that are currently connected to the system.
UEFI Fast Boot	Disabled Enabled	Enable to boot with a minimum set of devices. No effect for BBS / legacy boot options.
SATA Support	Last Boot HDD Only, All SATA Devices	
VGA Support	Auto UEFI Driver	'Auto' - Installs legacy video option ROM for legacy operating system boot. Boot logo will not be shown during POST. 'UEFI Driver' - Installs UEFI GOP driver.
USB Support	Disabled Full Init Partial Init	'Disabled' - USB devices will not be available before operating system boot. 'Full Init' - All USB devices will be available during POST and after operating system boot. 'Partial Init' - Specific USB ports/devices will not be available before operating system boot.
PS/2 Device Support	Disabled Enabled	Disable to skip PS/2 devices.
Network Stack Driver Support	Disabled Enabled	Disable to skip the UEFI network stack driver installation.
UEFI Screenshot Capability	Disabled Enabled	If enabled, press CTRL+ALT+F12 to take a screen shot of the current setup, POST, UEFI shell or driver and save it as PNG on the first writable partition

Note

The term 'AC power loss' stands for the state when the module loses the standby voltage on the 5V_SB pins. The standby voltage is continuously monitored after the system is turned off. If the standby voltage is not detected within 30 seconds, this is considered an AC power loss condition. If the standby voltage remains stable for 30 seconds, it is assumed that the system was switched off properly.

Inexpensive ATX power supplies often have problems with short AC power sags. The system turns off but might not switch back on, even when the PS_ON# signal is asserted correctly by the module. In this case, the internal circuitry of the ATX power supply has become confused. Usually, a AC power off/on cycle is necessary to recover from this situation.

10.8 Save & Exit Menu

Select the Save & Exit tab from the setup menu with the <Arrow> keys to enter the Save & Exit setup screen.

Feature	Description
Save Changes and Exit	Exit setup menu after saving the changes. The system is only reset if settings have been changed.
Discard Changes and Exit	Exit setup menu without saving any changes.
Save Changes and Reset	Save changes and reset the system.
Discard Changes and Reset	Reset the system without saving any changes.
Save Options	
Save Changes	Save changes made so far to any of the setup options. Stay in setup menu.
Discard Changes	Discard changes made so far to any of the setup options. Stay in setup menu.
Restore Defaults	Restore default values of all the setup options.
► Boot Override	
List of all boot devices currently detected.	Select device to leave setup menu and boot from the selected device. Only visible and active if Boot Priority Selection setup node is set to "Device Based".

11 Additional BIOS Features

The conga-TC97 uses a congatec/AMI AptioEFI that is stored in an onboard Flash Rom chip and can be updated using the congatec System Utility (version 1.5.0 and later), which is available in a DOS based command line, Win32 command line, Win32 GUI, and Linux version.

The BIOS displays a message during POST and on the main setup screen identifying the BIOS project name and a revision code. The initial production BIOS is identified as BV97R7xx or BU97R7xx where:

- BV97 is the BIOS for modules with the premium chipset
- BU97 is the BIOS for modules with the base chipset
- R is the identifier for a BIOS ROM file, 7 is the so called feature number and xx is the major and minor revision number.

The BV97 BIOS binary size is 16MB and the BU97 BIOS binary size is 8MB.

11.1 Supported Flash Devices

The conga-TC97 supports the following flash devices:

- Spansion S25FL064K0SMFI01 (8MB)
- Winbond W25Q128FVSI01 (16MB)
- Winbond W25Q64CVSSIG (8MB)

The flash devices listed above can be used on the carrier board for external BIOS support. For more information about external BIOS support, refer to the Application Note AN7_External_BIOS_Update.pdf on the congatec website at <http://www.congatec.com>.

11.2 Updating the BIOS

BIOS updates are often used by OEMs to correct platform issues discovered after the board has been shipped or when new features are added to the BIOS.

For more information about “Updating the BIOS” refer to the user’s guide for the congatec System Utility, which is called CGUTLm1x.pdf and can be found on the congatec AG website at www.congatec.com.

12 Industry Specifications

The list below provides links to industry specifications that apply to congatec AG modules.

Specification	Link
Low Pin Count Interface Specification, Revision 1.0 (LPC)	http://developer.intel.com/design/chipsets/industry/lpc.htm
Universal Serial Bus (USB) Specification, Revision 2.0	http://www.usb.org/home
PCI Specification, Revision 2.3	http://www.pcisig.com/specifications
Serial ATA Specification, Revision 3.0	http://www.serialata.org
PICMG® COM Express Module™ Base Specification	http://www.picmg.org/
PCI Express Base Specification, Revision 2.0	http://www.pcisig.com/specifications